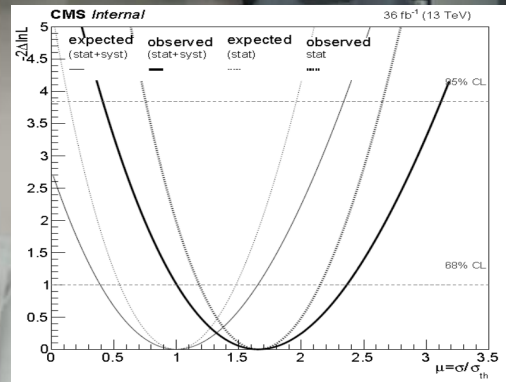
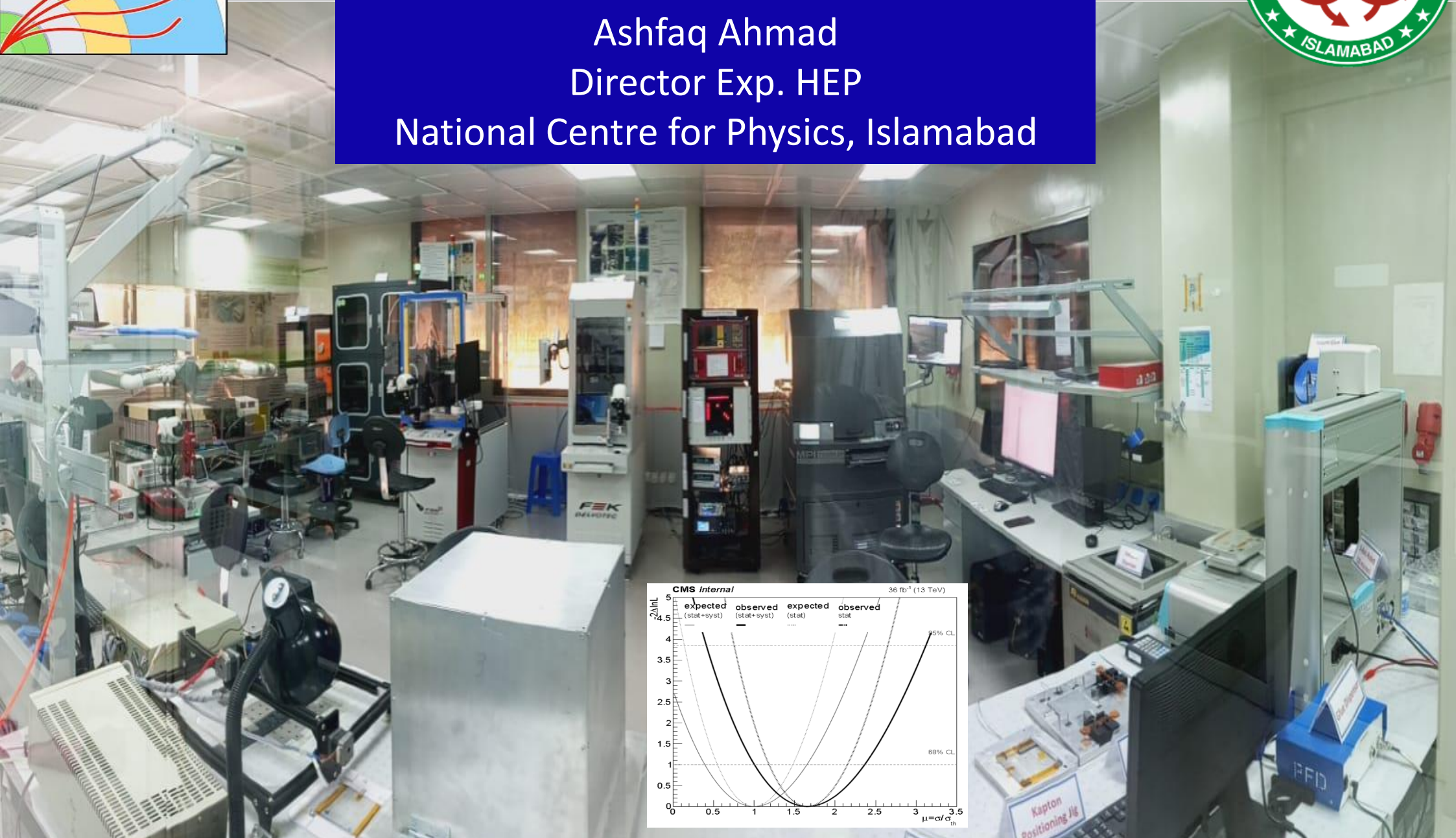




CMS Tracker Phase-2 Upgrade Projects at NCP



Ashfaq Ahmad
Director Exp. HEP
National Centre for Physics, Islamabad



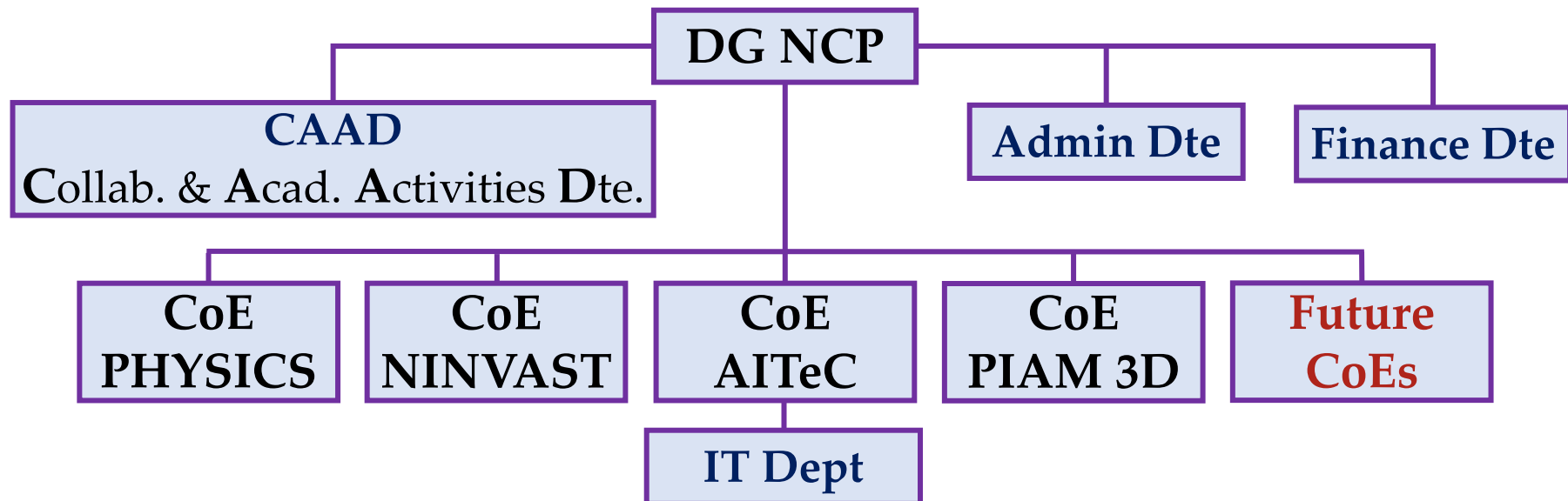
Introduction

- Brief Introduction to National Centre for Physics
- Outer Tracker Phase 2 upgrade

- Phase 2 upgrade projects at NCP
 - ❑ Ladder Mechanics Project at NCP
 - ❑ Sensor Quality Control project
 - ❑ Assembly, metrology and testing of TB2S modules

- Summary

Organogram of NCP



PHYSICS: Exp. HEP, Th. HEP, Accelerator, Laser Physics

NINVAST: National Institute of Vacuum Science and Technology

AITeC: Artificial Intelligence Technology Centre

PIAM-3D: Pakistan Institute of Additive Manufacturing

Panoramic View of NCP

Central part of NCP



Total Area~ 25 Acre

NCP Uniqueness

- One of a kind national research center in Physics & Emerging Techs.
- Breaking the scientific isolation of local researchers by conducting conferences, seminars, workshops.
- Unique Hosted Researcher Program – For Students / Faculty from all national / international universities
- Connected with: CERN, ICTP & TWAS, IHEP, DESY and SESAME

Hosted Researchers

1. **Adjunct Faculty**: Foreign/Local Researchers (Academia & R&D orgs.)
2. **Visiting Scholars**: Foreign / Local PhD Scholars up to 3 months
3. **NCP Associates**: Foreign / Local researchers up to 3 years
4. **Post-Doctoral Fellows**: Foreign / Local PhDs for 6 – 12 months
5. **Research Students**: Foreign / Local M.Phil / PhD 1– 3 years
6. **Internees**: For 3 – 6 months

Some facilities at NCP

5 MV Ion Beam Tandem Accelerator



Probe station

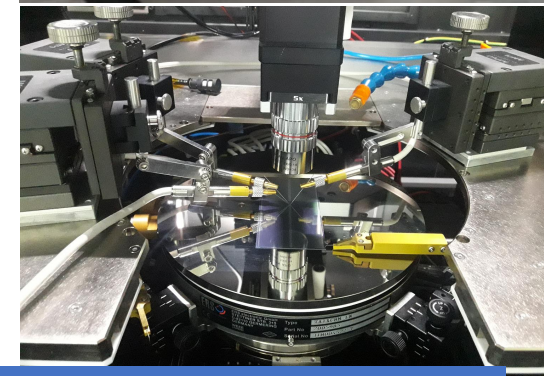
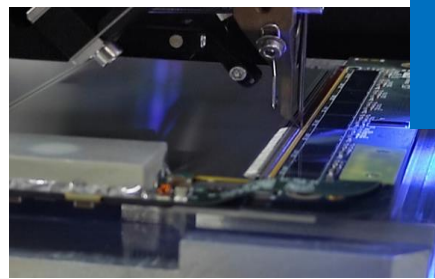


cleanroom



30 meters

Wire/ball bonding machine



New cleanroom



LIBS



PLD



Ion Implanter



Logistics Facilities at NCP

1. Auditorium (2, Capacity: 285, 70) with Record / Video Conf. Facilities
2. Computer Lab (50 latest general purpose computers)
3. Lecture Theater (Capacity: 60 persons)
4. Lecture Hall (3), Lecture Rooms (4), Conference Rooms (6)
5. Good furnished accommodation for researchers
 1. BoQs (Capacity, 100 guests)
 2. MoQs (Capacity, 50 guests)
 3. Guest House for foreign faculty (Capacity, 50 guests)
6. Cafeteria with seating capacity of 200 persons
7. Wi-Fi throughout the campus

AS-ICTP like Organization of Scientific Events

Int. Workshop on Tracking Detectors



24-28 October
ISPAD-23

Ion Beam Application



School on LHC Physics



Max Plank Crystallography



Plasma Physics



GANDE-China



Abdus Salam Sci. Mela



Laser-Matter Interaction



Annual School on LHC Physics



LHC = The Large Hadron Collider

Mont Blanc

Lake Geneva

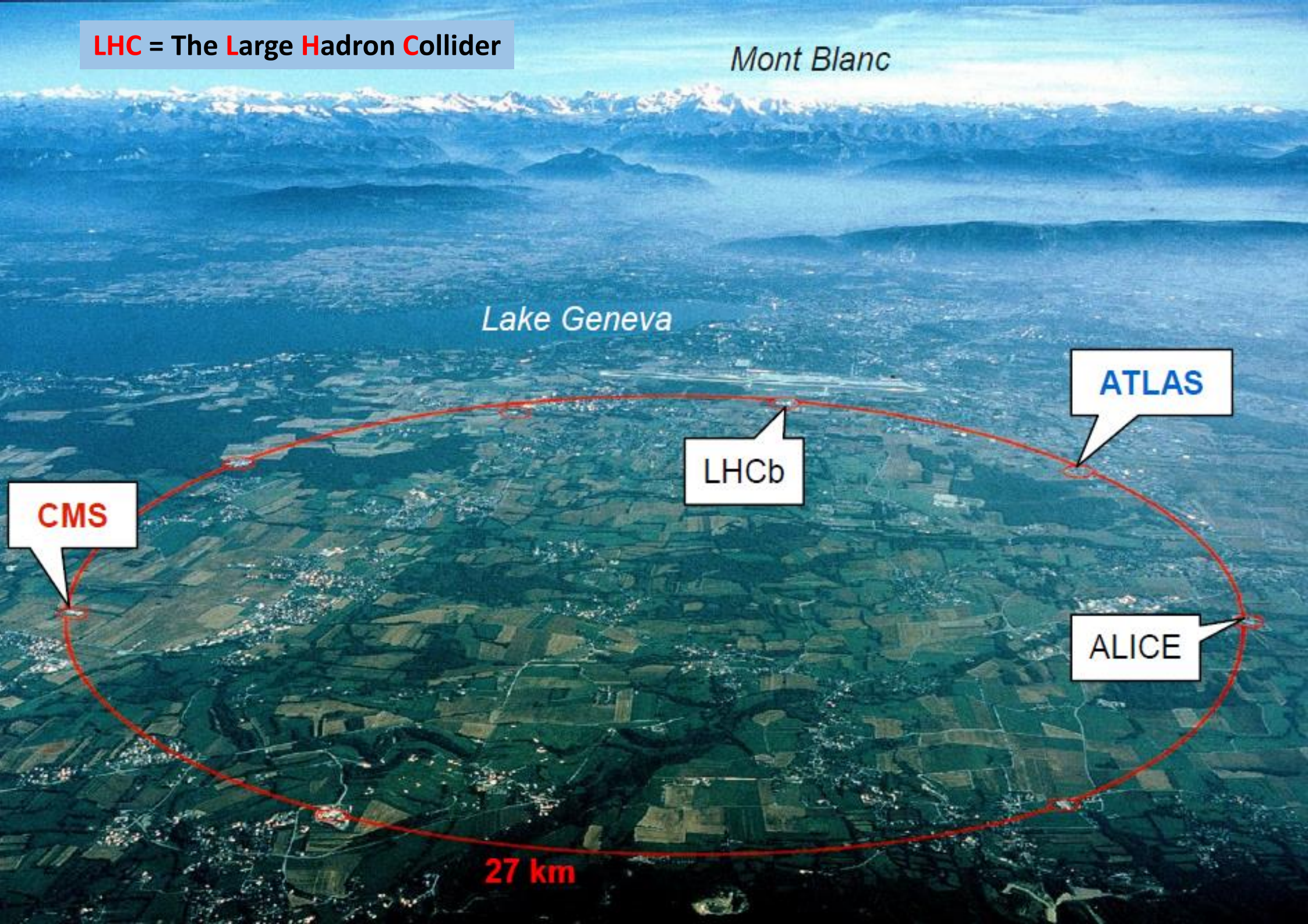
CMS

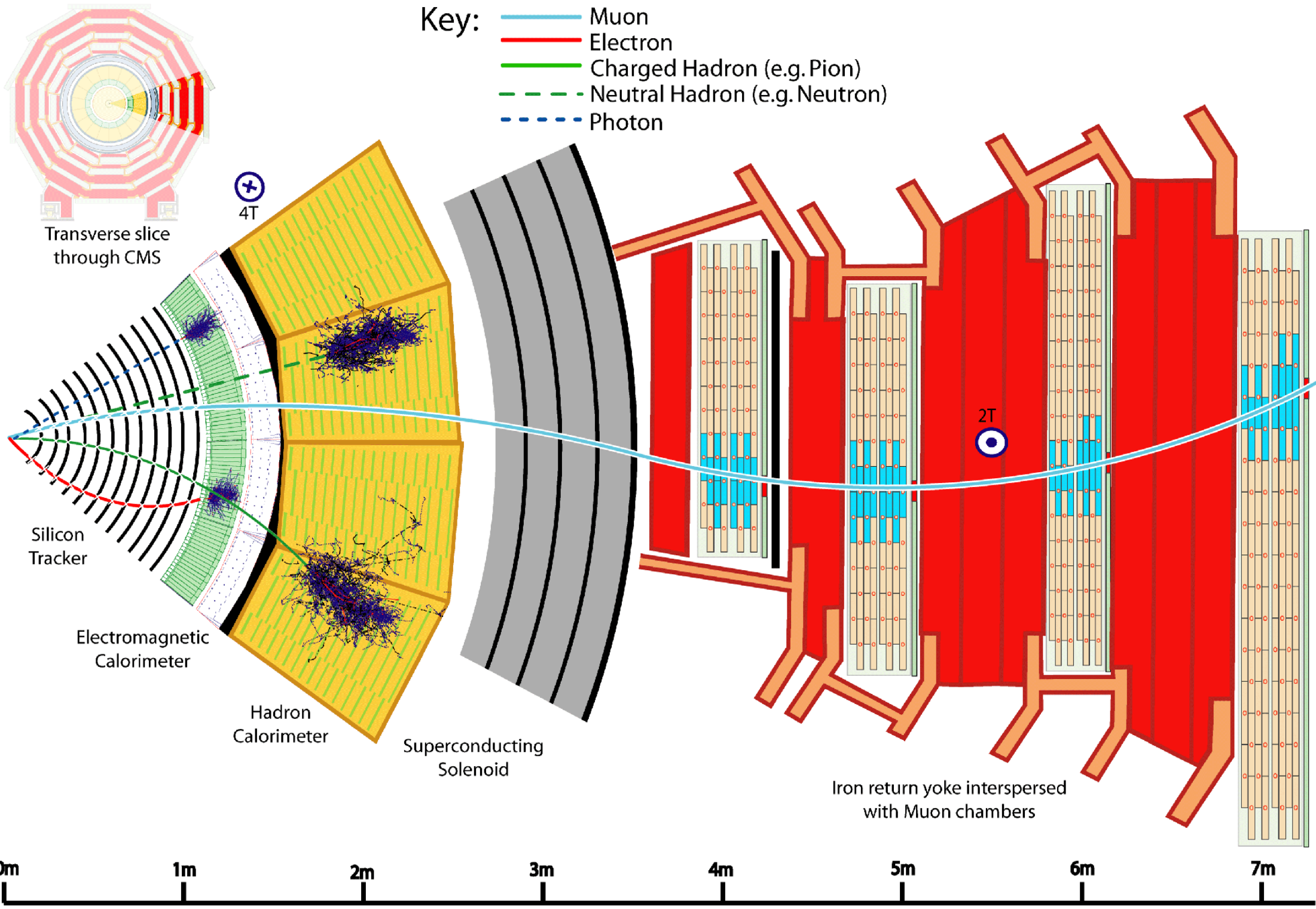
LHCb

ATLAS

ALICE

27 km

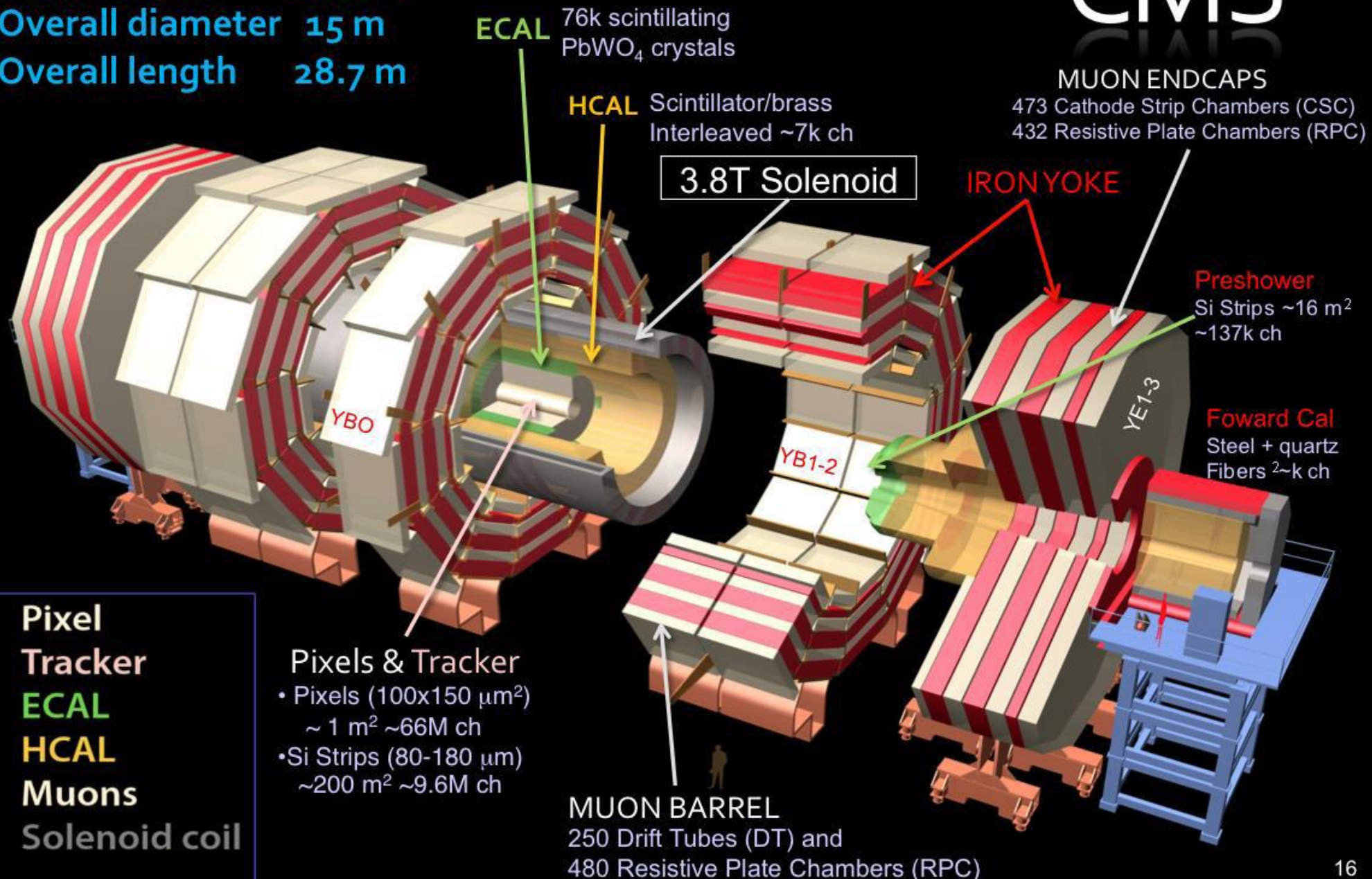




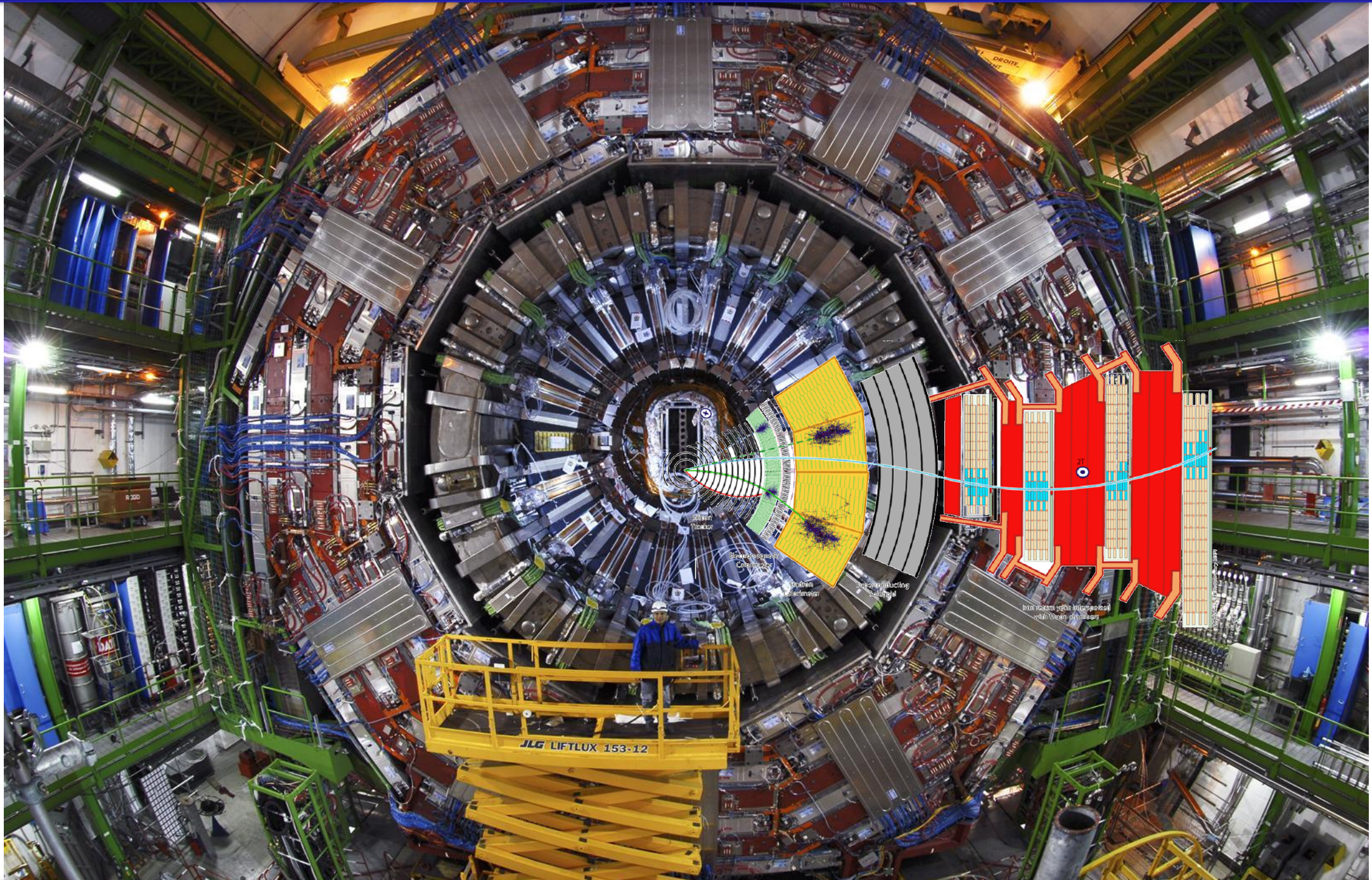
Compact Muon Solenoid(CMS) Experiment

CMS

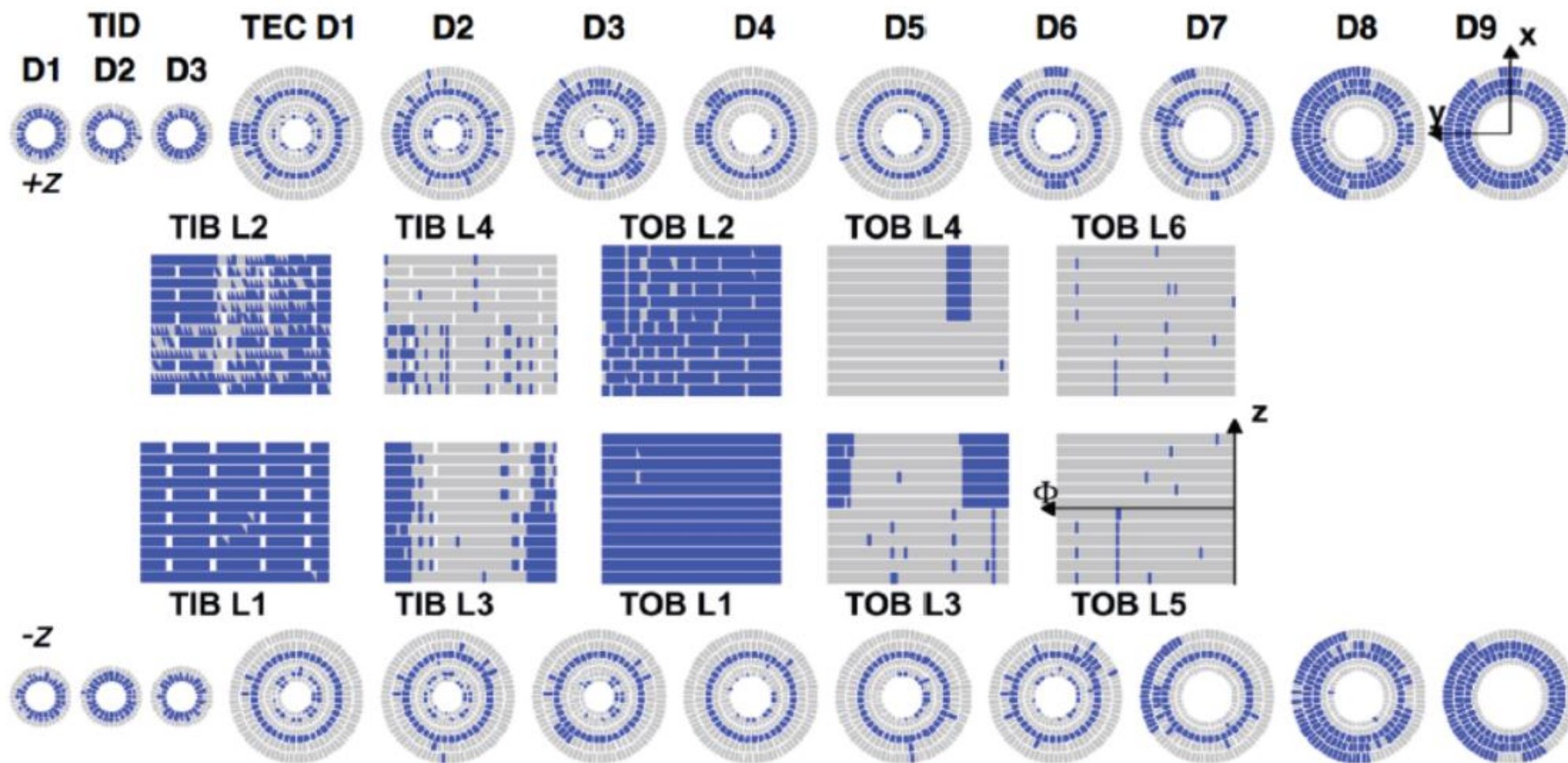
Total weight 14000 t
 Overall diameter 15 m
 Overall length 28.7 m



The CMS Detector (real!)



Why we need to upgrade the detector?

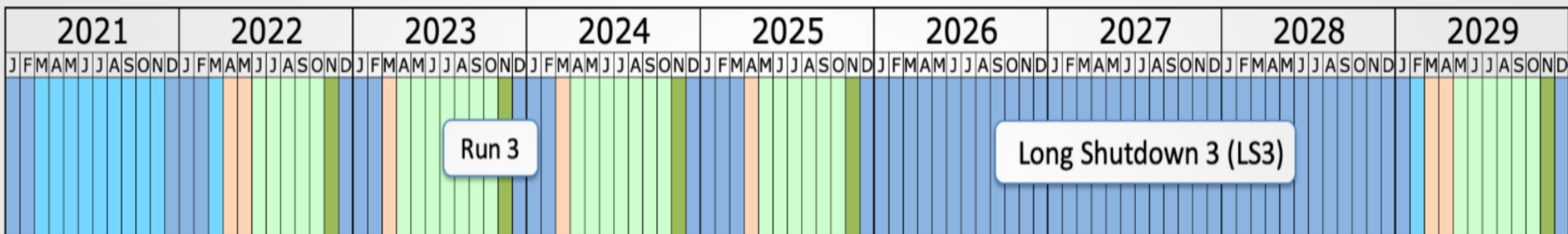



Non-functional modules in CMS after accumulating 1000 fb^{-1} integrated luminosity.

Motivation for HL-LHC

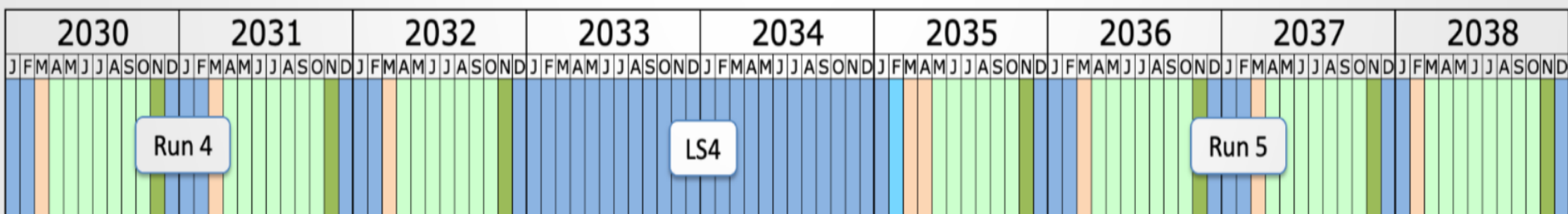
- **Motivation:** To improve further the physics potential of the LHC for rare standard model and beyond standard model processes. The LHC will be upgraded to deliver an instantaneous luminosity up to $7.5 \times 10^{34} \text{ cm}^{-2}\text{s}^{-1}$. Following are the main features of the upgraded detector:
- **Improving luminosity:** from $\sim 500 \text{ fb}^{-1}$ to 3000 fb^{-1}
- **Radiation tolerance:** Radiation hard technologies to withstand with fluences up to $2.3 \times 10^{16} \text{ n}_{\text{eq}}/\text{cm}^2$ (in pixel layer 1)
- **Increased granularity:** Occupancy $< 1\%$ in all tracker regions in order to ensure efficient tracking at high PU(~ 200)
- **Reduced material budget** in the tracking volume to improve primary vertex reconstruction
- **Extended tracking acceptance** efficient tracking up to $|\eta| = 4$
- **Tracking information** to be made available at trigger level for more selective L1 trigger (contribute to the event selection)
 - ❑ will improve the transverse momentum resolution of various objects at L1 (e.g. jets)
 - ❑ will allow the exploitation of information on track isolation.
 - ❑ will contribute to the mitigation of pileup

LHC LONG TERM SCHEDULE



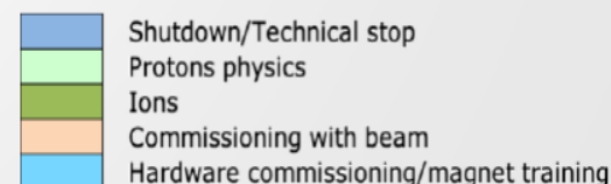

 Run (2+)3: 300-350 fb⁻¹
 (~2×10³⁴ cm⁻²s⁻¹), PU 40-60, “last significant low PU run”

→ HL-LHC



Last updated: January 2022

(~5-7 10³⁴ cm⁻²s⁻¹), 3-4 ab⁻¹, PU 140-200 → Major detector upgrades



CMS Phase 2 Upgrade

Replacements of existing system/detector

Electronics upgrade/replacement

New detector

L1-Trigger/HLT/DAQ [CMS-TDR-021 / 022]

- Tracks in L1-Trigger at 40 MHz
- PFlow-like selection 750 kHz output
- HLT output 7.5 kHz

Calorimeter Endcap [CMS-TDR-019]

- 3D showers imaging for pattern recognition
- Precision timing for PU mitigation
- Si, Scint+SiPM in Pb/W-SS

Tracker [CMS-TDR-014]

- P_T module design for tracking in L1-Trigger
- Extended coverage to $\eta \approx 3.8$
- Much reduced material budget
- Si-Strip and Pixels increased granularity

Barrel Calorimeters [CMS-TDR-015]

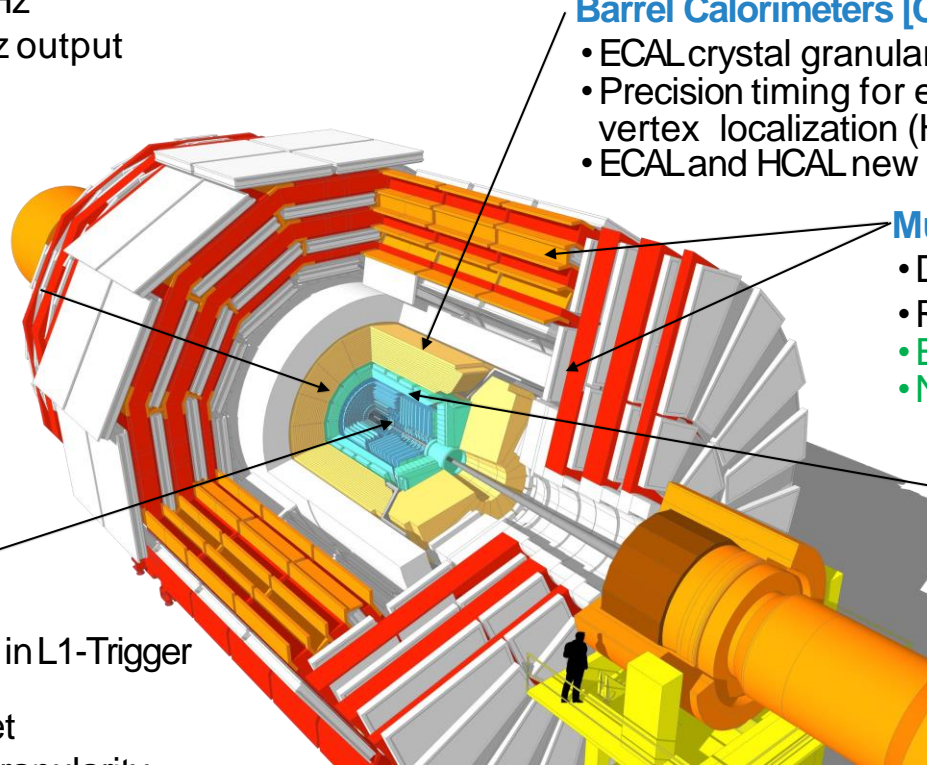
- ECAL crystal granularity readout at 40 MHz
- Precision timing for e/γ at 30 GeV, for vertex localization ($H \rightarrow \gamma\gamma$)
- ECAL and HCAL new Back-Endboards

Muon systems [CMS-TDR-016]

- DT & CSC new FE/BE readout
- RPC back-end electronics
- Extended GEM coverage to $\eta \approx 3$
- New GEM/RPC $1.6 < \eta < 2.4$

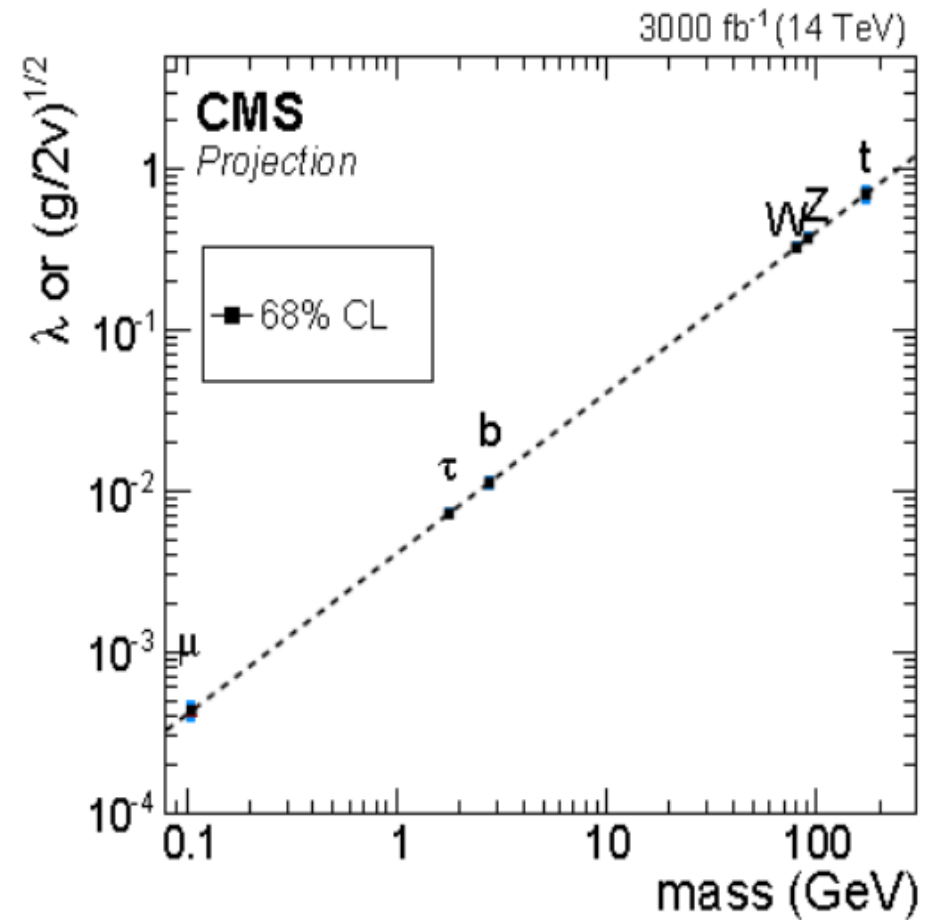
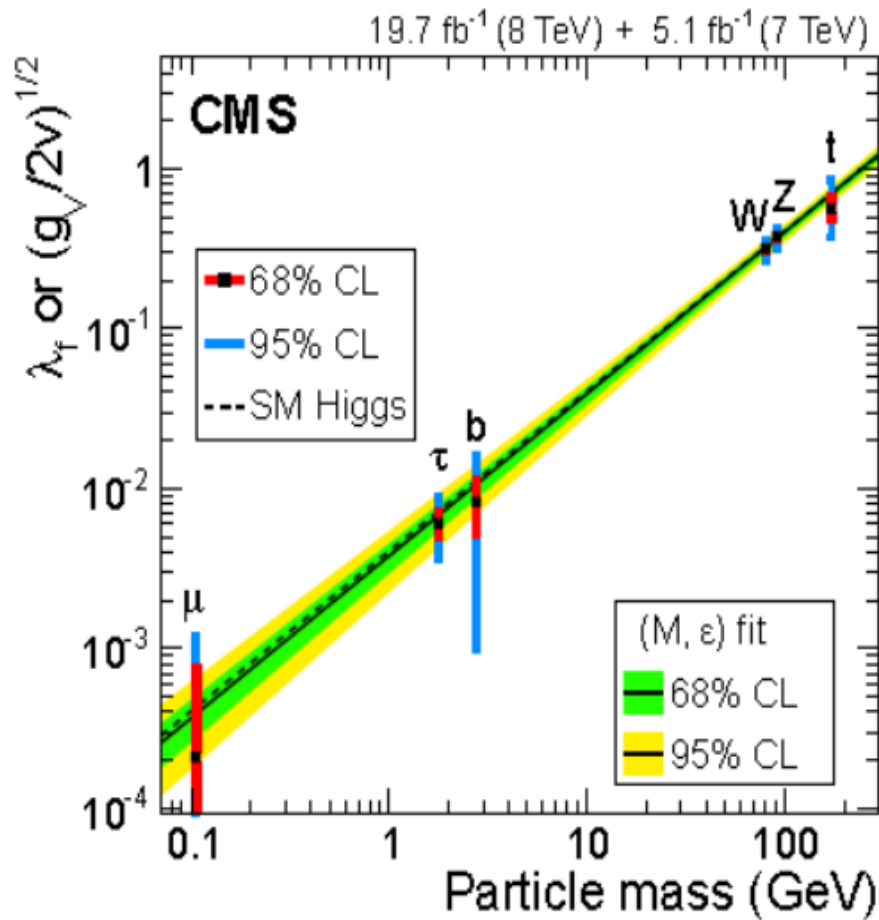
MIP Timing Detector [CMS-TDR-020]

- Precision timing for PU mitigation
- Barrel layer: Crystals + SiPMs
- Endcap layer: Low Gain Avalanche Diodes



Physics Motivation for HL-LHC

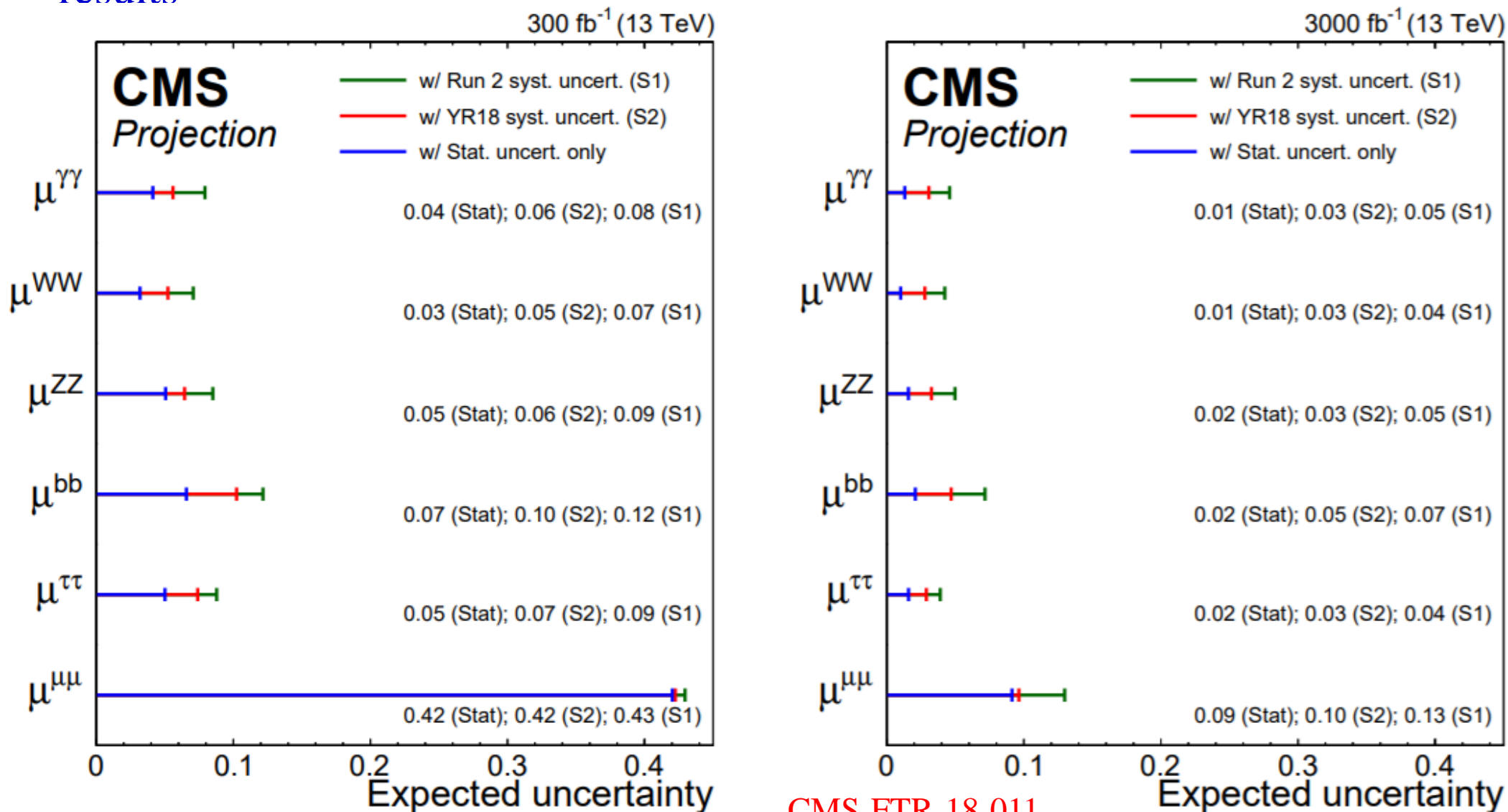
- Yukawa and boson couplings as function of particle's mass



- Run 1 data (left) and projection of the uncertainties(right) (assuming standard model couplings)

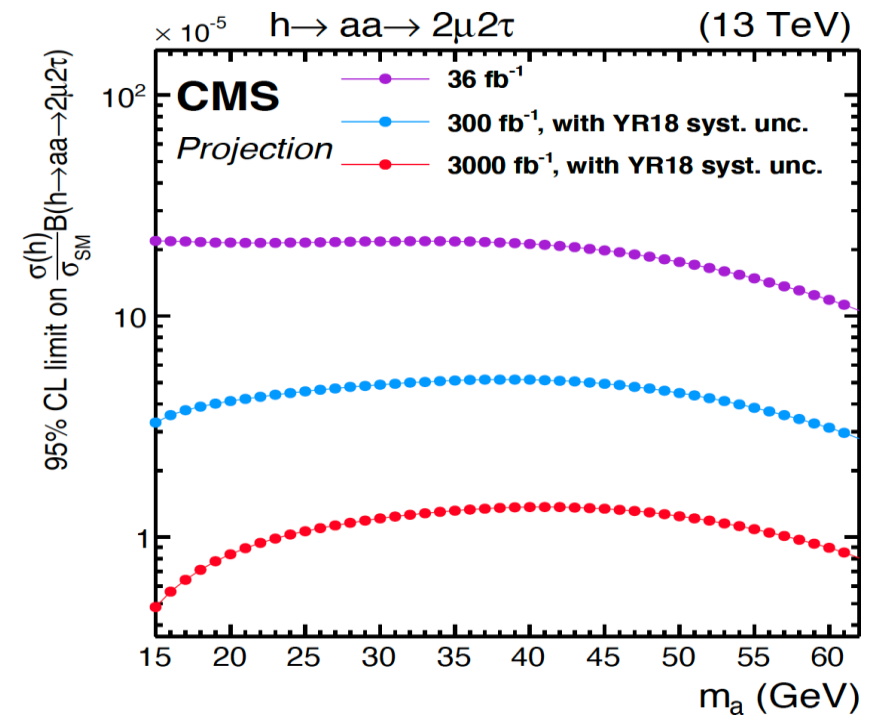
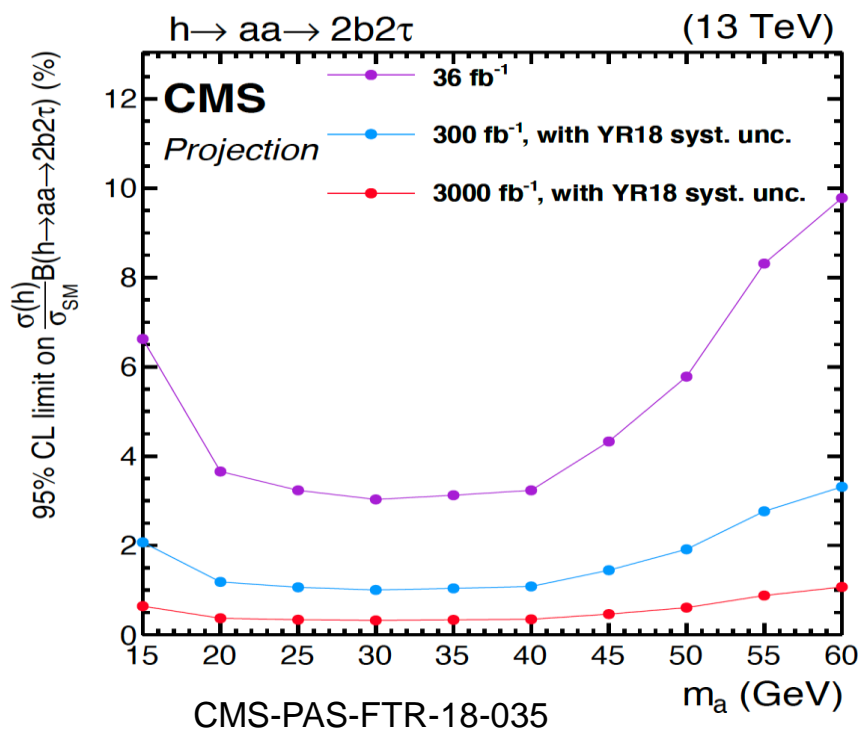
Higgs Coupling Sensitivity at HL-LHC

➤ Projected HL-LHC uncertainties on Higgs couplings, extrapolated from Run 2 results

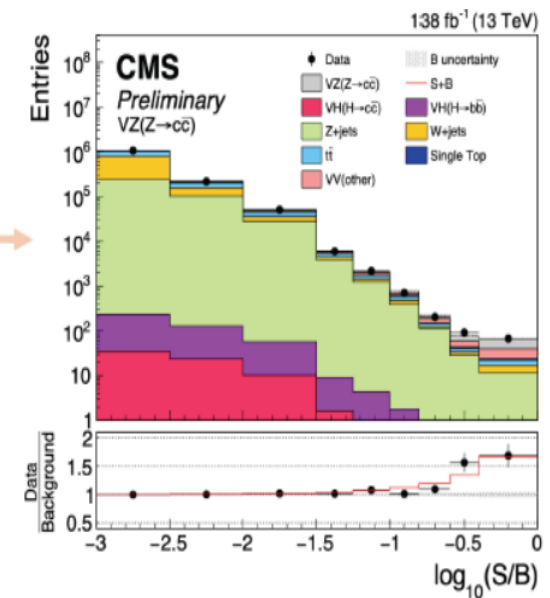
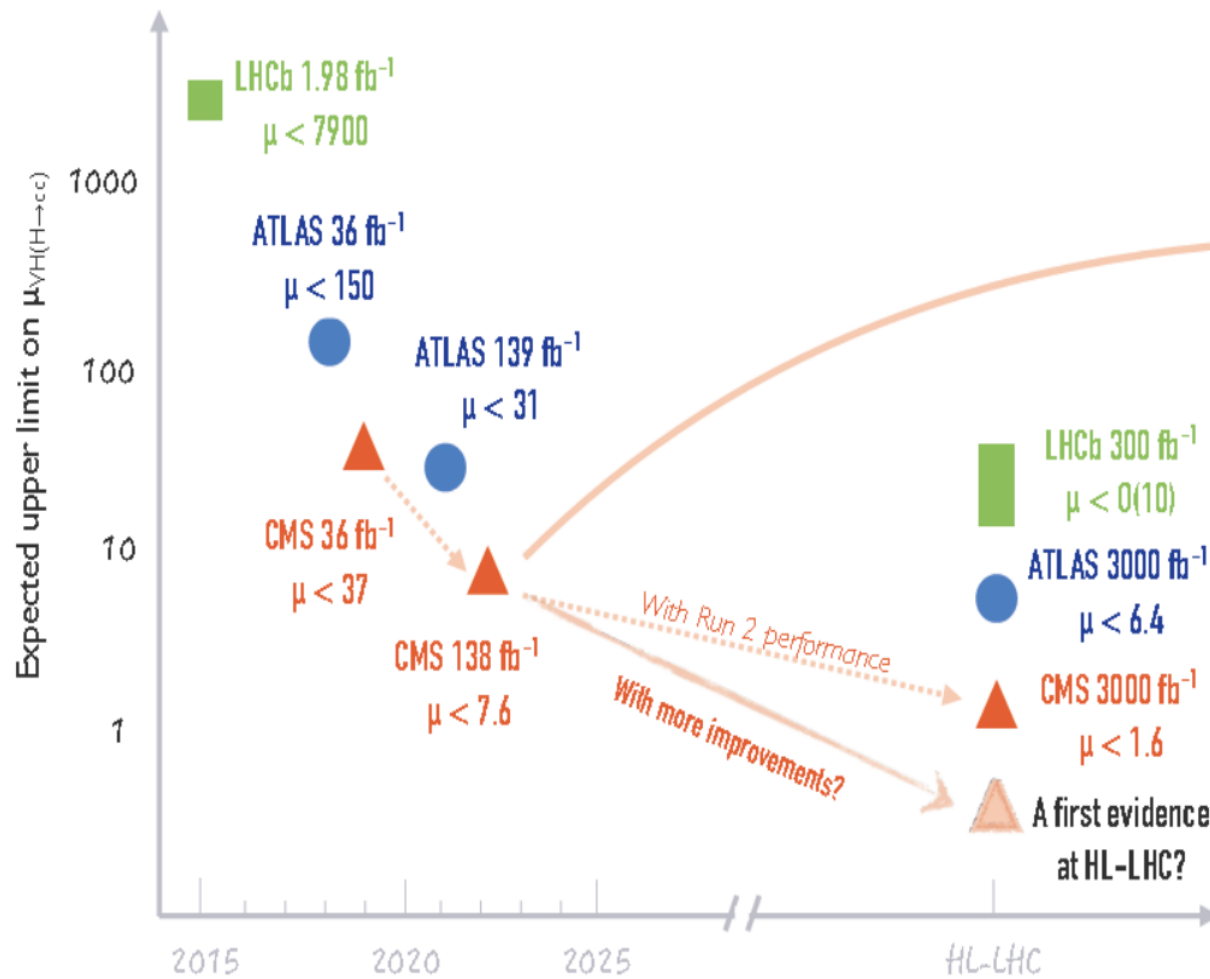


BSM Higgses: Exotic Higgs boson decays to light Pseudoscalars

- Light scalar Higgs “a” from NMSSM could decay to hadronic and leptonic τ final states:
 - ☐ $h \rightarrow aa \rightarrow bb\tau\tau, \mu\mu\tau\tau$ (hadronic and leptonic τ decays).
- Searchers are interpreted in two-Higgs-doublet models extended with a scalar singlet (2HDM+S)
- Projected expected limits show increased sensitivity, of the order of SM cross section



Future Expectation



First observation of $Z \rightarrow cc$ at a hadron collider!
Opening a new era for future explorations.

- More channels: $t\bar{t}H(cc)$, VBF $H(cc)$, indirect constraints, etc.
- Improvements in advanced analysis techniques (e.g., Deep Learning) and instrumentation (e.g., tracker)
- Reduction of systematic uncertainties: c-tagging, event

CERN LPCC EP-LHC Seminar 1 March 2022

Tracker Upgrade

High-Luminosity LHC scenario

➤ Increase (6x) granularity in the innermost detector

➤ Outer Tracker TB2S ~ 31 M channels with 7608

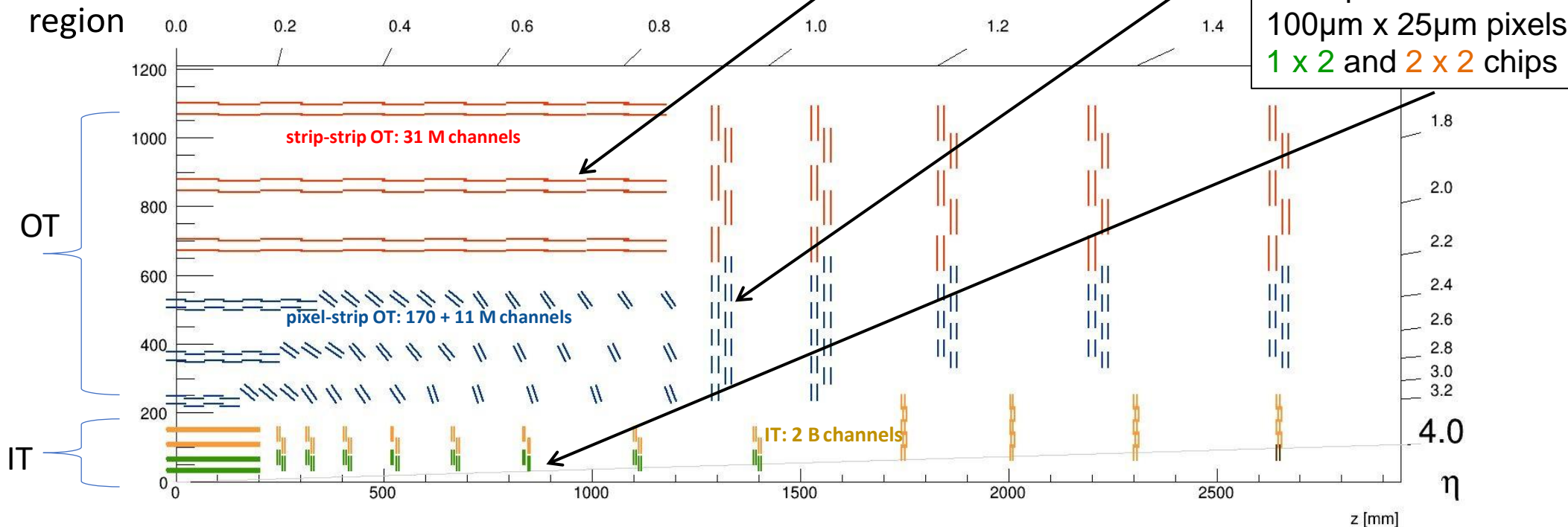
modules. For 5592 OT PS modules ~ 170+11M channels

And for Inner Tracker about 2 billions channels

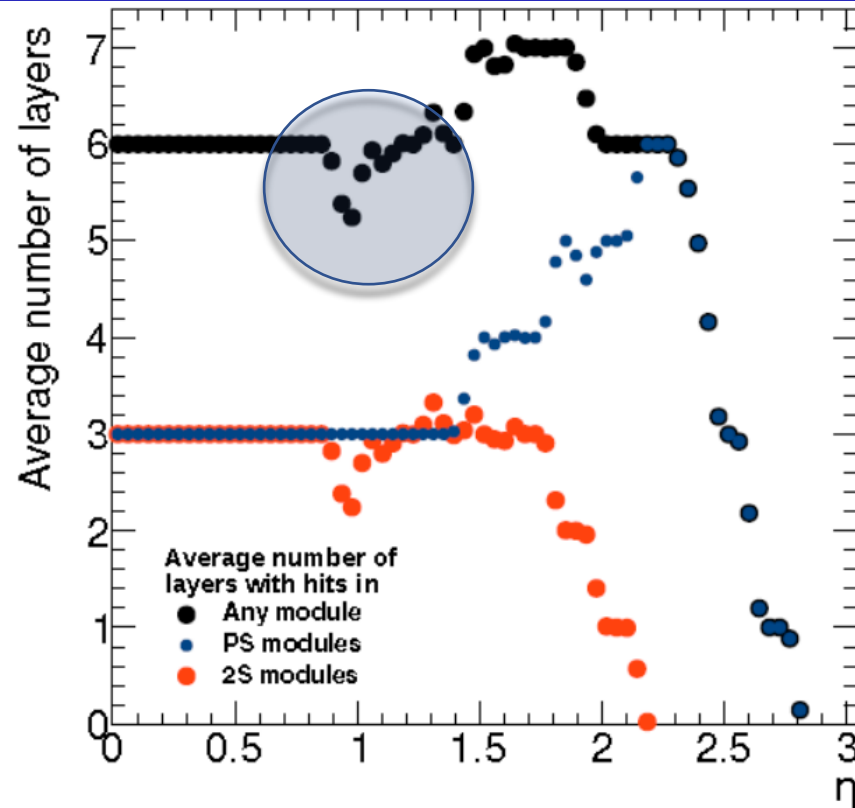
➤ Improve (10x) radiation tolerance of the detectors

➤ Easy maintenance and replacement of the innermost

region

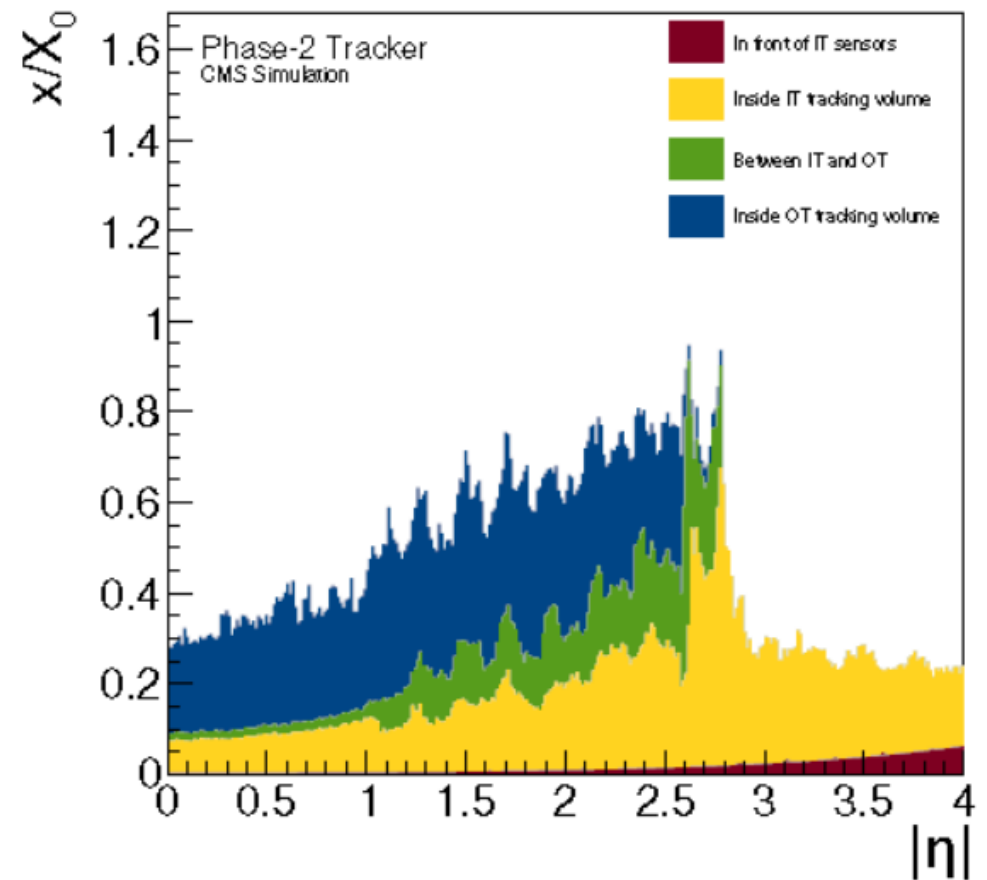
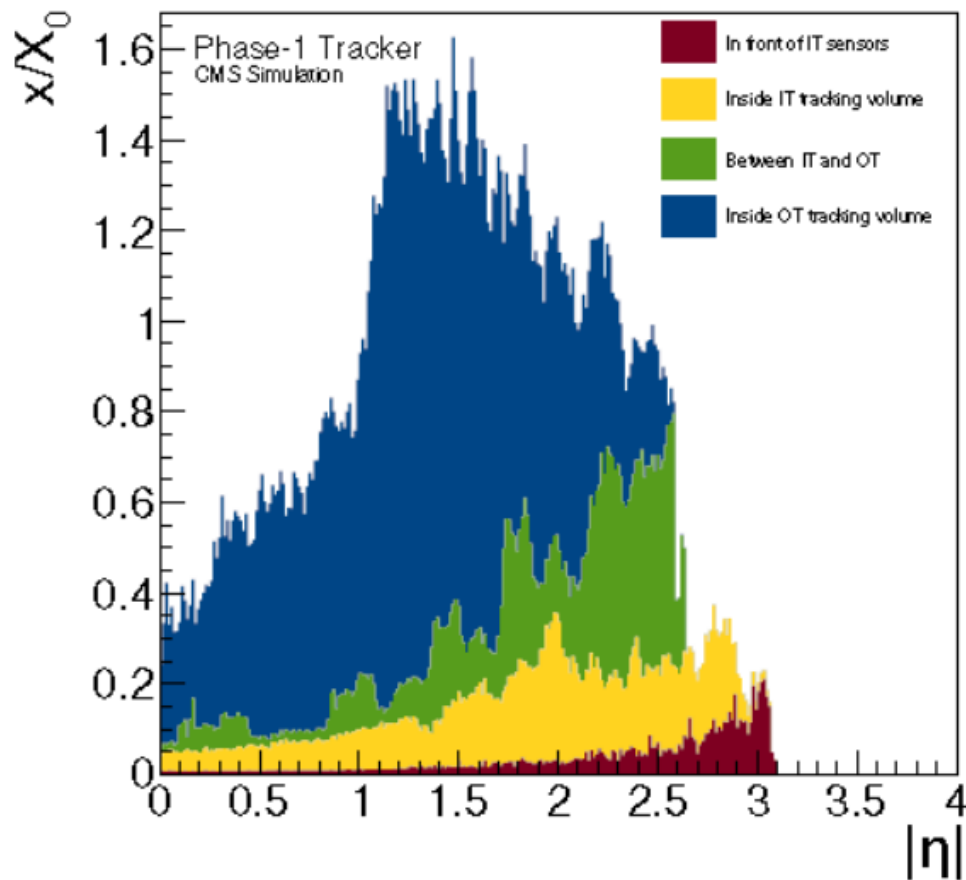


Module layers crossed by particles



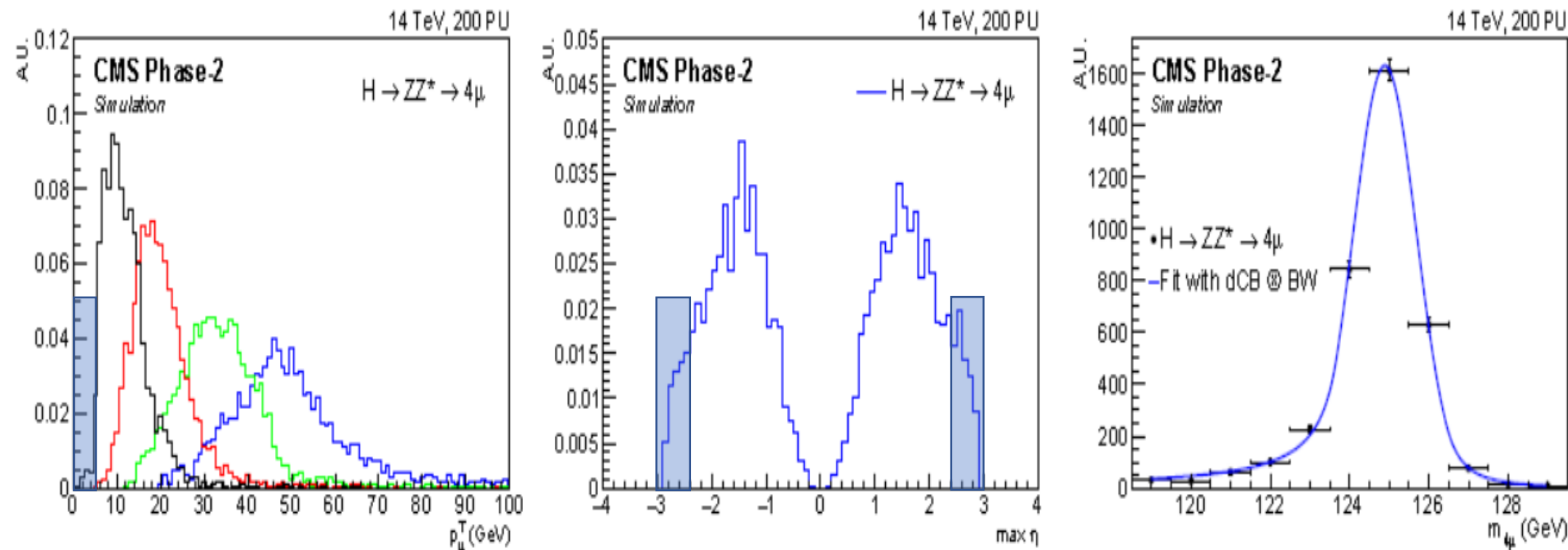
- At least six module layers are crossed by all particles in the rapidity range $|\eta| < 2.4$ (except in the transition region)
 - These are the minimum that ensures sufficiently robust track finding performance for the L1 trigger

CMS Tracker Material Budget



- **Reduced material budget** in the tracking volume to improve primary vertex reconstruction
- Extended tracking acceptance up to $|\eta| = 4$

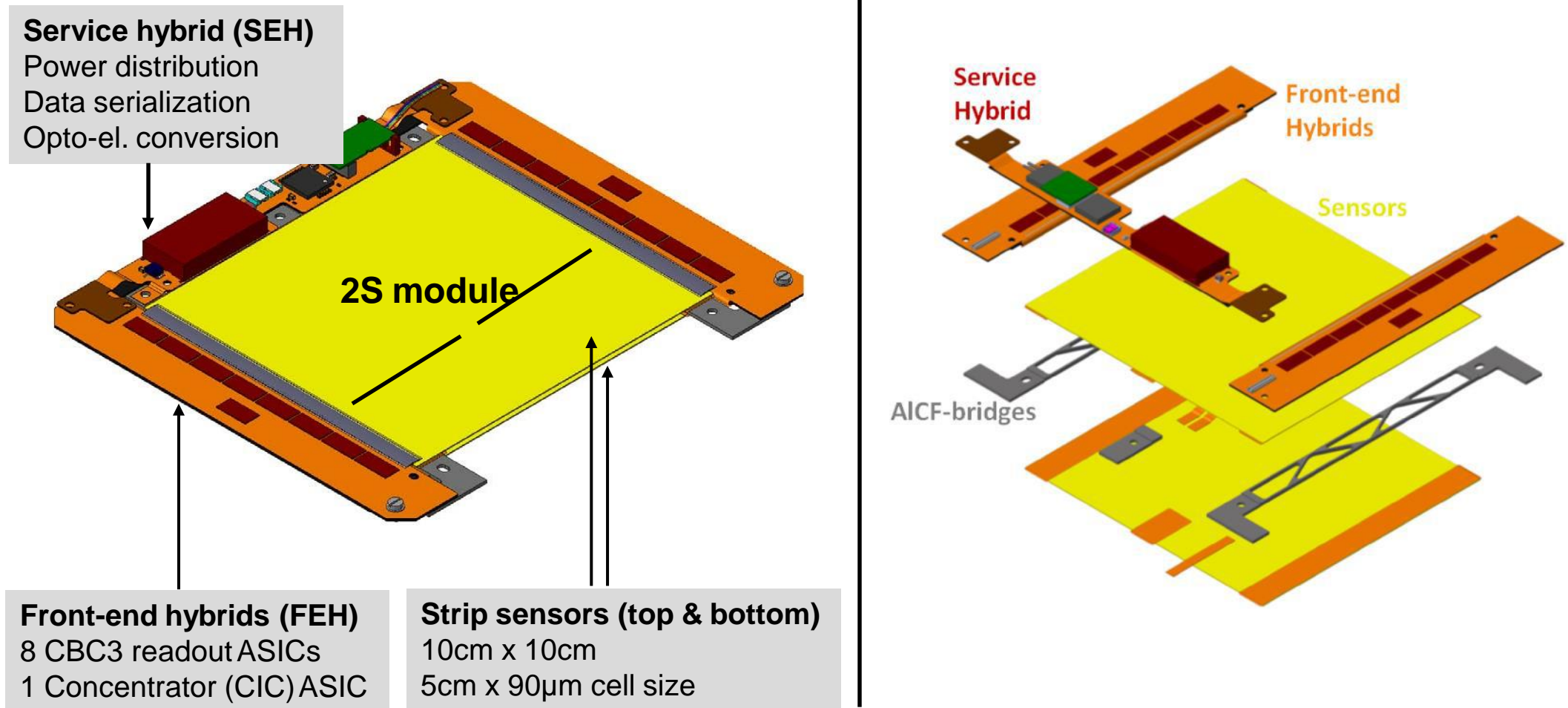
Acceptance enhancement



- Lowering p_T threshold for triggering and increase in eta coverage maximize the acceptance
- Increase in acceptance from 2.4 to 3 corresponds to an increase in acceptance of about 15% for four leptons from Higgs decay with respect to Run II detector acceptance
- No worsening of the mass resolution due to increase in pileup

TB2S Modules

- The pT module concept relies on the fact that the strips of the top and bottom sensors of a module are parallel to each other
- Stringent alignment constraints between top and bottom sensors in modules
- Should be below $400 \mu\text{rad}$ for 2S module and below $800 \mu\text{rad}$ for PS modules



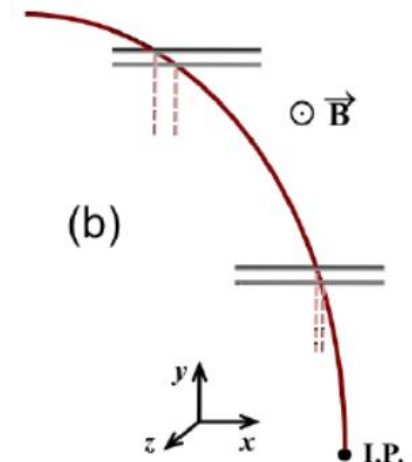
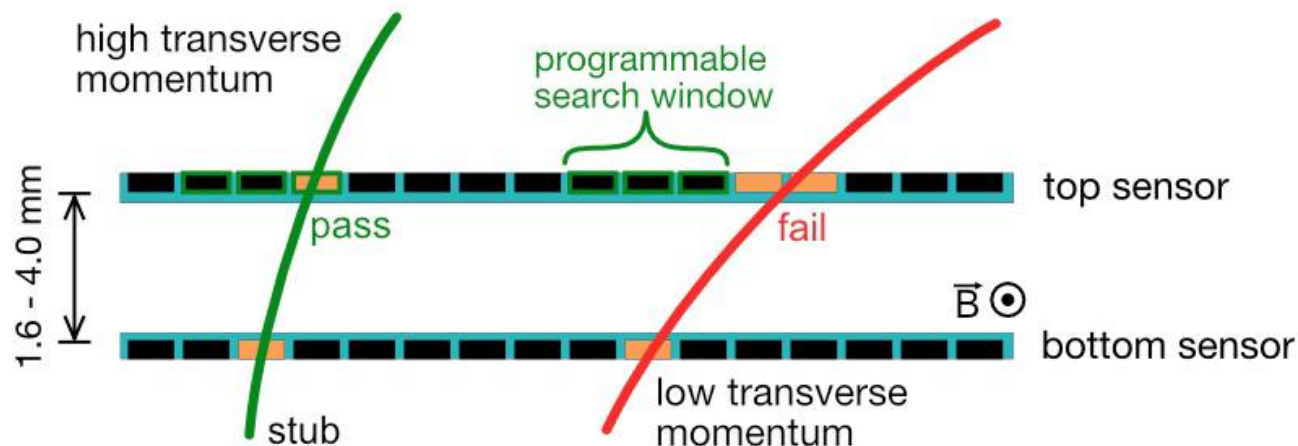
Outer Tracker pT modules

□ pT module concept:

- Exploit bending of charged particle tracks in CMS 3.8T B-field
- Correlate hits from 2 closely spaced sensors to form “stubs” compatible with a track $p_T > 2$ GeV (stub is pair of hits in closely spaced sensors of the same module)
- Space/offset between two sensors and stub window is tuneable for p_T threshold throughout the Outer Tracker

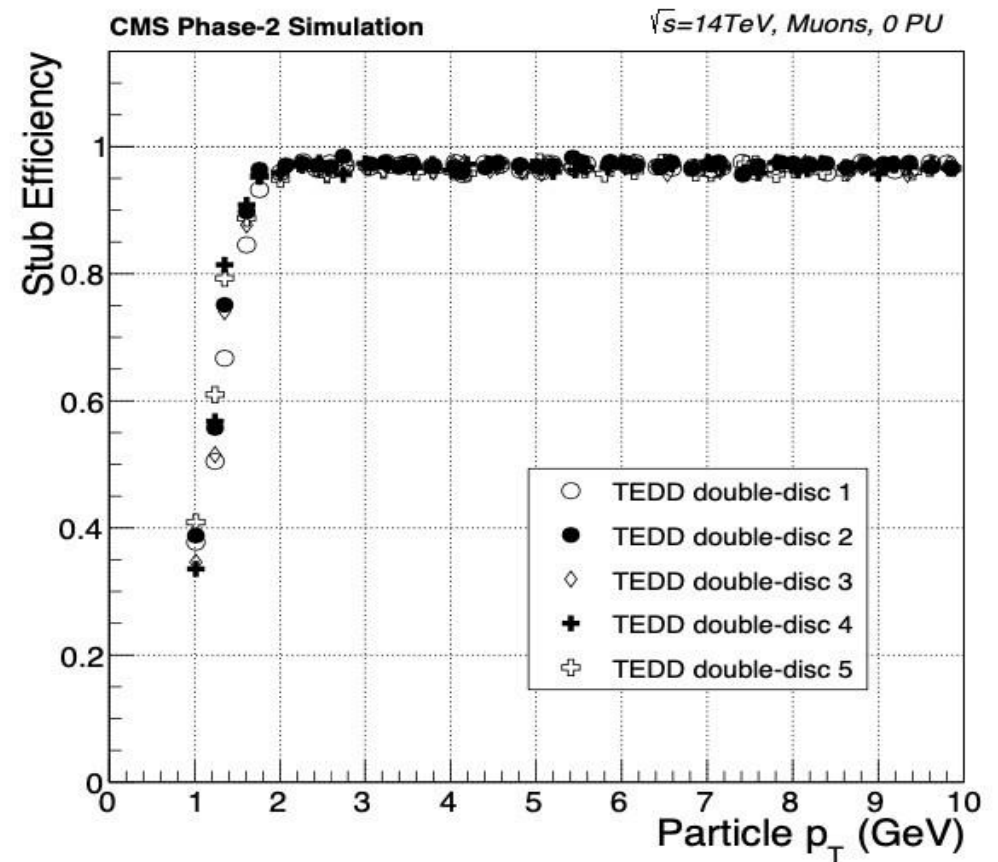
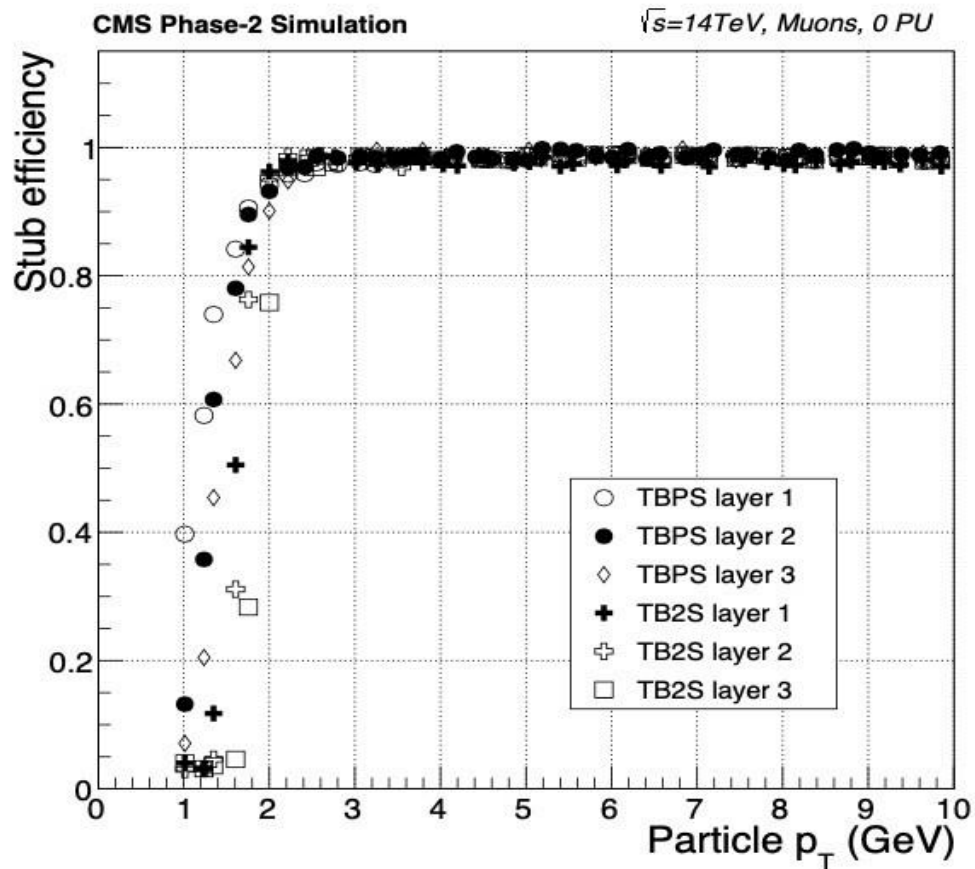
□ Use of Tracking Information at L1 Trigger

- Provision of tracking information at L1 trigger will enhance performance (currently only muon and Calo.)
- Can't read out all information at 40MHz → reduction of data volume at front-end needed
- majority of hits are from low p_T tracks → select hits from tracks with $p_T > 2$ GeV (reduction by factor of 10)
- “Stubs” are sent to the back-end at 40MHz → track reconstruction → L1 trigger decision
- On receipt of a L1 trigger, the complete event information is read out (750kHz)



Phase 2 Tracker Performance

➤ Stubs well reconstructed with about 99% efficiency



Tracker and GEM Upgrade Funding by Govt of Pakistan

- Two Exp. HEP related PC-1's approved by Govt. of Pakistan, namely,
 1. The upgrade of the Compact Muon Solenoid (CMS) Silicon Strip Tracker and GEM detectors
 - ❖ Project Cost: **PKR 275.75 +41 Million (~1.7 M CHF)** (from 2018-onward)
 2. Upgrade of the Exp. HEP laboratory and IT infrastructure at NCP
 - ❖ Project Cost EHEP Lab Upgrade: **PKR 95.94 Million** (from 2018-2020)
- Total funding of ~2.5 M CHF

GE1/1 Project: Assembly and testing of GEM detectors

GE1/1 assembly and testing in Pakistan

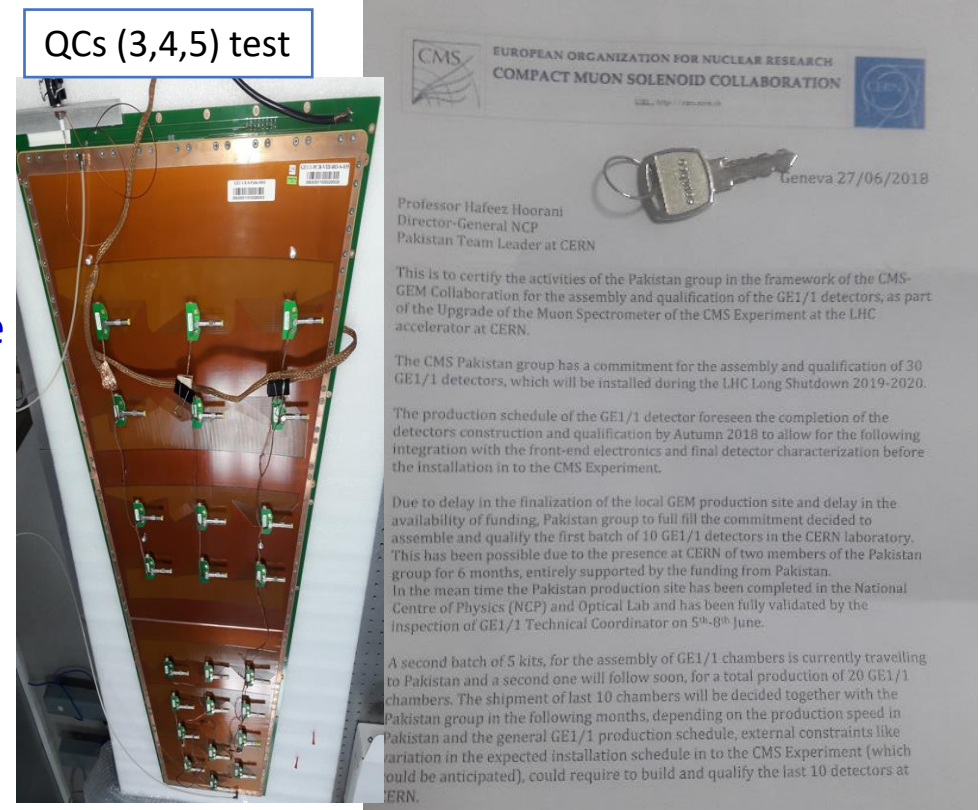
- GE1/1 detector assembly inside Clean room of class 10k
- Our assembly/testing sites were validated by CERN team in June 2018
- GEM detectors were assembled and tested successfully
- After Quality Control, the GEM detectors were shipped to CERN and installed as part of CMS experiment
- Worked on development of GEM software database



QCs setup at NCP



Site validation



QCs (3,4,5) test

R&D for Phase II upgrade of CMS Tracker

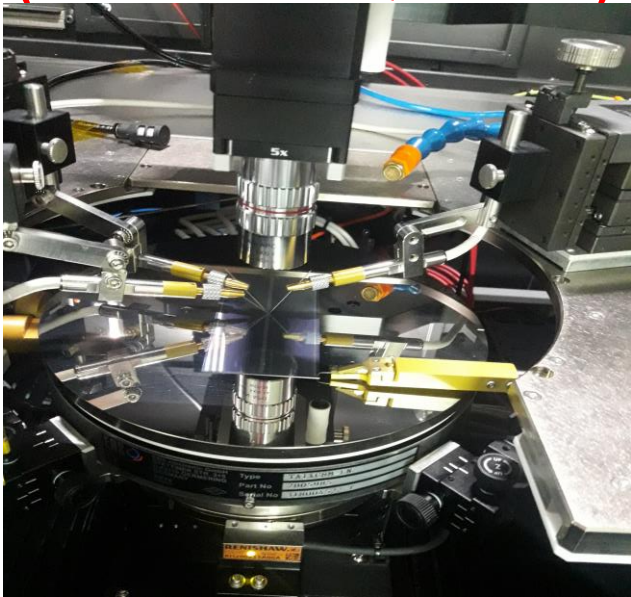
➤ Project started from scratch

➤ Major sub-projects:

1. Lab development 2. Training of Manpower

3. Qualification and testing of silicon sensors and modules. NCP is SQC Center

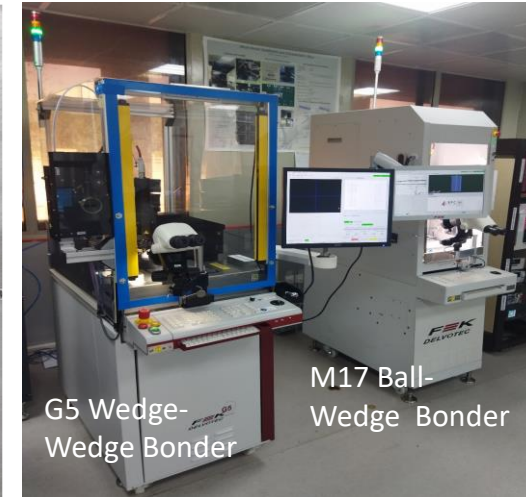
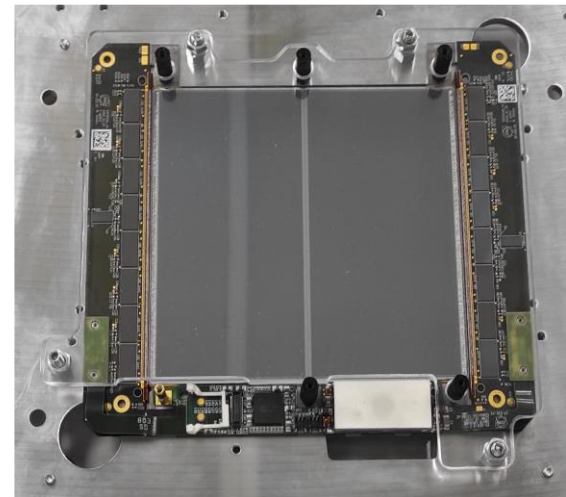
(total six CMS SQC centers)



4. Assembly/testing of silicon modules at NCP. Prototyping finished. Built, tested and validated

NCP is silicon module assembly center

(total eight CMS 2S module assembly centers)



5. Building 410 Al-CF TB2S ladders at NCP. Three prototypes successfully built at NCP and validated at CERN.

For production, has been awarded to a local company.

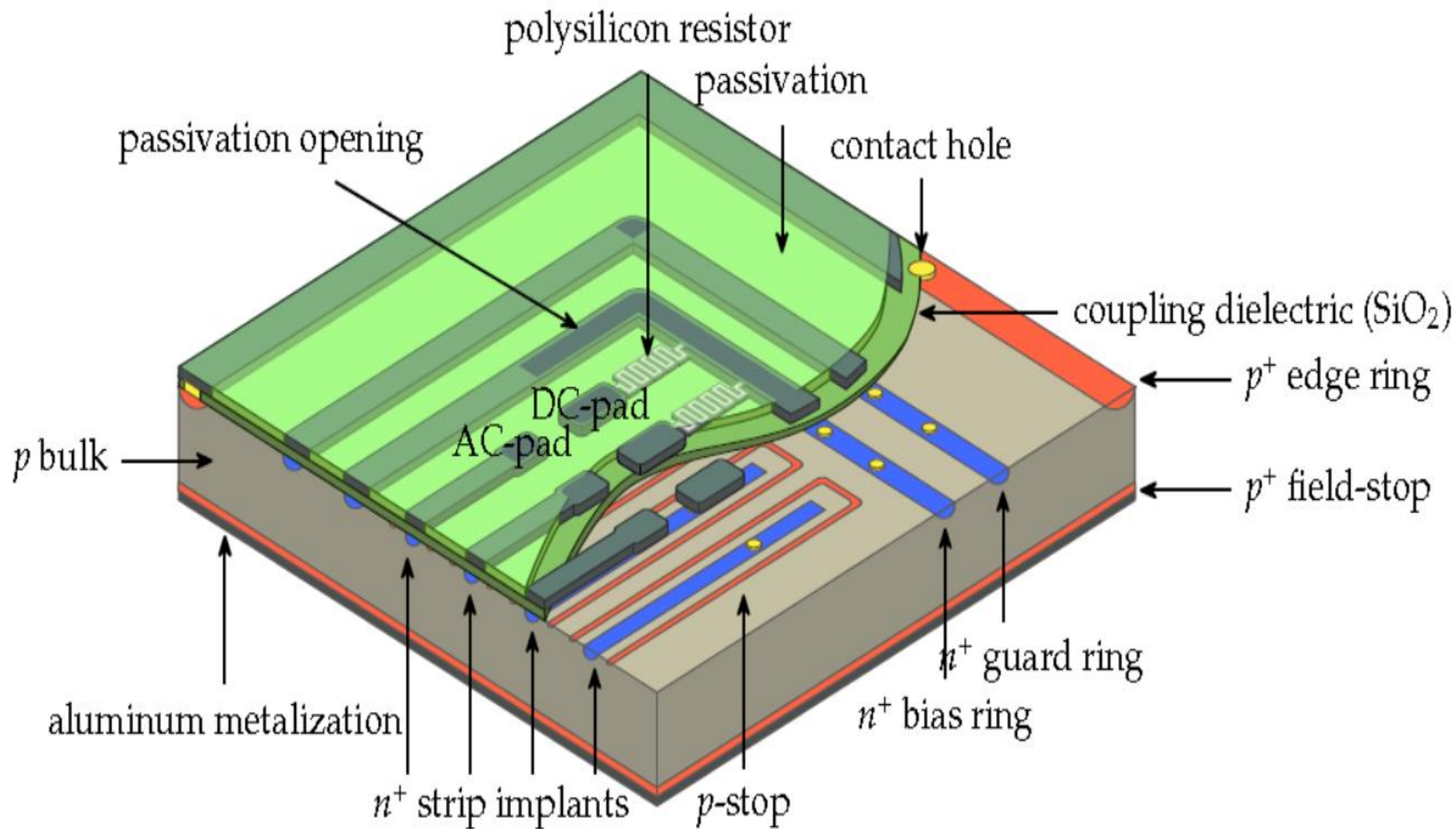
The first three pre-production ladders have been built and sent to CERN. Pre-production ongoing.

(NCP is the only center building TB2S Ladders for CMS)



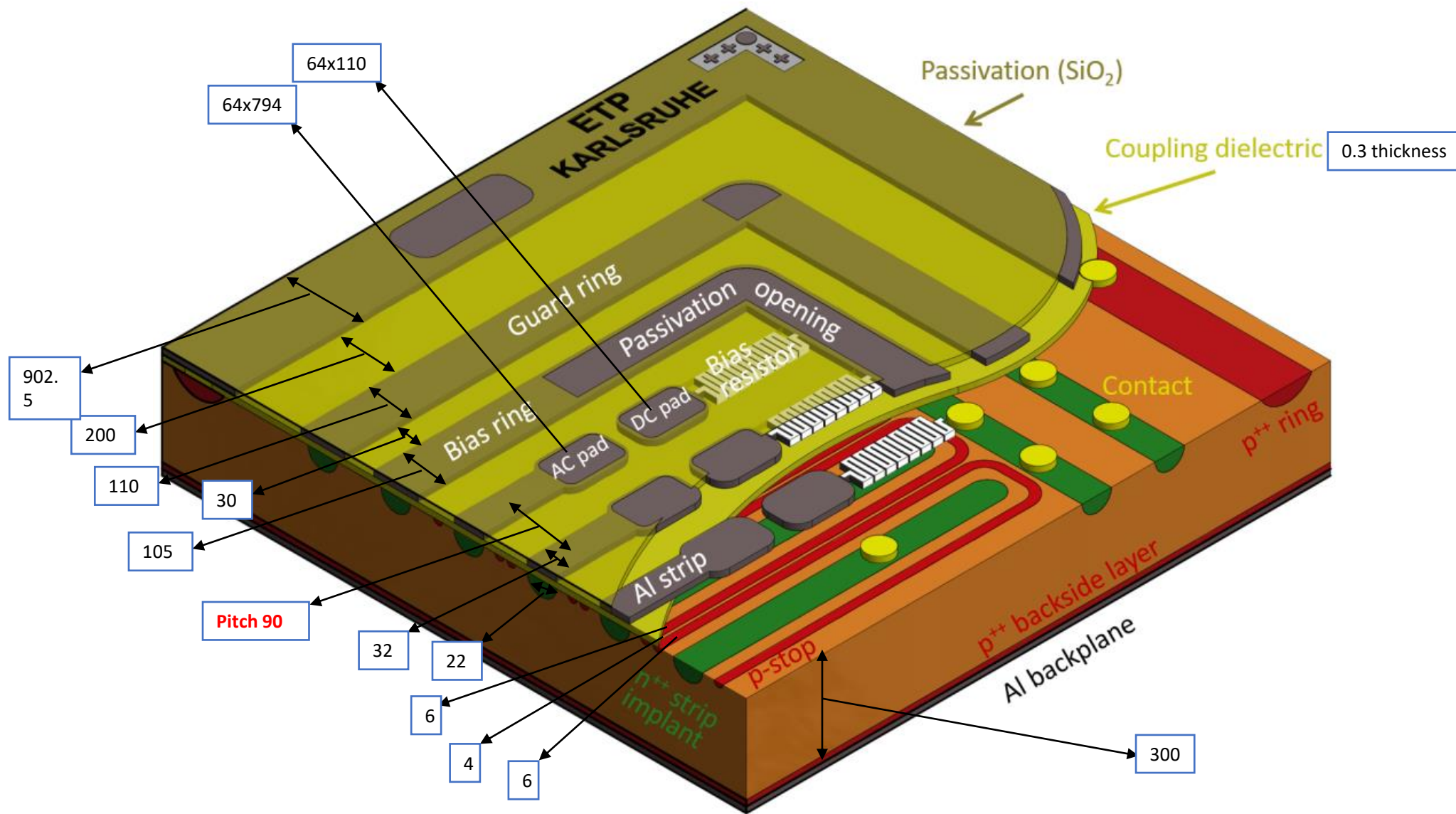
Silicon Sensor Qualification

3D Model of n-in-p Silicon Sensor



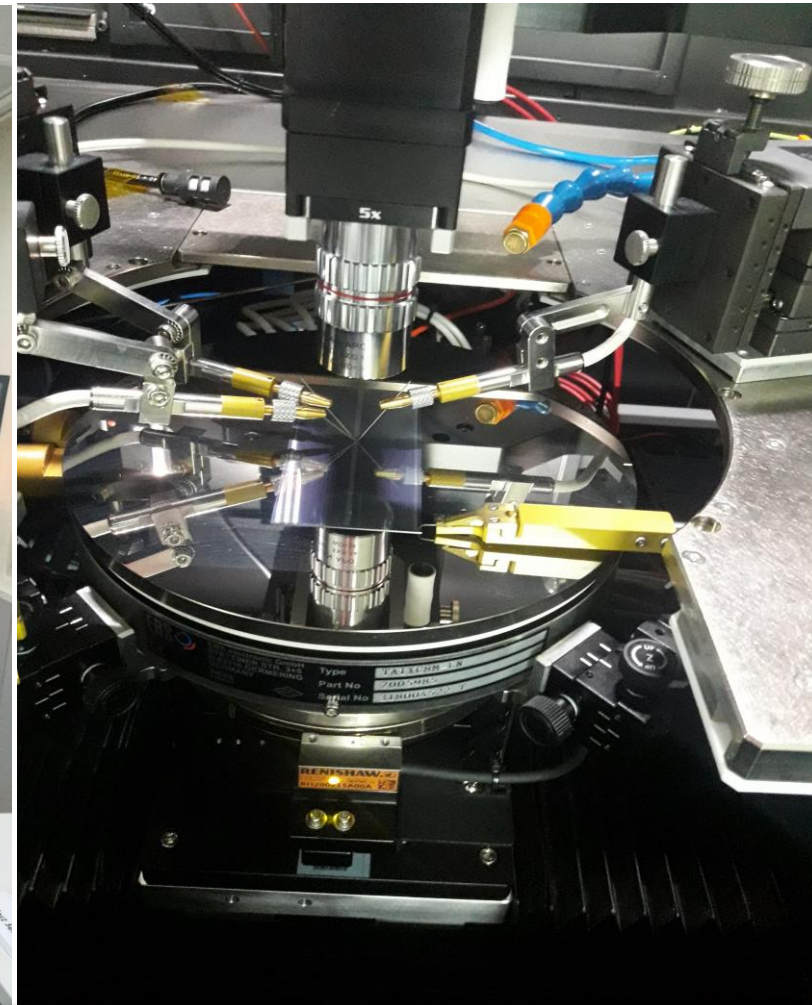
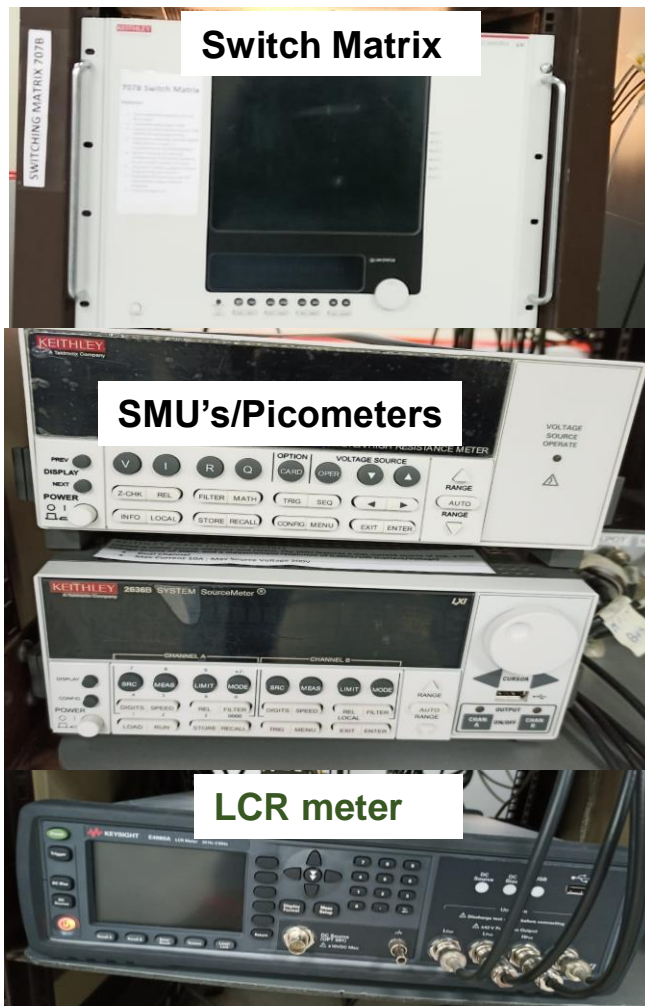
CMS Strip Silicon Sensor

dimensions in μm



Sensors Qualification Lab Setup

- ❑ SQC setup is operational: **MPI Probe Station** with motorized chuck with $2\mu\text{m}$ precision.
 1. Six micro positioners installed.
 2. Switching matrix system (crate and cards)
 3. SMU's and pico-ammeters (Keithley 2636B, 2470 and 6517B)
 4. LCR meter (Keysight-4980A)
- ❑ Fully automatized with indigenously developed LabVIEW programs/vi's
- ❑ **NCP is validated silicon sensor qualification center of CMS!**

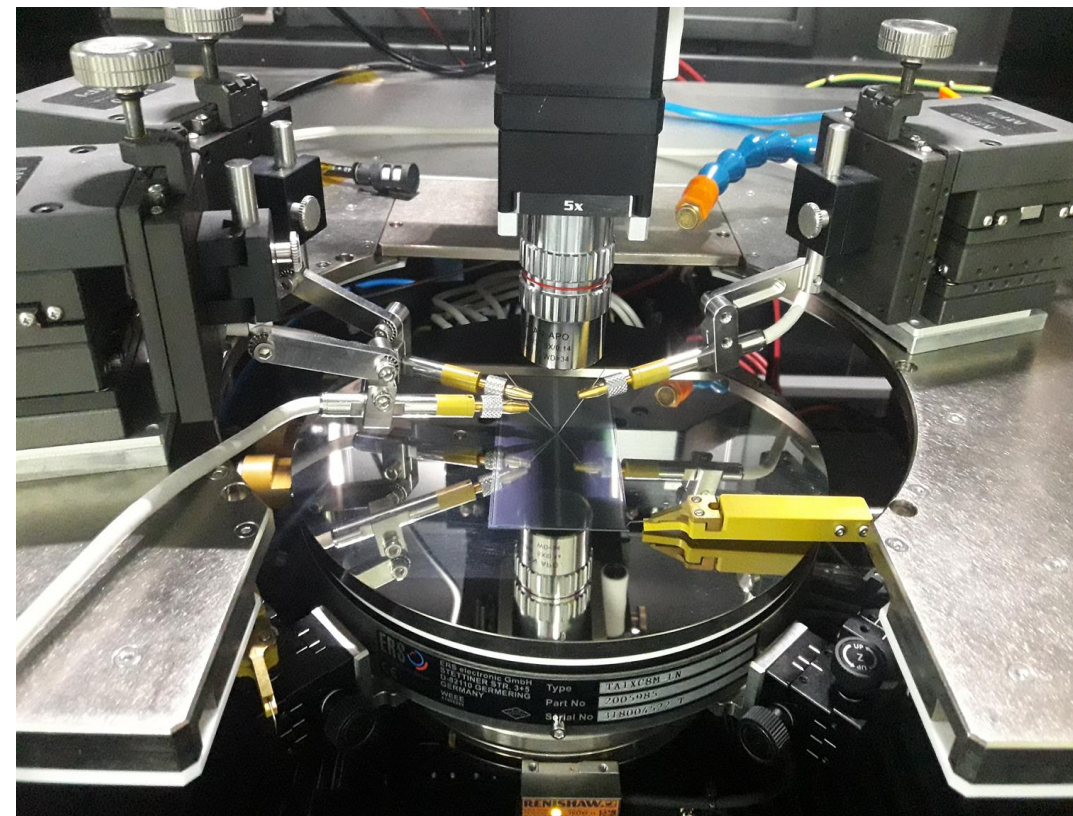
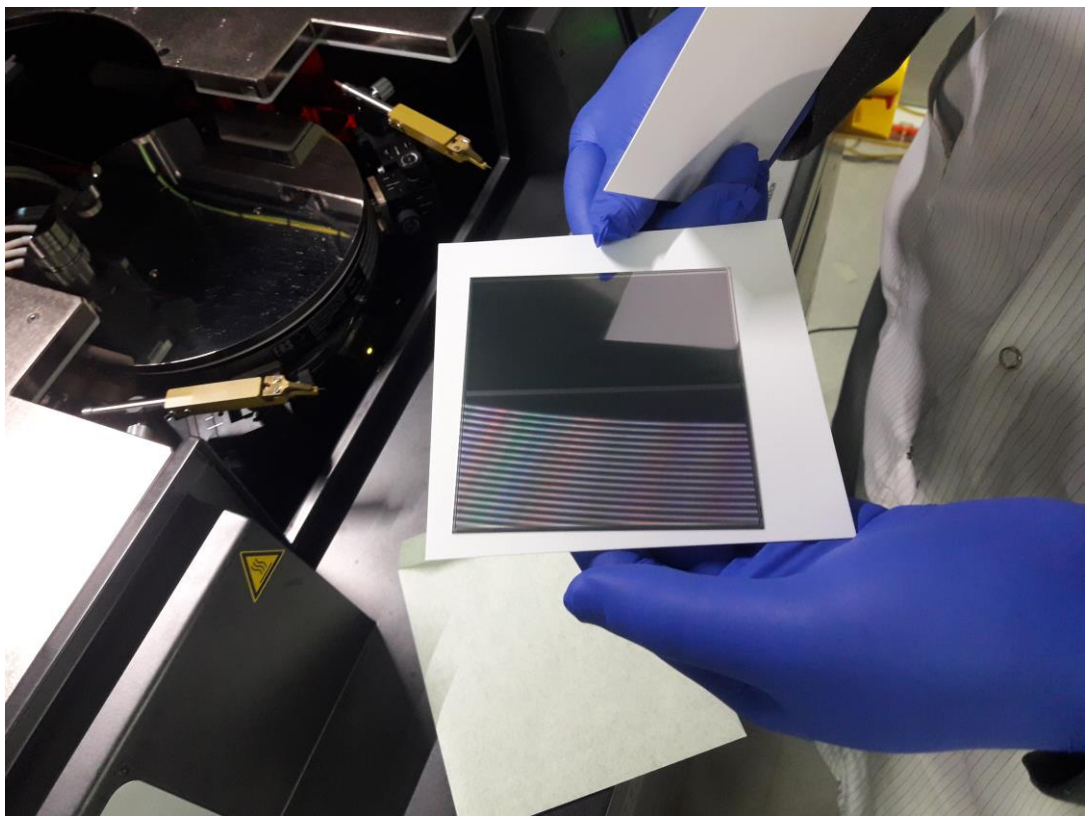


Silicon Sensors Quality Control setup at EHEP Lab, NCP



About 2000 CMS Silicon Sensors have been qualified so far.

Sensors Visual Inspection and Placement



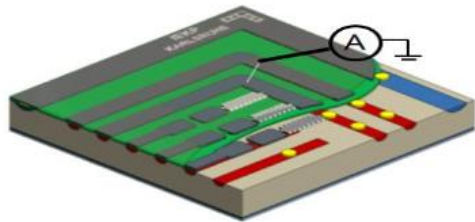
Sensor Storage in environmentally controlled cabinet

- Sensors storage cabinet is available to store sensor with control T and RH
- $T \sim 20-25\text{C}$ and $RH \sim 10-15\%$
- To keep stable environment in the cabinet, only it is opened for a short time just to put in and out the sensors
- Cleanroom T and RH is continuously controlled monitored at $20-25\text{ C}$ and $40-45\%$ respectively

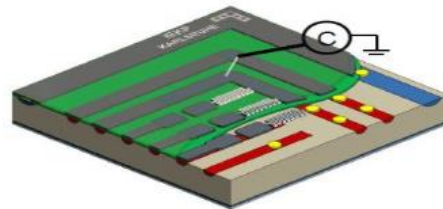


Silicon Sensor Qualification

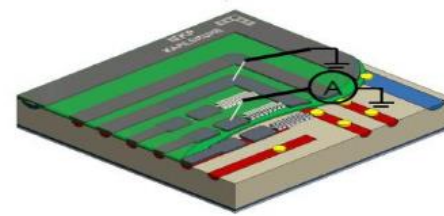
1. I_V
Sensor current vs
Bias



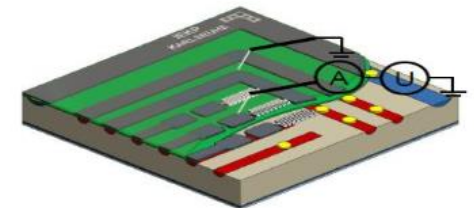
2. C_V
Sensor capacitance vs
Bias



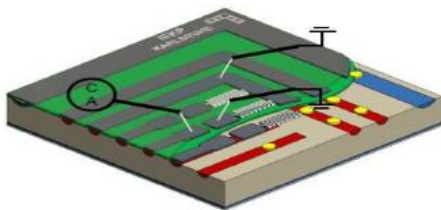
3. I_{leak}
Strip leakage
current



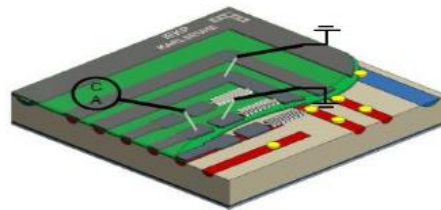
4. R_{bias}
Strip bias resistor



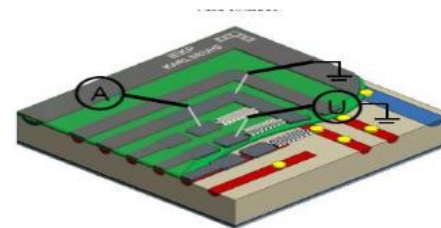
5. C_{Coup}
Coupling capacitance



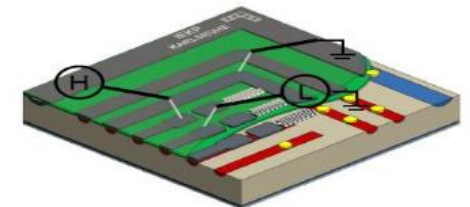
6. I_{diel}
Dielectric current



7. R_{int}
Interstrip resistance



8. C_{int}
Interstrip capacitance



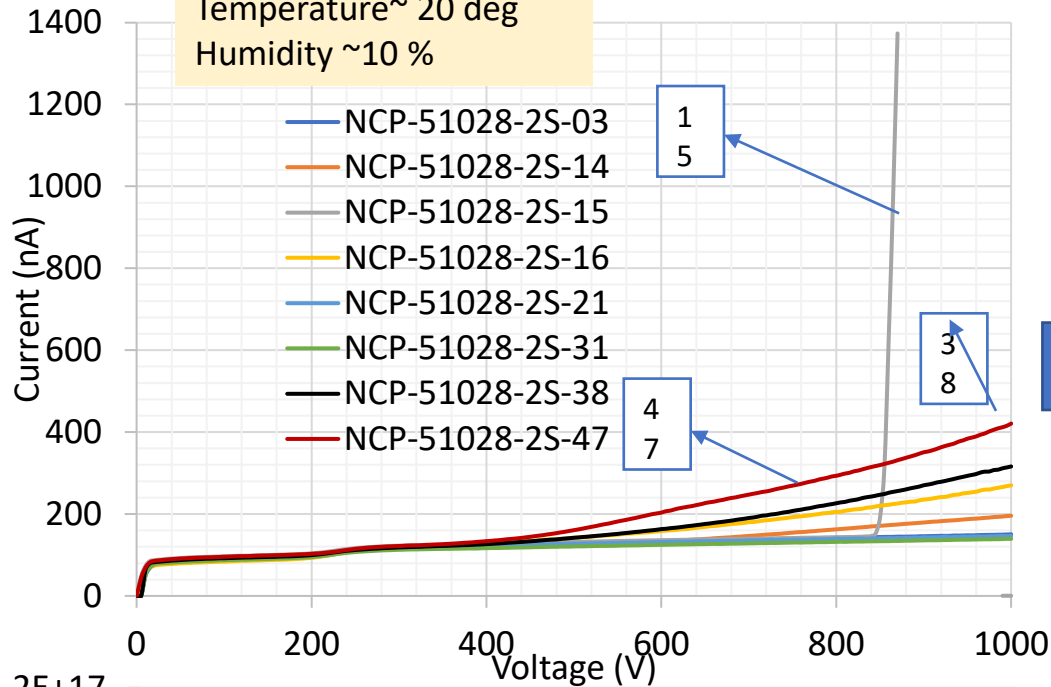
SQC Requirements

#	Parameters	Limits
1	Global IV	600V@7.5 μ A (upper limit) 800 V, I800 < 2.5 x I600 1000 V, I1000 < 2.5 x I800
2	Global CV	~ 3-4 nF
3	Strip Current	50nA @ 600V
4	Coupling Capacitance	~ 132 pF
5	Inter-strip Capacitance	< 0.5 pF/cm
6	Dielectric current	< 10 nA@10 V
7	Inter-strip Resistance	> 50 G Ω cm
8	Polysilicon resistance	~ 1.5 \pm 0.5 M Ω

IV and CV (Batch no. 51028)

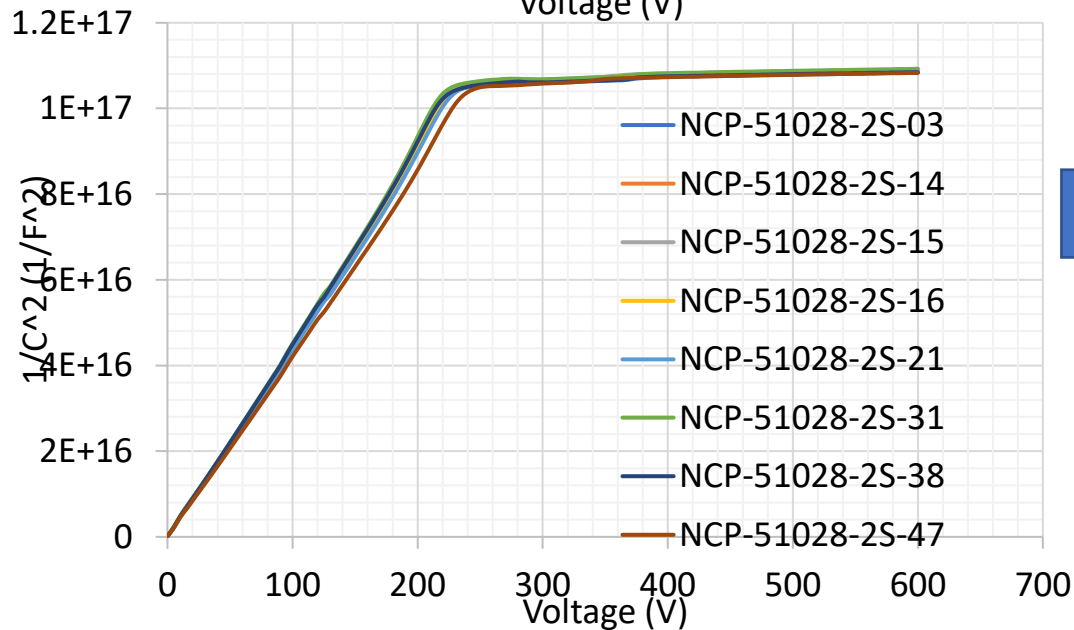
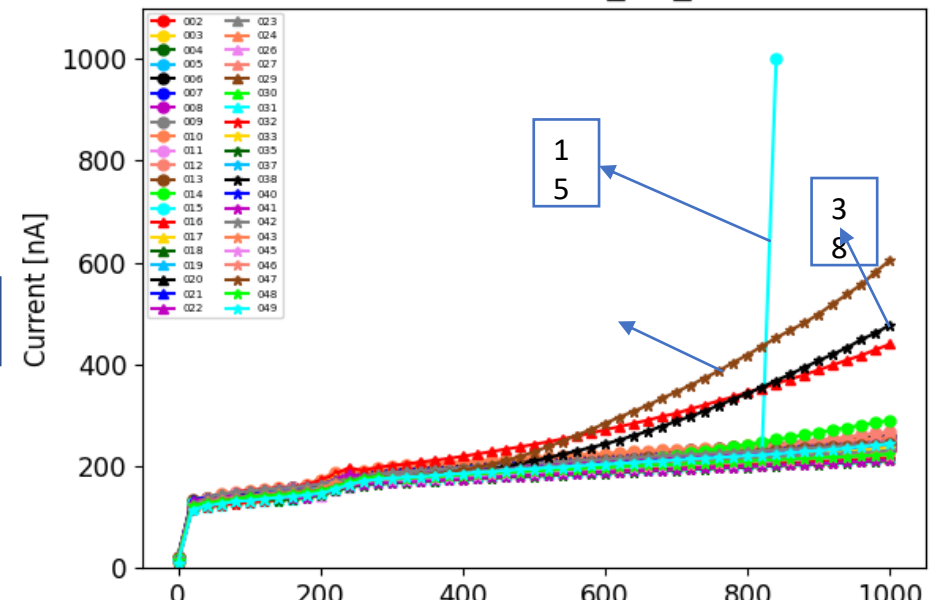
NCP

Temperature ~ 20 deg
Humidity ~ 10 %

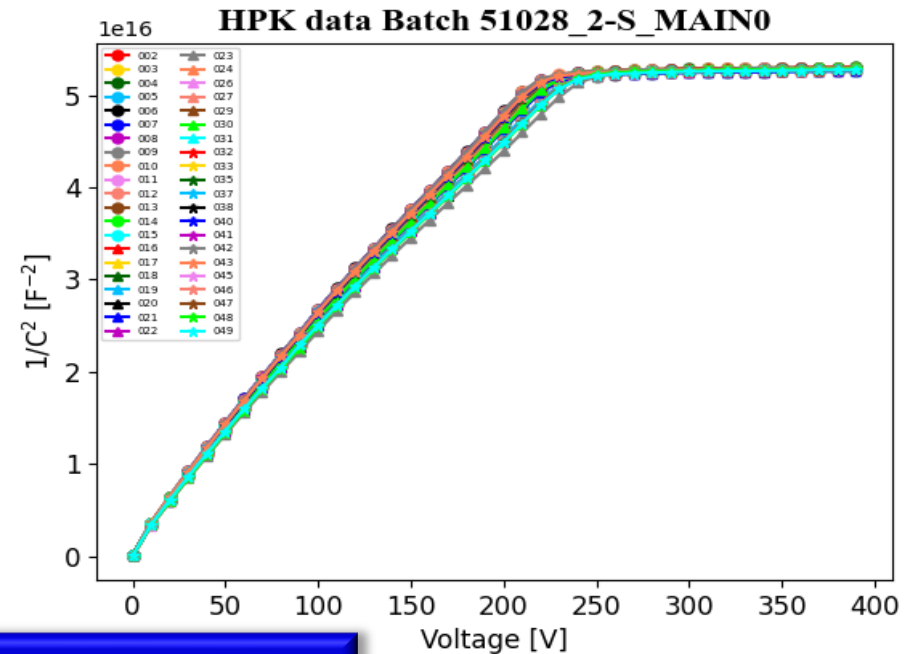


IV

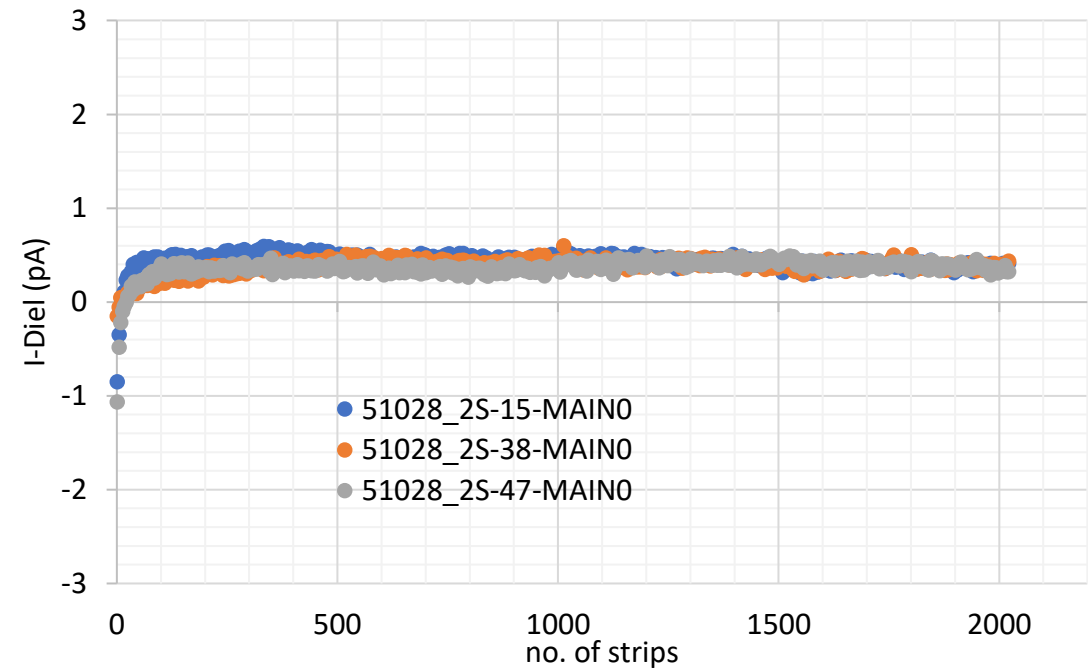
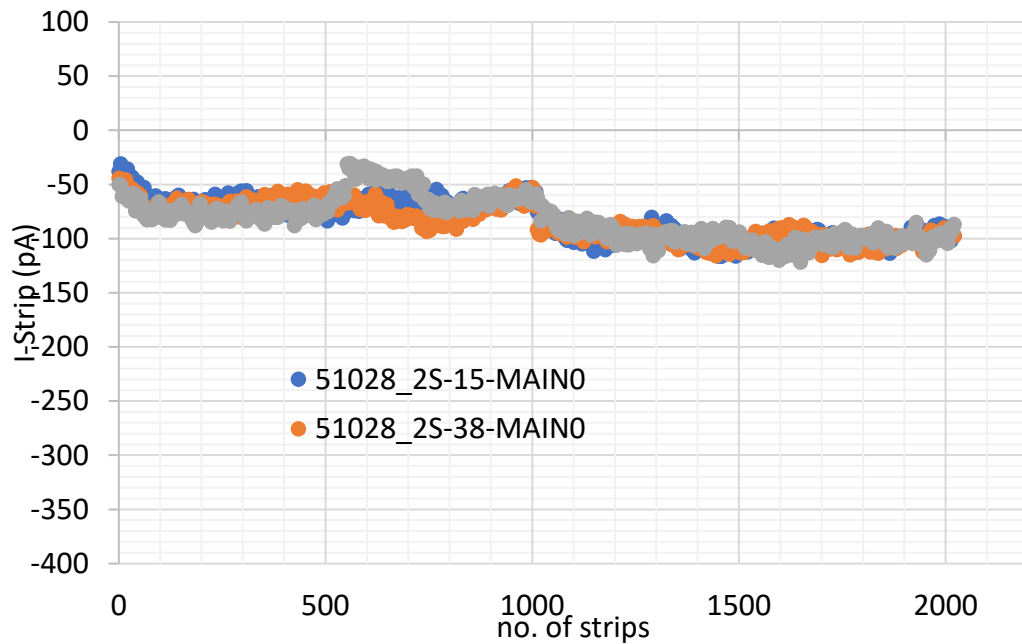
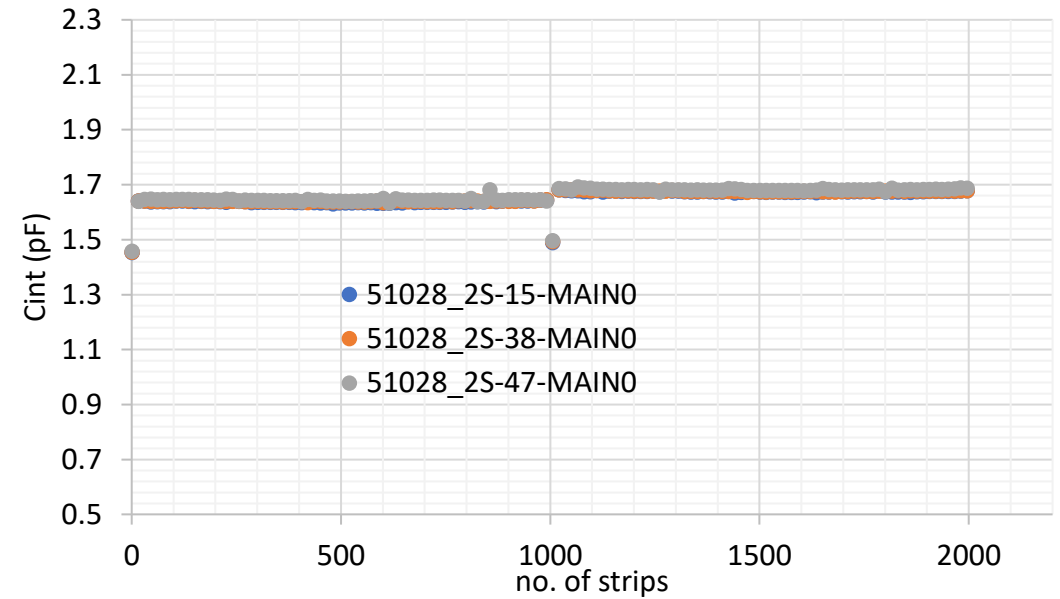
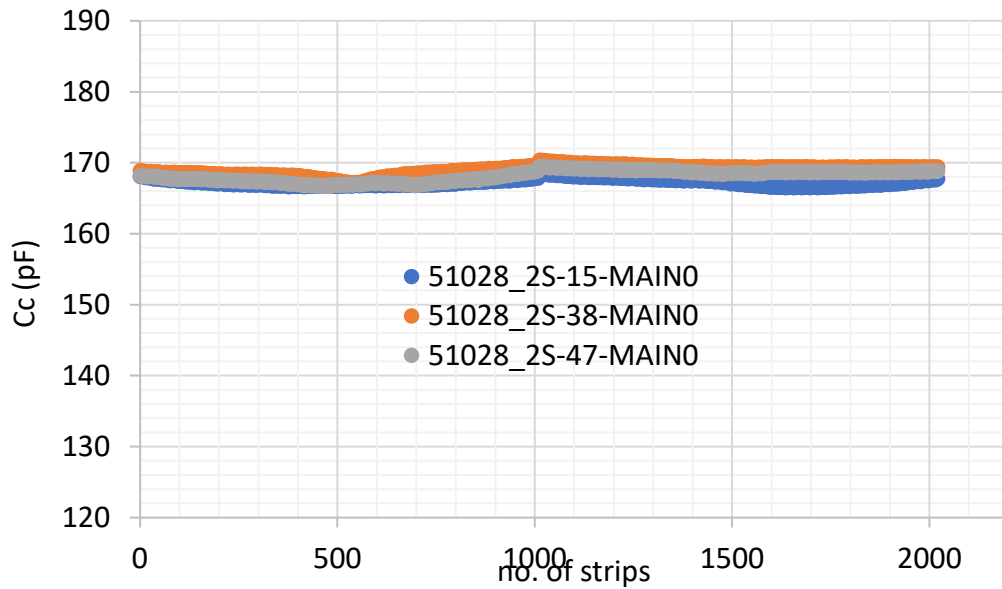
HPK data Batch 51028_2-S_MAIN0



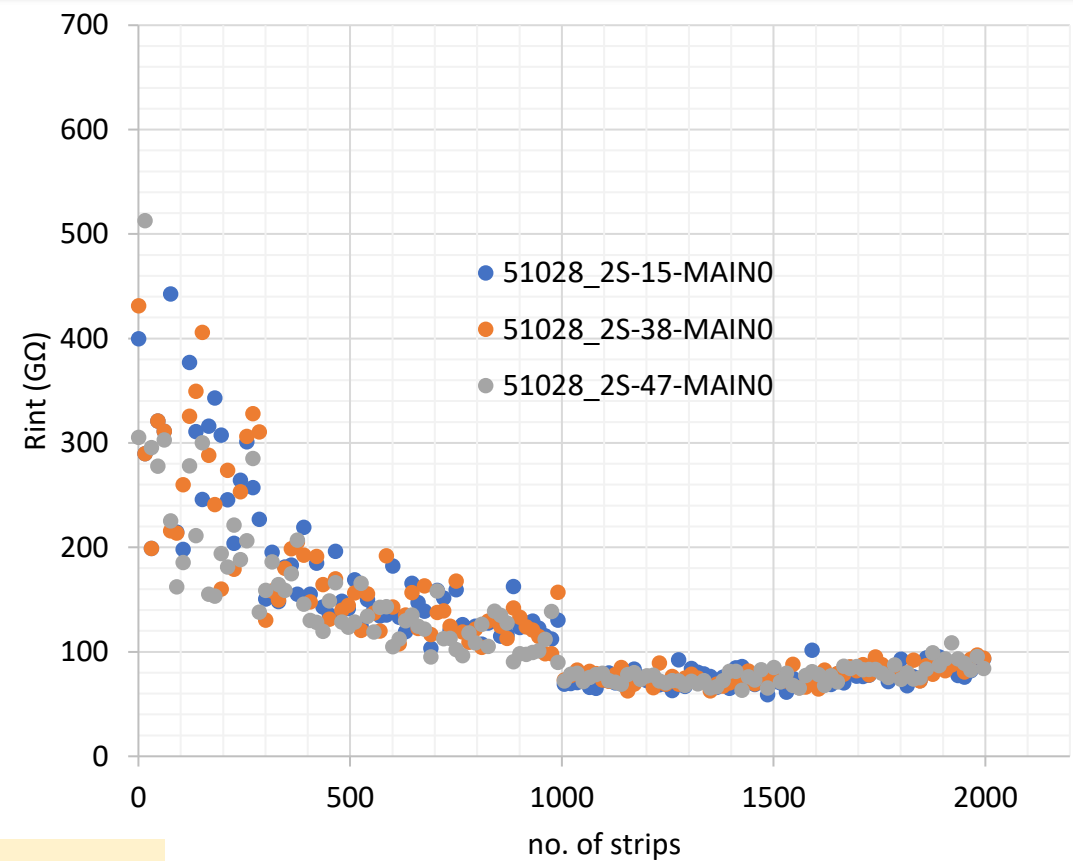
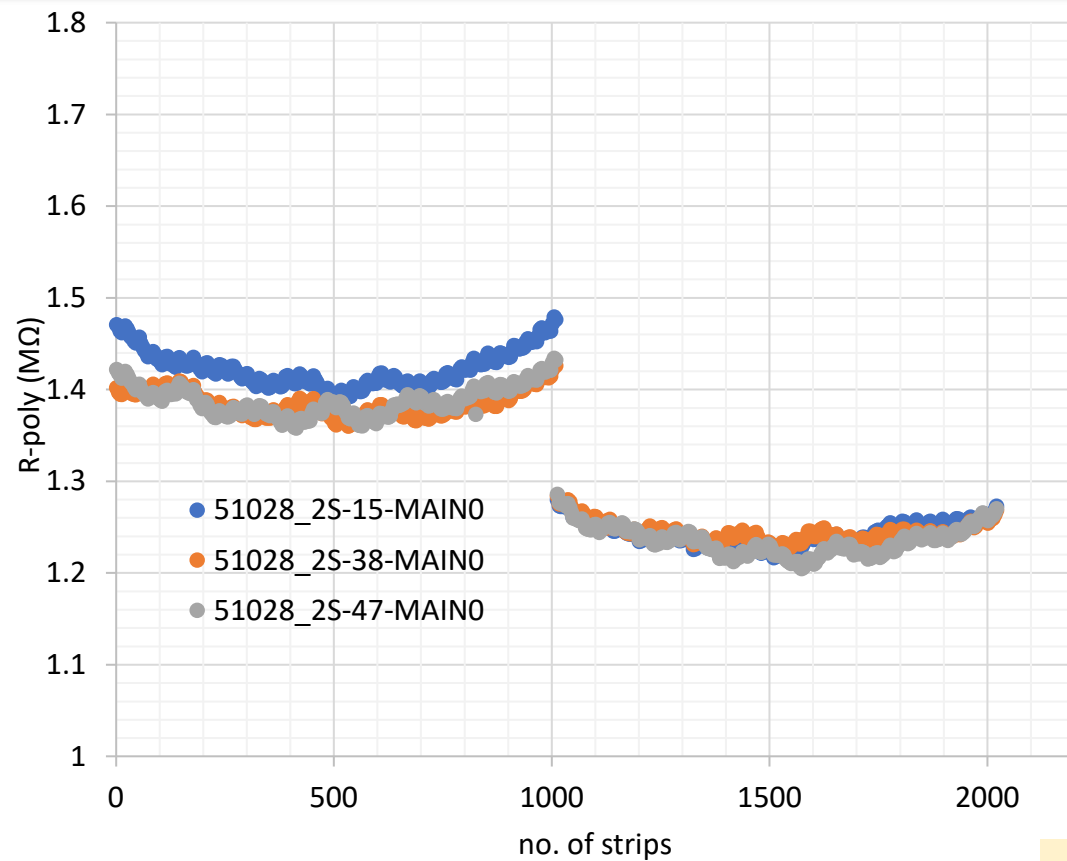
CV



C_c , C_{int} , I_{strip} and I_{diel} Batch no. 51028



R_{poly} and R_{int} (Batch no. 510280)



Summary

Sensor no.	I@600 (nA)	I@800 (nA)	I800/I600	Vfd	I-strip (pA)	Rpoly (M Ω)	Cac (pF)	Cint (pF)	Rint (G Ω)
51028_2S_15	-135.84	-143.01	1.05	~225	-82.19	1.33	167.20	1.65	131.76
51028_2S_38	-163.38	-226.48	1.38	~225	-81.82	1.31	168.99	1.63	130.63

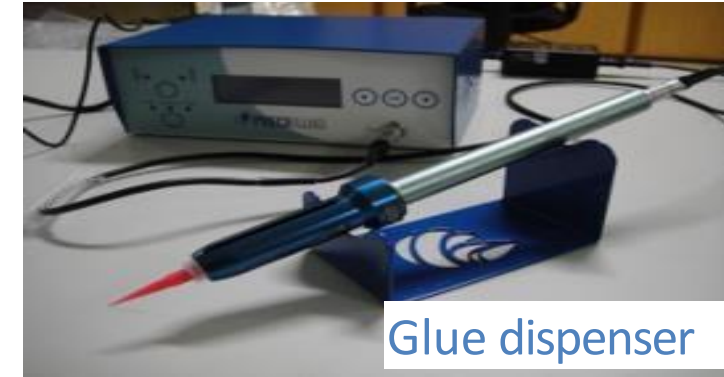
54 batches with about ~2000 silicon sensors have been qualified at NCP

Silicon Module Assembly Setup

- ❑ Developed Lab Setup for module assembly and testing
 - Build **8 mechanical modules** to validate dimensional accuracies and refine/fix locally made assembly jigs
- ❑ Built **eight silicon modules**(including kickoff modules). Tested, validated and presented in CMS meetings.
- ❑ **NCP is one of the eight silicon module assembly center**

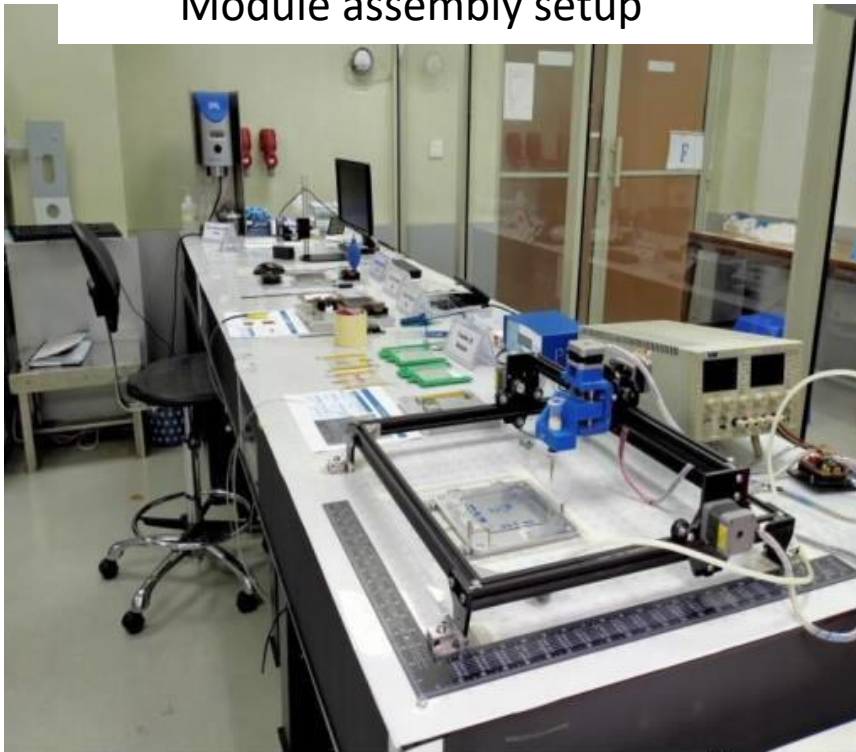


Glue Mixer

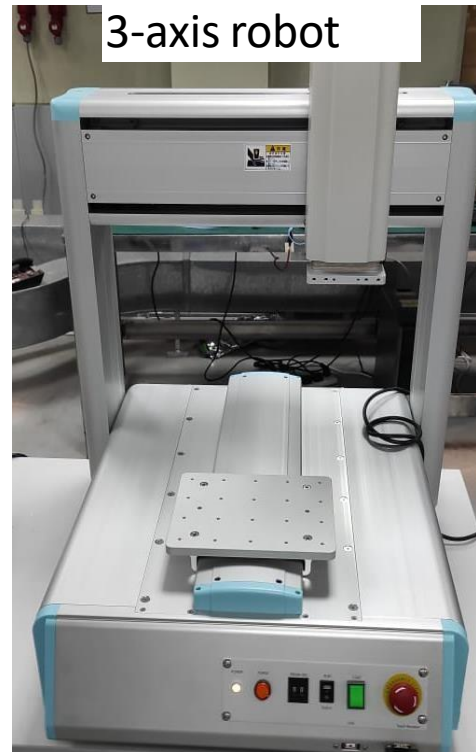


Glue dispenser

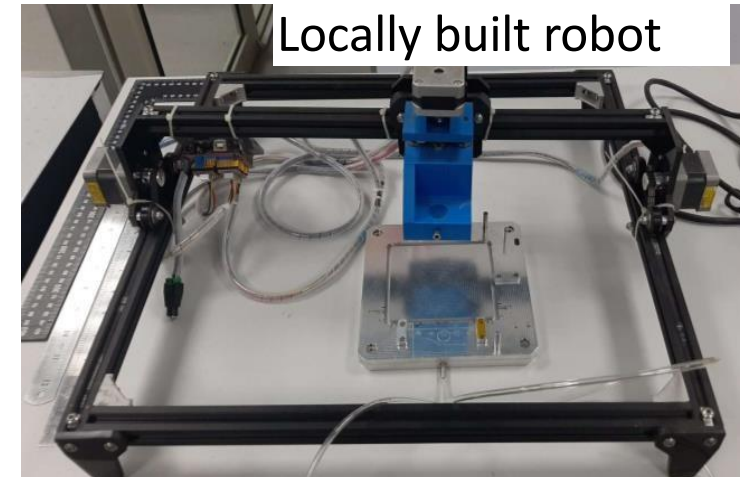
Module assembly setup



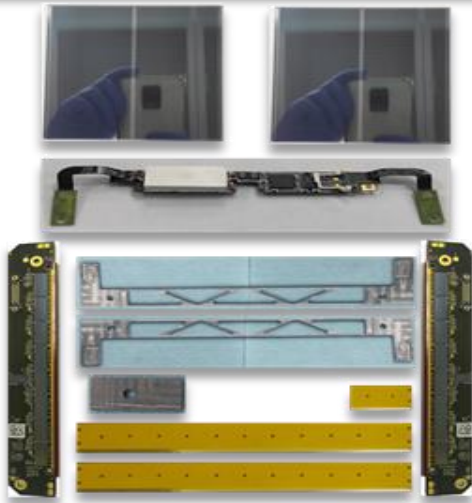
LH-300T Robot
3-axis robot



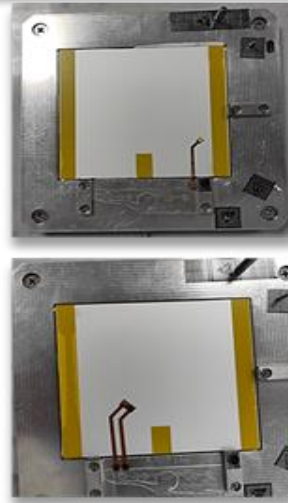
Locally built robot



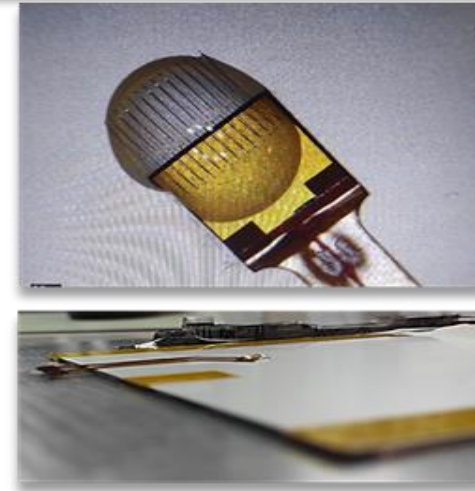
Module Assembly Flow Chart



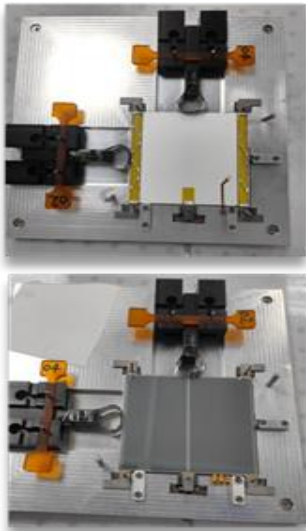
STEP 1: Optical Inspection



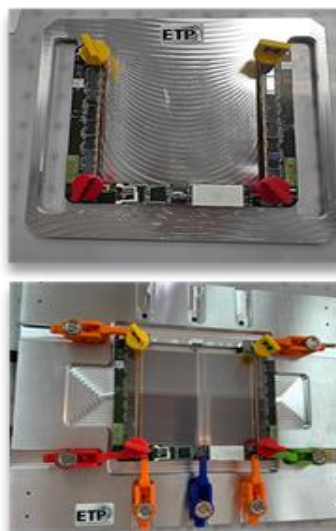
STEP 2: PI-Strips & HV-tail Gluing



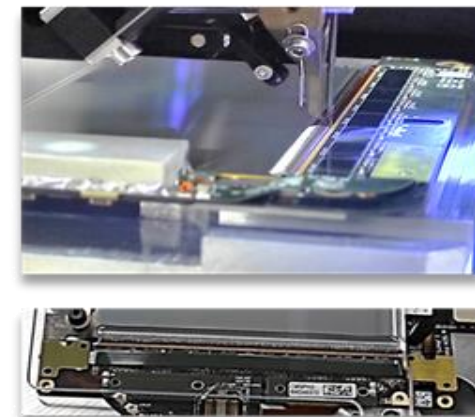
STEP 3: HV-tail Wire-bonding & Encapsulation



STEP 4: Bare-Module Assembly



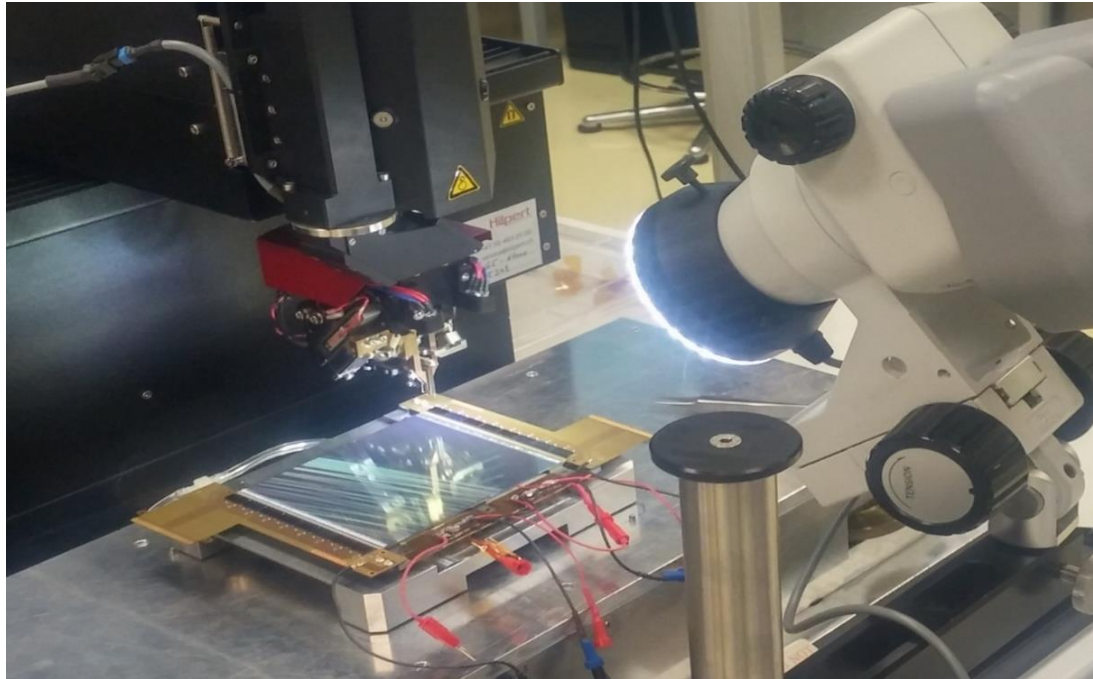
STEP 5: Hybrid Gluing



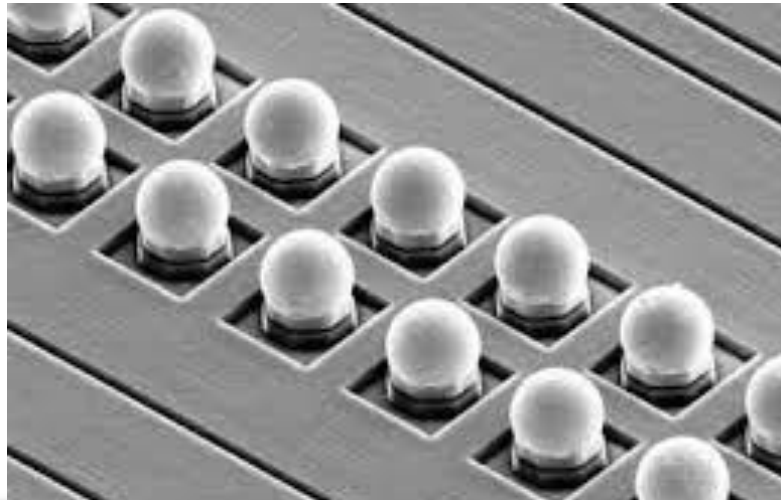
STEP 6: Sensor-to-FEH Wire-bonding & Encapsulation

Wire/ball Bonding Setup for Silicon Modules

Wire bonding setup is operational at NCP



Ball-wedge bonding machine is being installed



A unique facility

Wire bonding machine-1



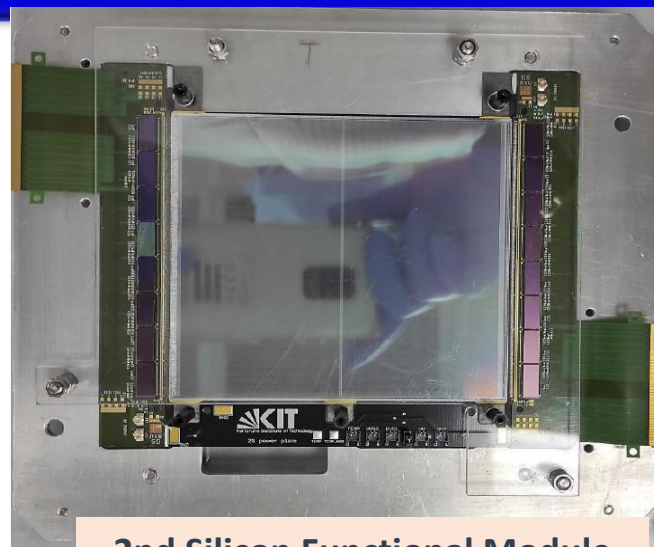
Wire bonding machine-2



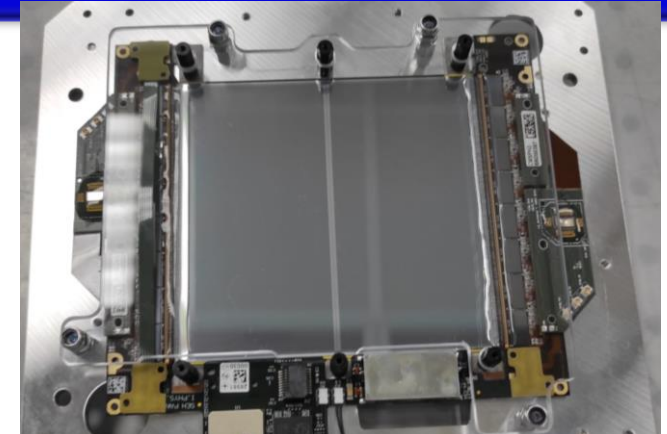
Outer Tracker Modules Assembly at NCP



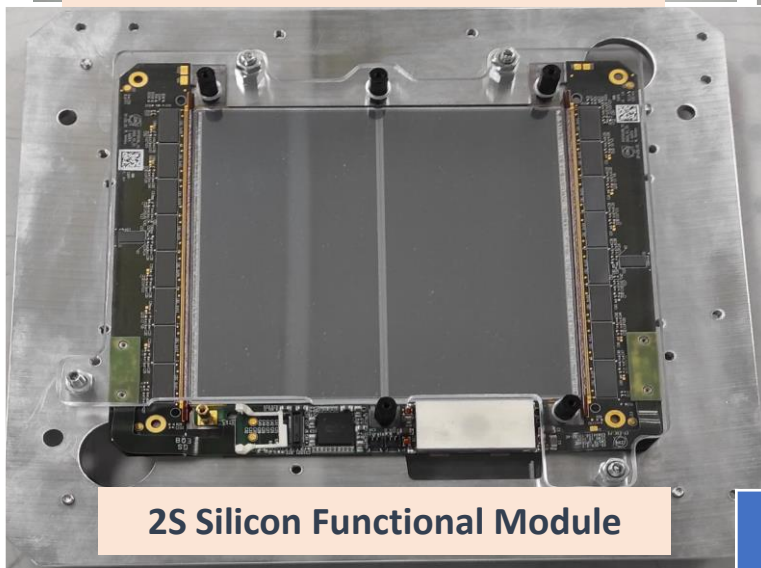
1st Silicon Module



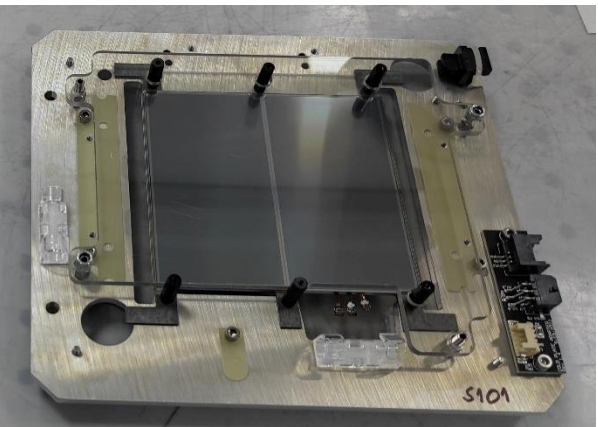
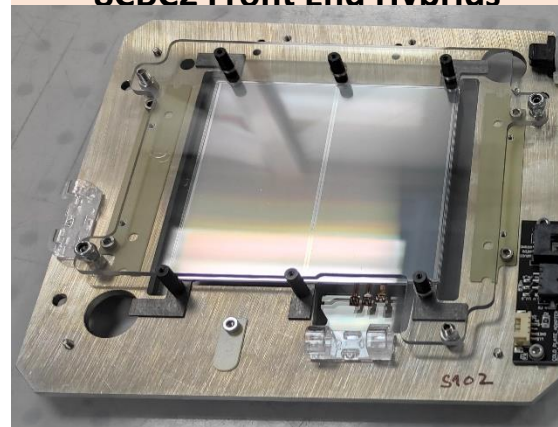
2nd Silicon Functional Module
8CBC2 Front End Hybrids



3rd Silicon Functional Module
8CBC3 Front End Hybrids
Module has been validated at CERN.



2S Silicon Functional Module

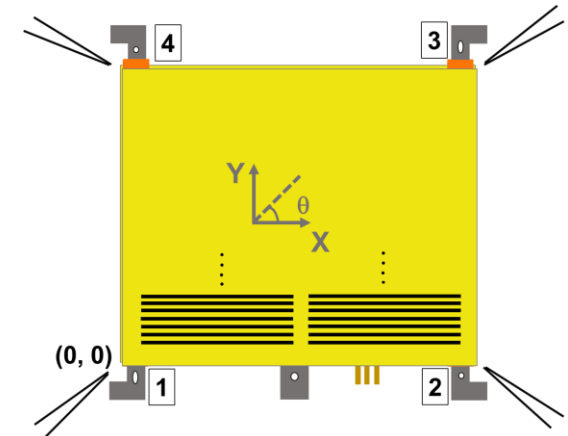
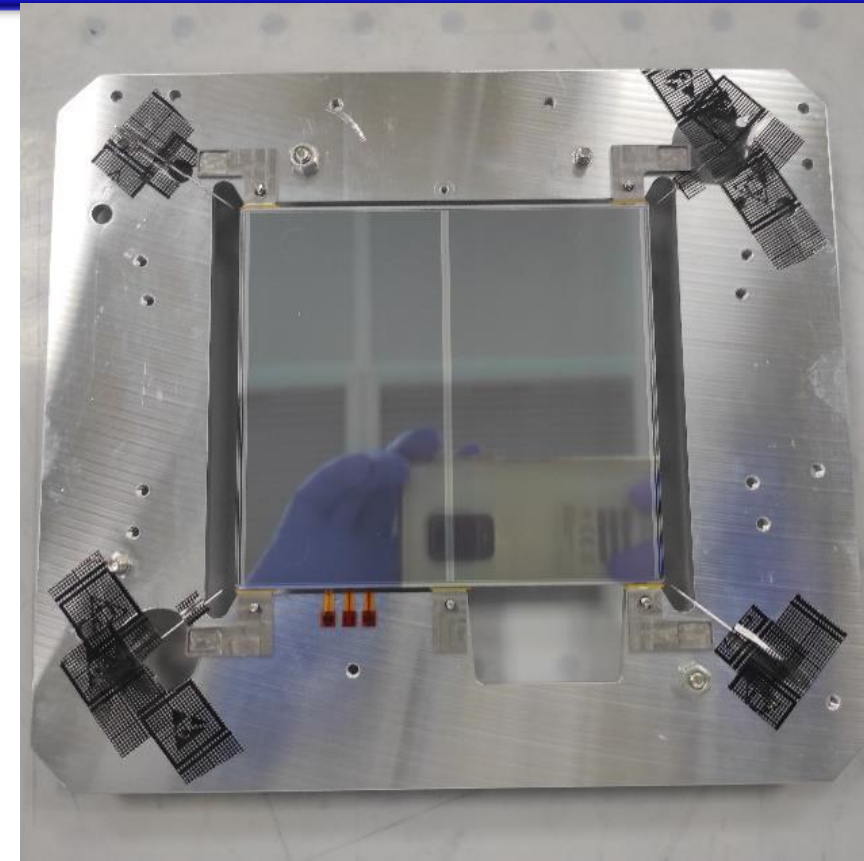
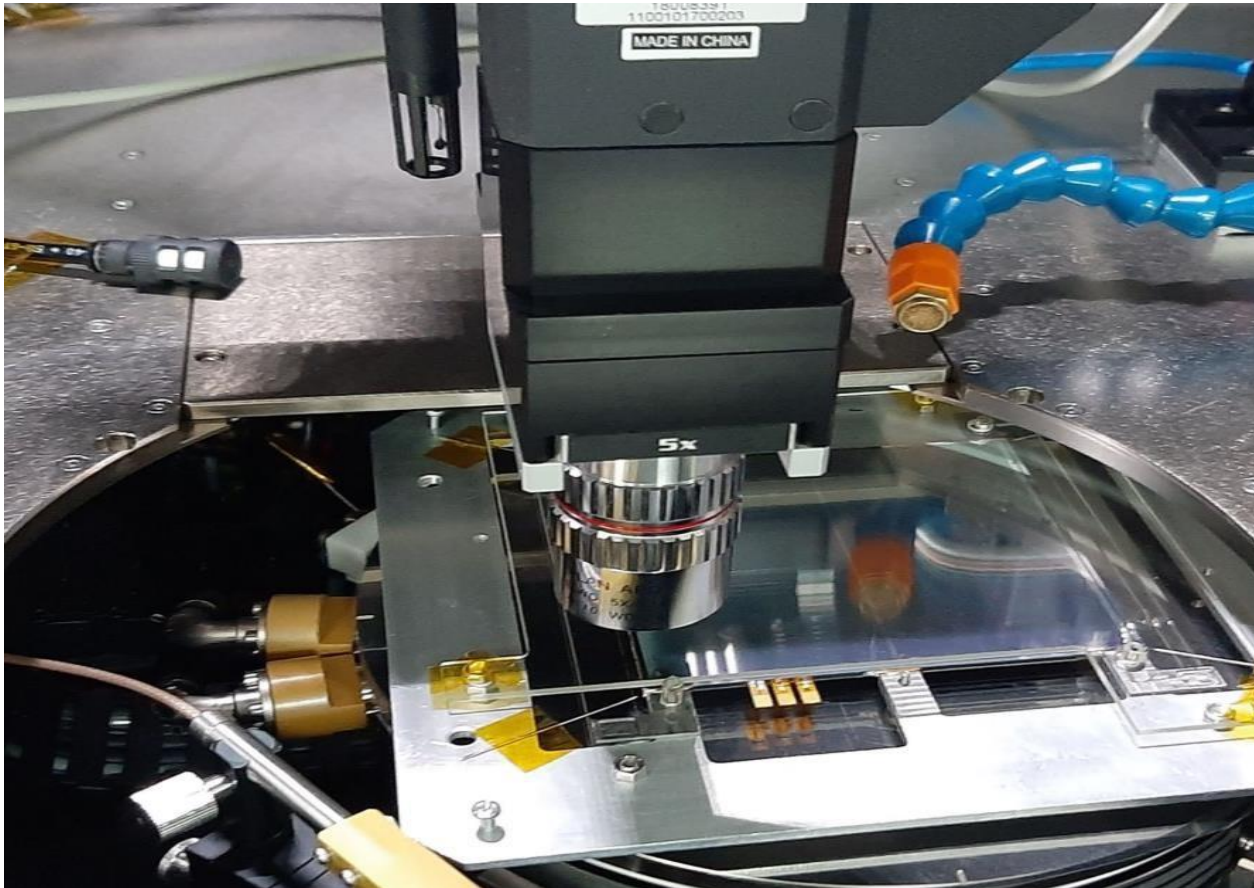


Eight modules built at NCP
so far!

Module	$\Delta\theta$ (μrad) Required < 400 μrad	Δx (μm) Required < 100 μm	Δy (μm) Required < 50 μm
2S_18_5_NCP-00101	51 ± 10	-7 ± 5	-1 ± 5
2S_18_5_NCP-00102	30 ± 10	-6 ± 5	-1 ± 5

Module Metrology

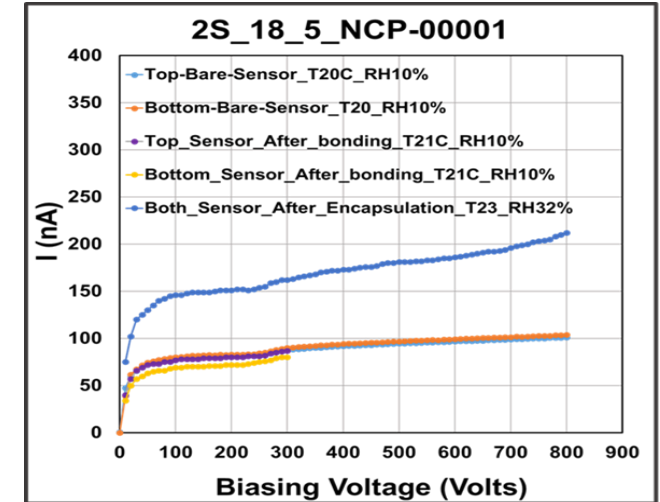
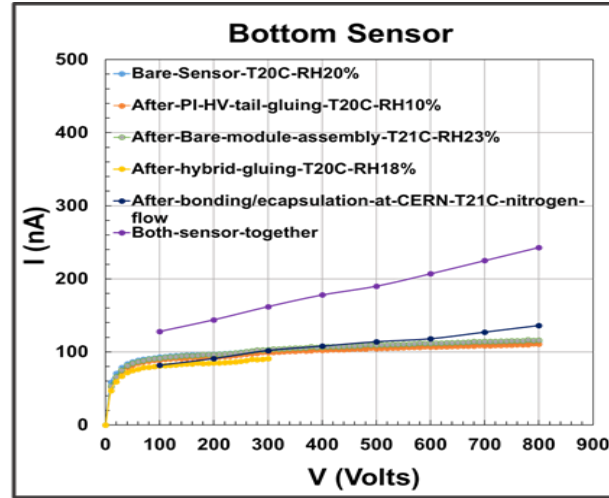
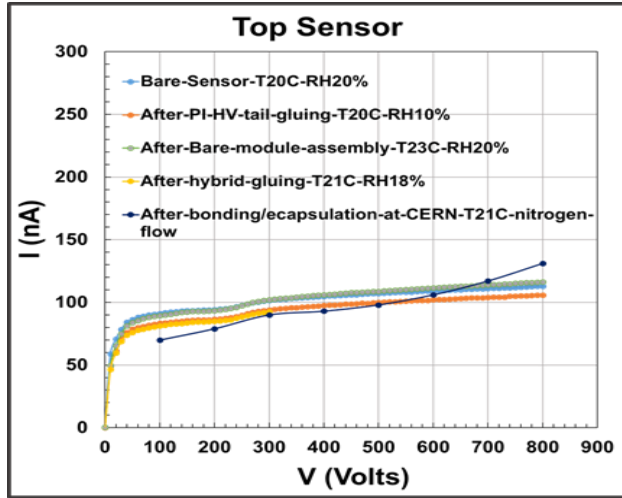
- Needle method locally developed to perform metrology of modules using probe station
- **Validated by measuring misaligned module**



Metrology summary Module Assembled

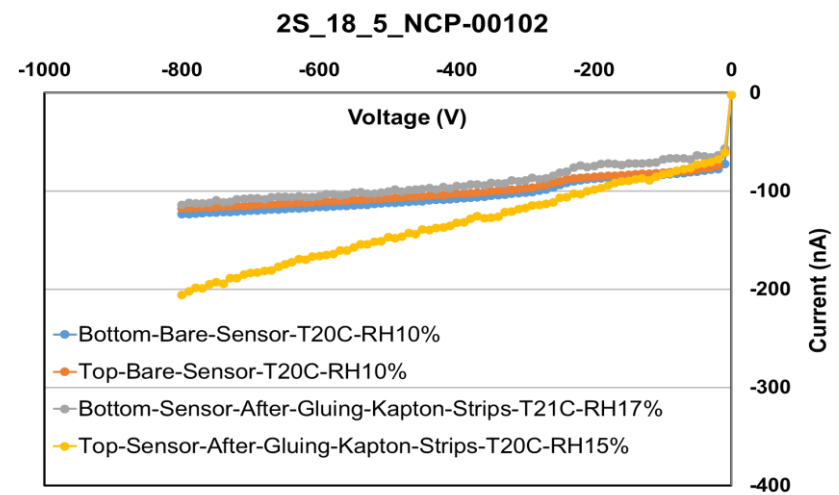
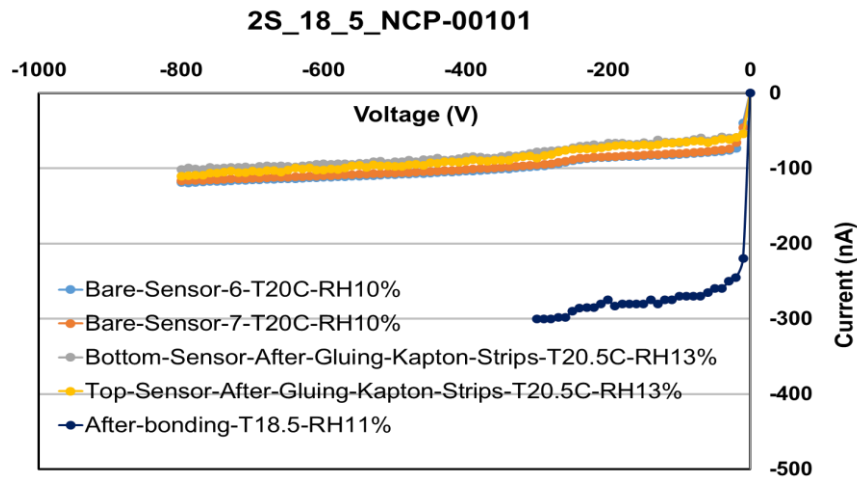
Module Name	Module Type	Module Batch	Δx (μm) tolerance < 100 (μm)	Δy (μm) tolerance < 50 (μm)	$\Delta\theta$ (μrad) tolerance < 400(μrad)
NCP - F01	8CBC2	Prototype	54	14	374
NCP - F02	8CBC3	Prototype	-13	-4	-22
2S_18_5_NCP-00001	2S	Prototype	-15	-13	-22
2S_18_5_NCP-00002	2S	Prototype	-1	-9	-31
2S_18_5_NCP-00003	2S	Prototype	3	3	24
2S_18_5_NCP-00101	2S	Kick-off	-7	-1	51
2S_18_5_NCP-00102	2S	Kick-off	-6	-1	-30

IV Measurements at different assembly steps



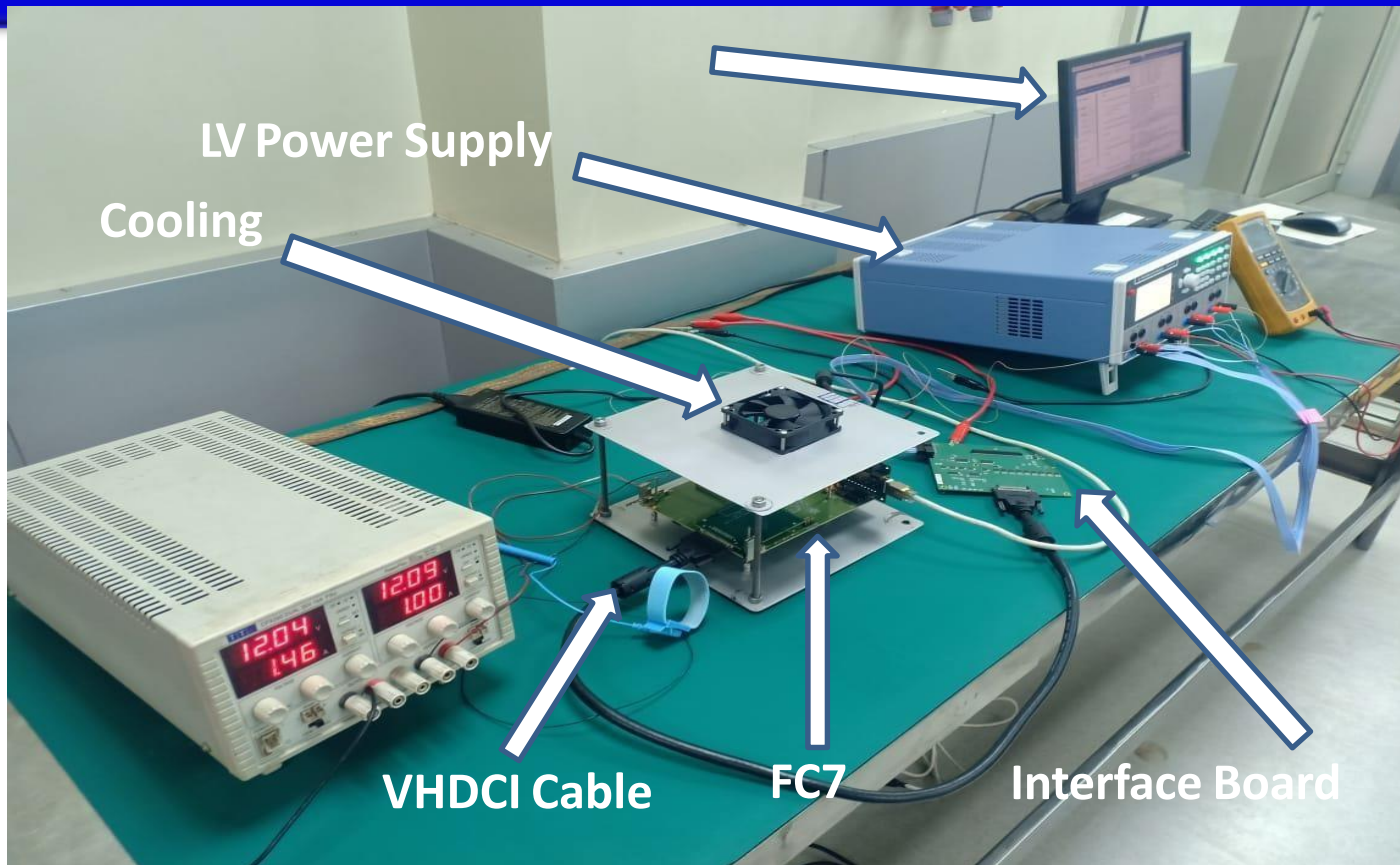
8CBC3 Prototype Module

2S Prototype Module

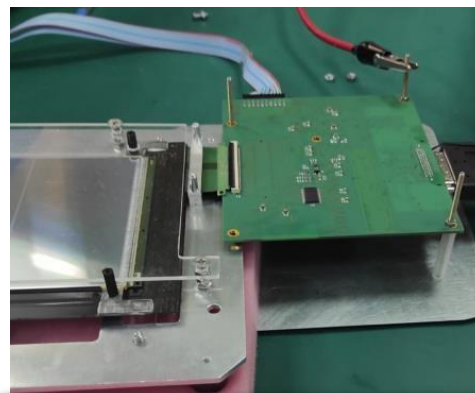


Kick-off Batch Modules

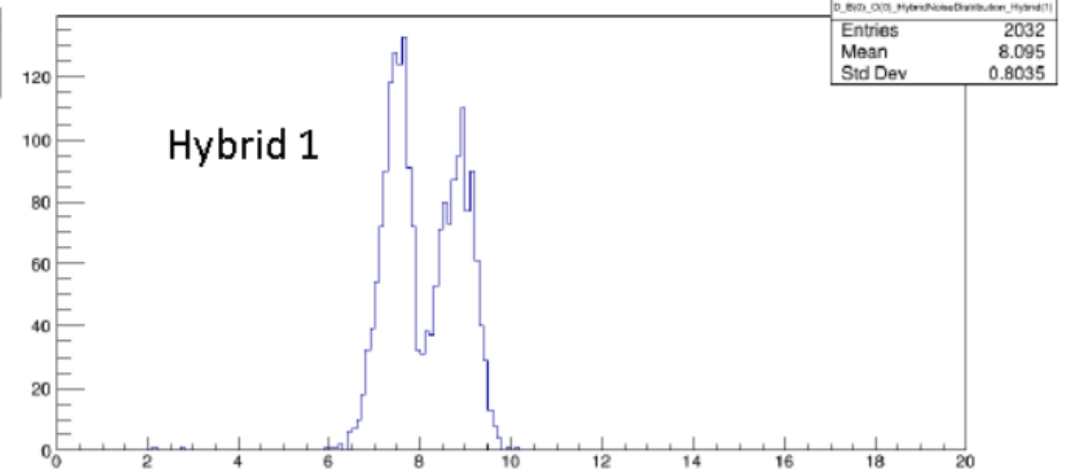
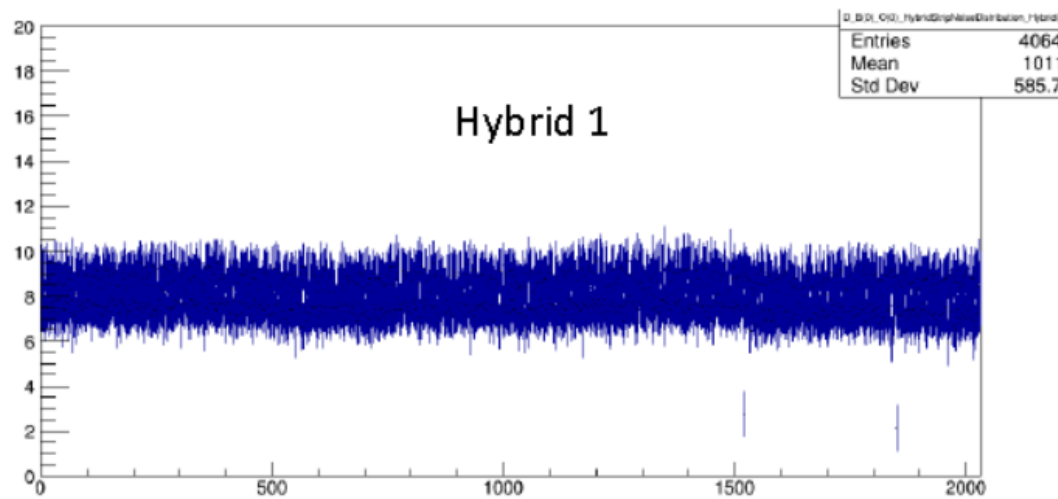
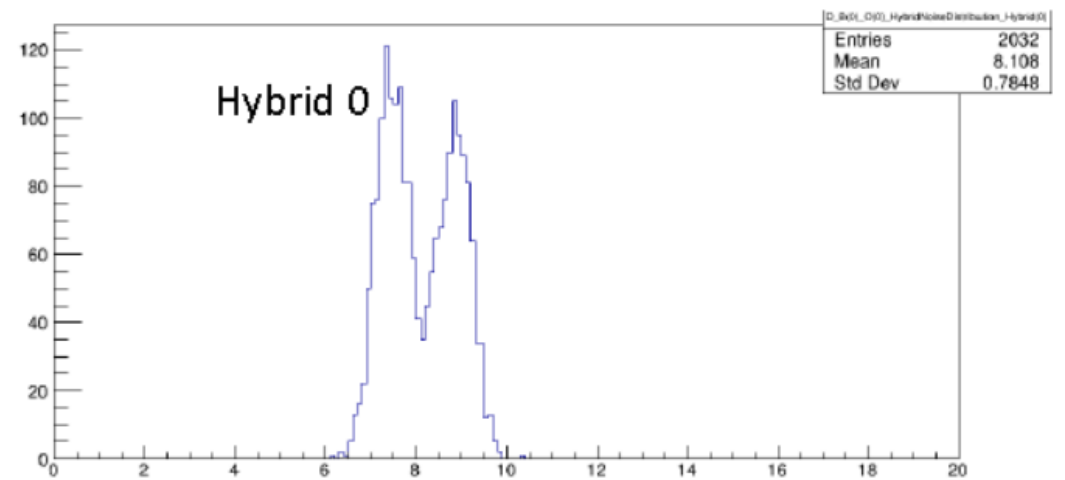
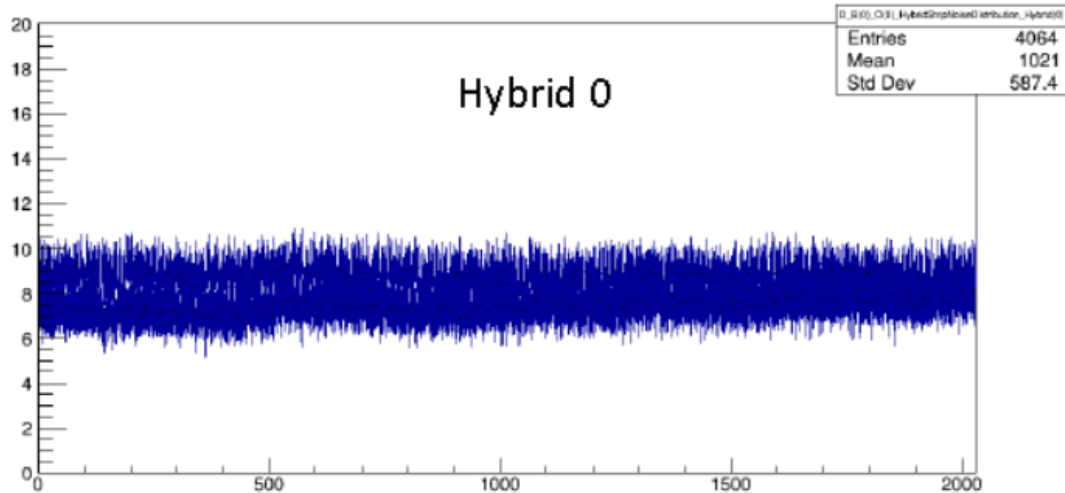
Module Test Setup – 8CBC2/CBC3/2S



- 8CBC2, 8CBC3 and 2S modules testing setups are operational
- Burn-in testing setup is operational



2S module Functionality Test @ 300V



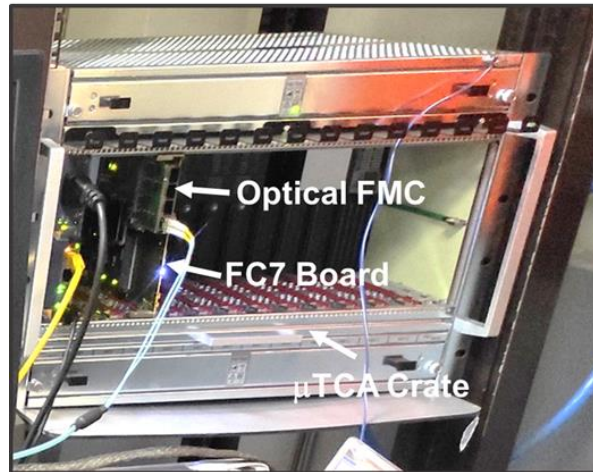
Strip no

noise

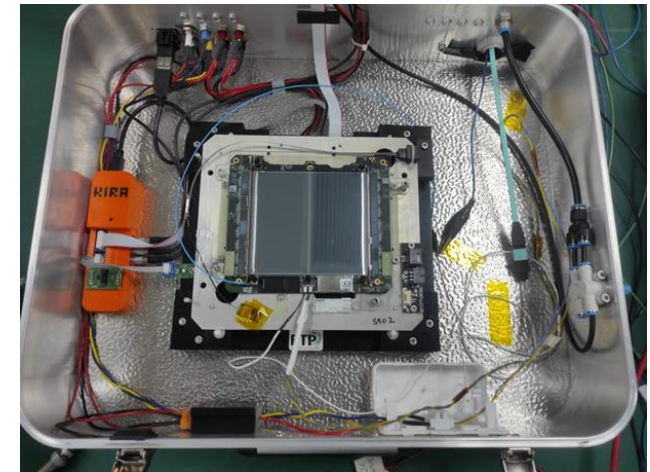
2S Module Testing Setups

❑ Noise Test Measurement Setup

- FC7 Board in μ TCA is used
- PH2_ACF algorithm developed by CMS collaboration is used for noise measurement



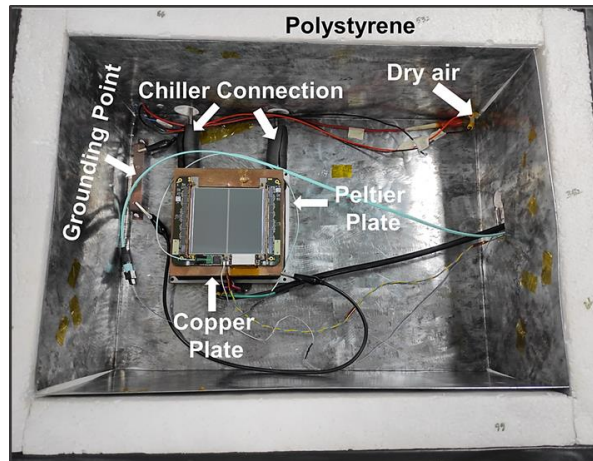
FC7 and μ TCA



Single Module test bench

❑ Cold test Setup

- Cold test box for testing single module
- Burn-in setup used to load and operate 10 modules at the same time



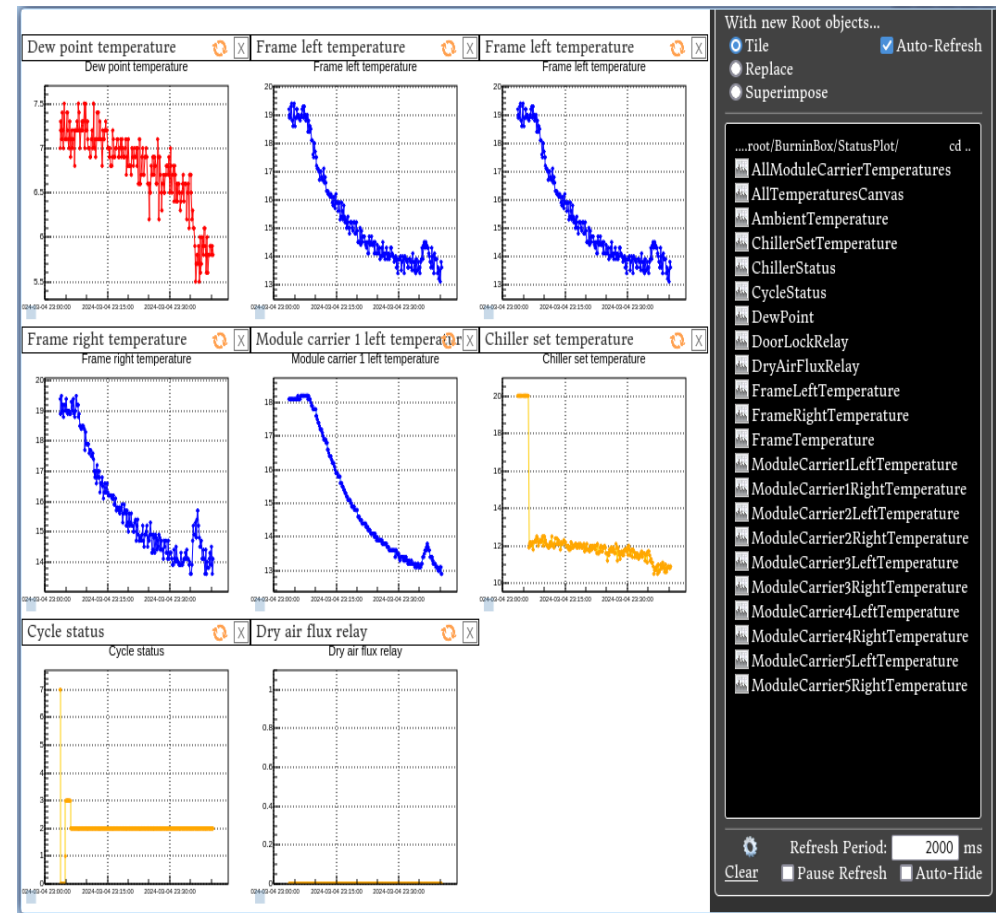
Single module cold test setup



Multi module cold test burn-in setup

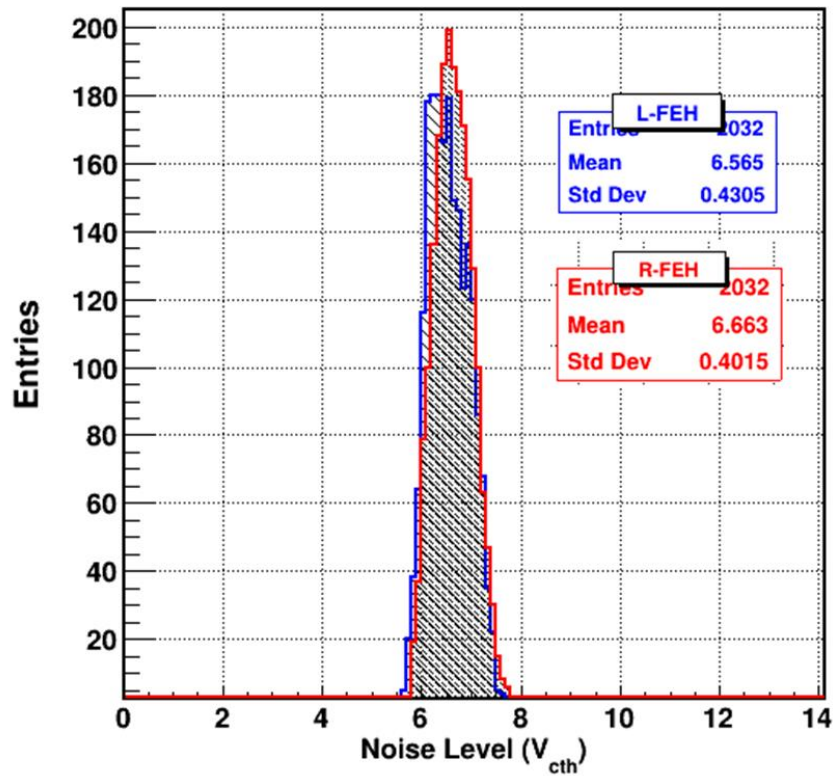
Burn-in Setup

➤ Ready for testing 10 modules in parallel

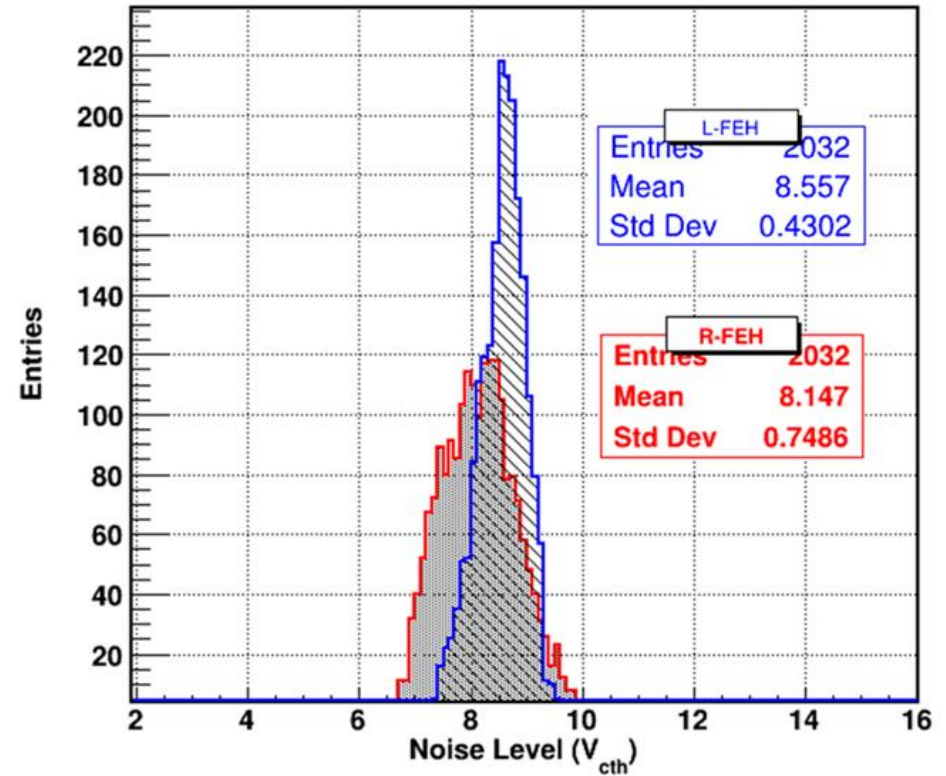


Noise Measurements

Noise Distribution After bonding 2S_18_5_NCP-00101



Noise Distribution After bonding 2S_18_5_NCP-00102



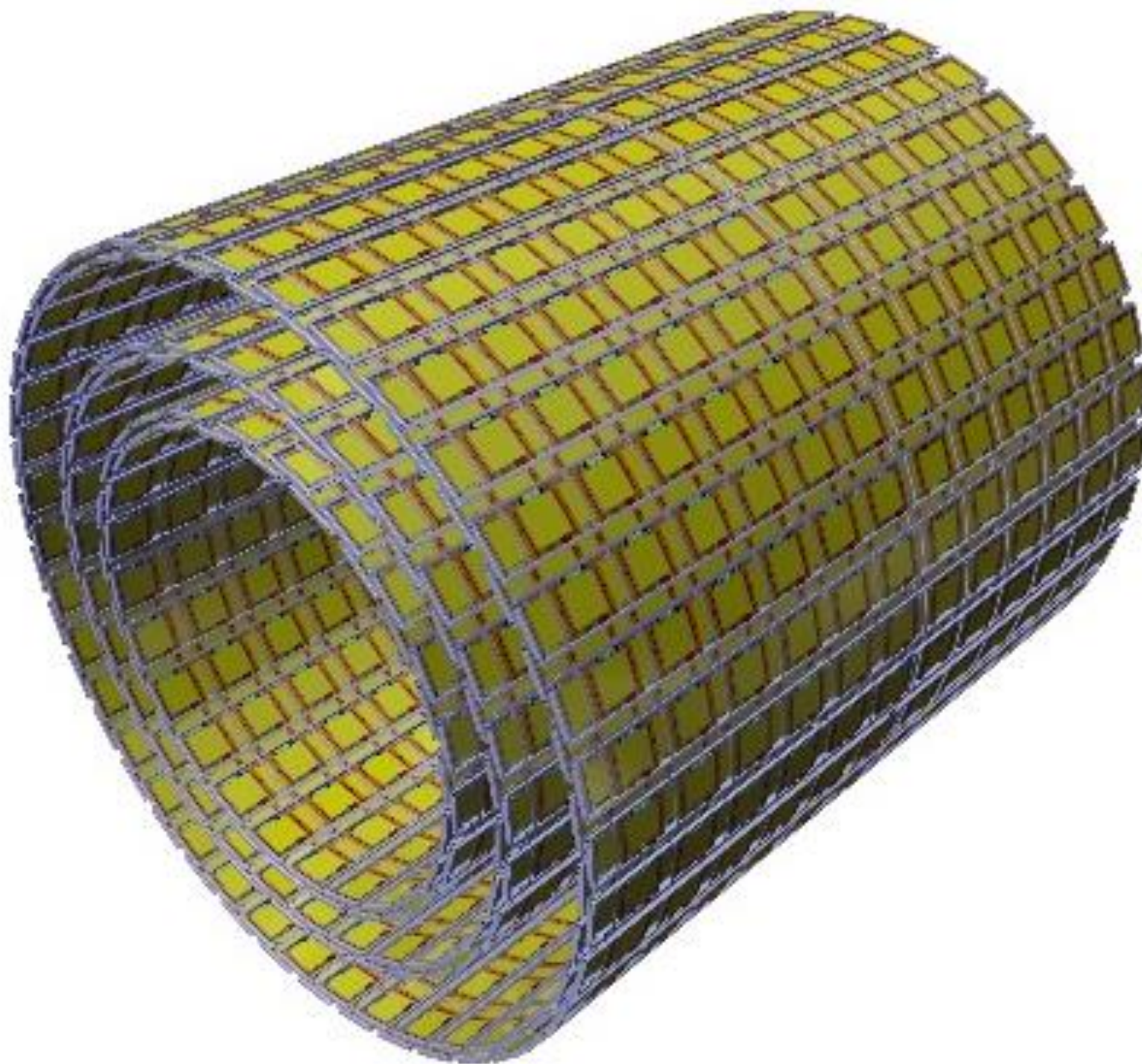
Noise Level distribution for Kick-off Batch Modules

Module Production Card Board Exercise in new Cleanroom

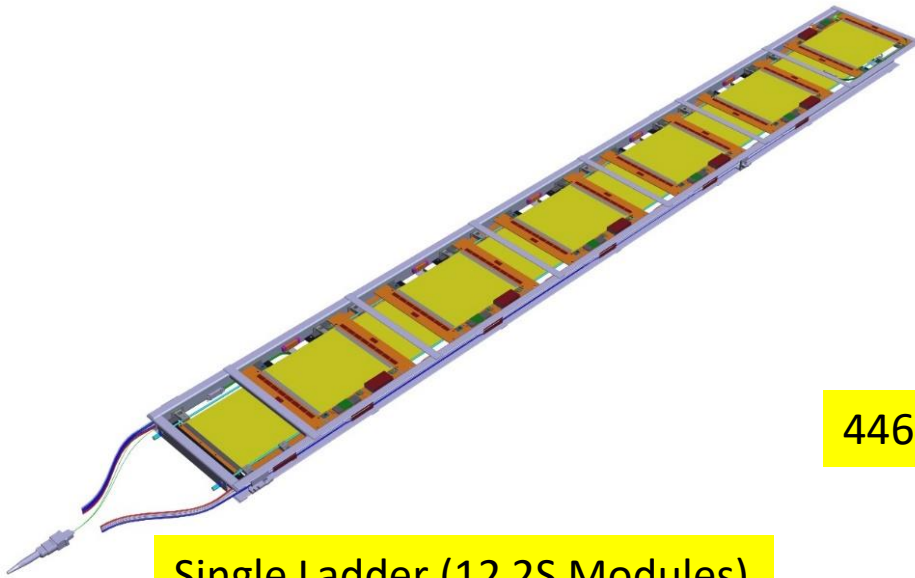


Fabrication and Assembly of TB2S Ladders

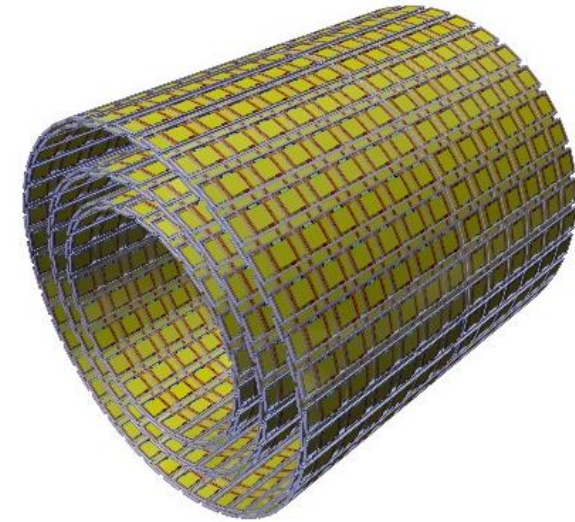
CMS Outer Tracker Barrel



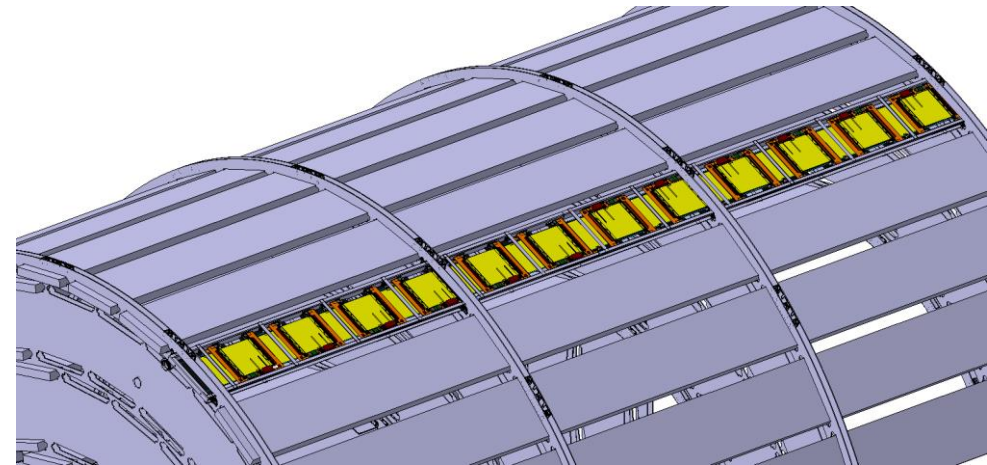
TB2S Ladder Mechanics at NCP



Single Ladder (12 2S Modules)

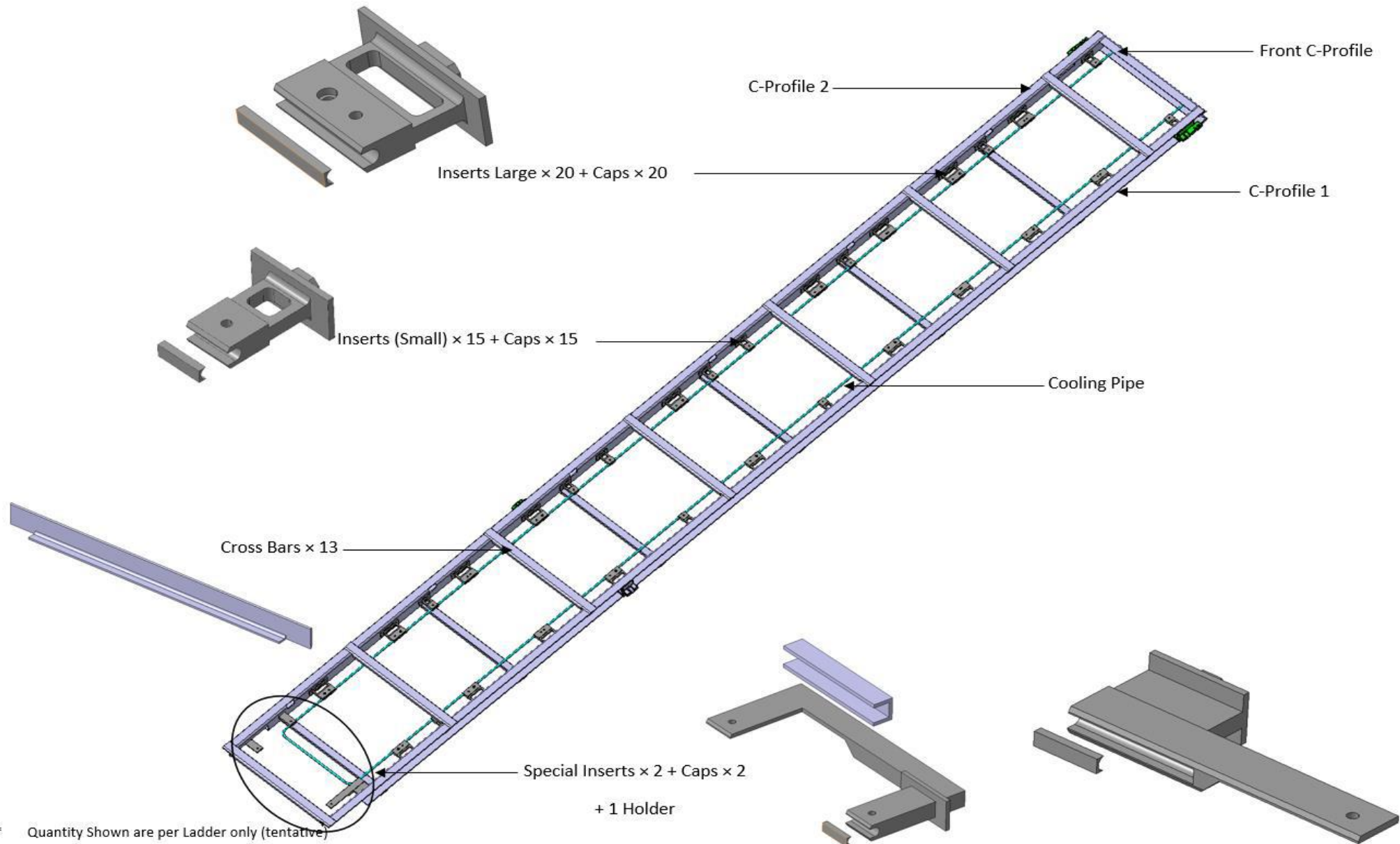


4464 2S Modules = (368 Ladders Arranged in 3 Layers)



NCP Scope of Work = build about 400 ladders including spares

TB2S Ladder Mechanics



* Quantity Shown are per Ladder only (tentative)

** All the numbers are based on the +ve side of the TB2S (The quantities may vary as the -ve side of the TB2S is still in design process)

*** Cooling pipe is a part of the ladder assembly but it is not in NCP's scope of work

Water Jet Cutting

- Different Industrial Setups were Explored
- Experienced Setups for CF cutting = 2
- R&D was done in one of the Setups;
 - ❑ Fixtures were designed to hold the Profile at 3 Locations
 - ❑ Different Cutting Pressures were tested (30 to 70 kpsi)
 - ❑ Nozzle Dia = 0.5 mm



Fixture for C-Profiles



Tracker Mechanics Project: TB2S Ladders

- Three ladder prototypes were designed, fabricated and assembled successfully at NCP
- Jigs, inserts fabricated and water jet cutting in a local company

1st Prototype Ladder – Proof of Concept sent to CERN in **April 2019**



2nd Prototype Ladder – planarity < 30 microns Sent to CERN in **August 2020**, validated and tested at CERN/Strasbourg, well appreciated!



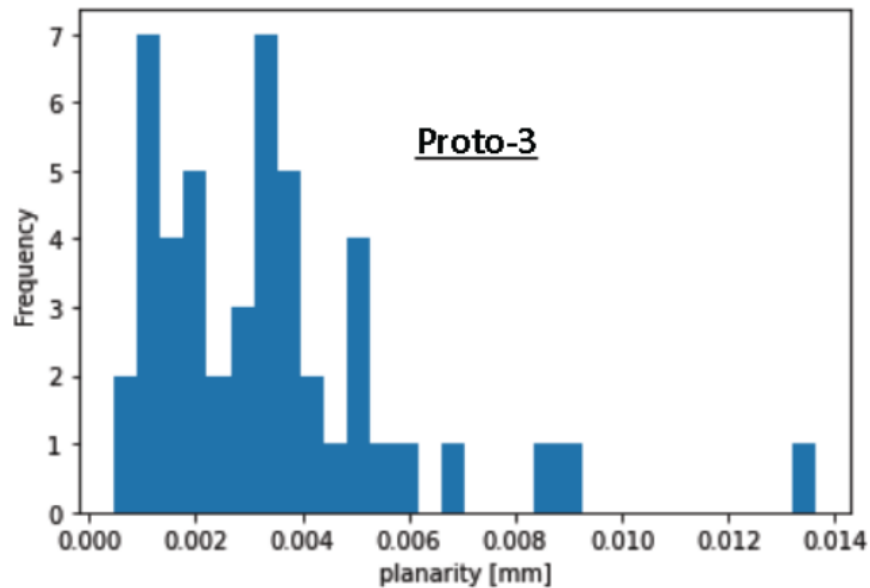
3rd Prototype Ladder – planarity < 10 microns) shipped to CERN on **14 October, 2021** Tested for performance at CERN/Strasbourg, well appreciated!



- ❑ Production of TB2S ladders will be done in local company

Metrology of 3rd and 2nd prototypes ladders at Strasbourg/France

Insert planarity

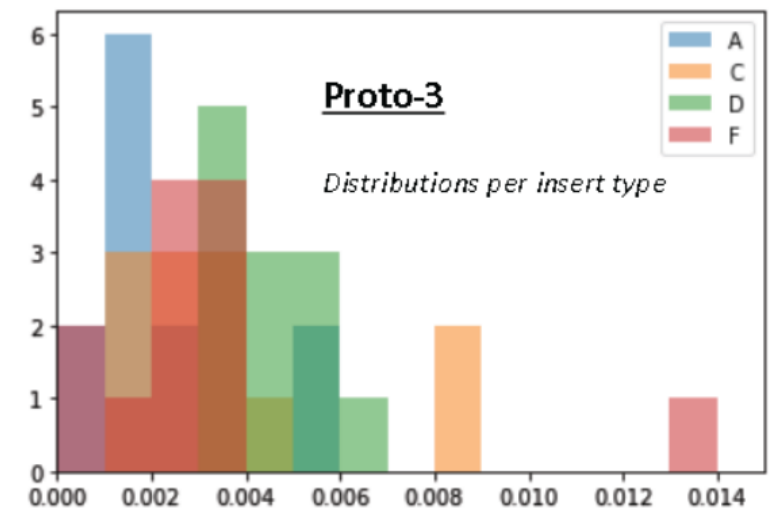
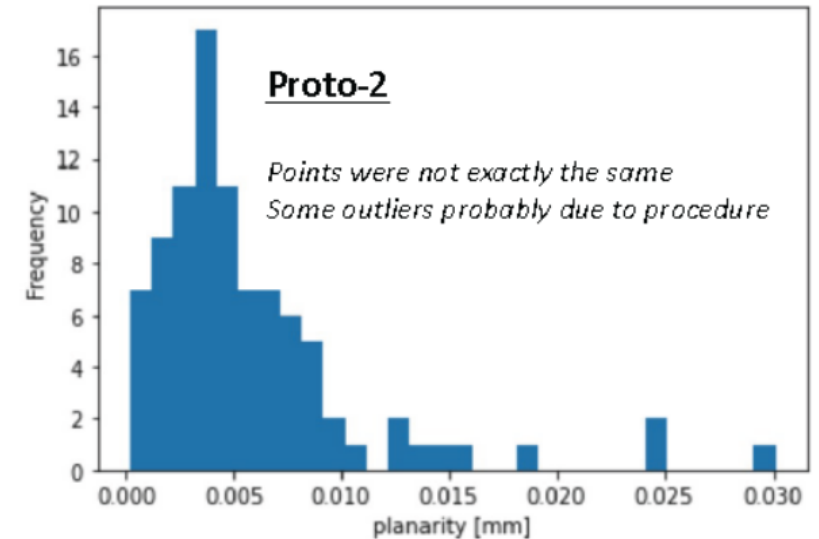


Observations:

- Measurement of the top surface, close to the hole
- Small inserts were not measured
- Mean planarity: $\sim 3.5 \mu\text{m}$
- 90% of inserts with planarity $< 5 \mu\text{m}$

Remark: CMM accuracy/repeatability of about $3.5 \mu\text{m}$

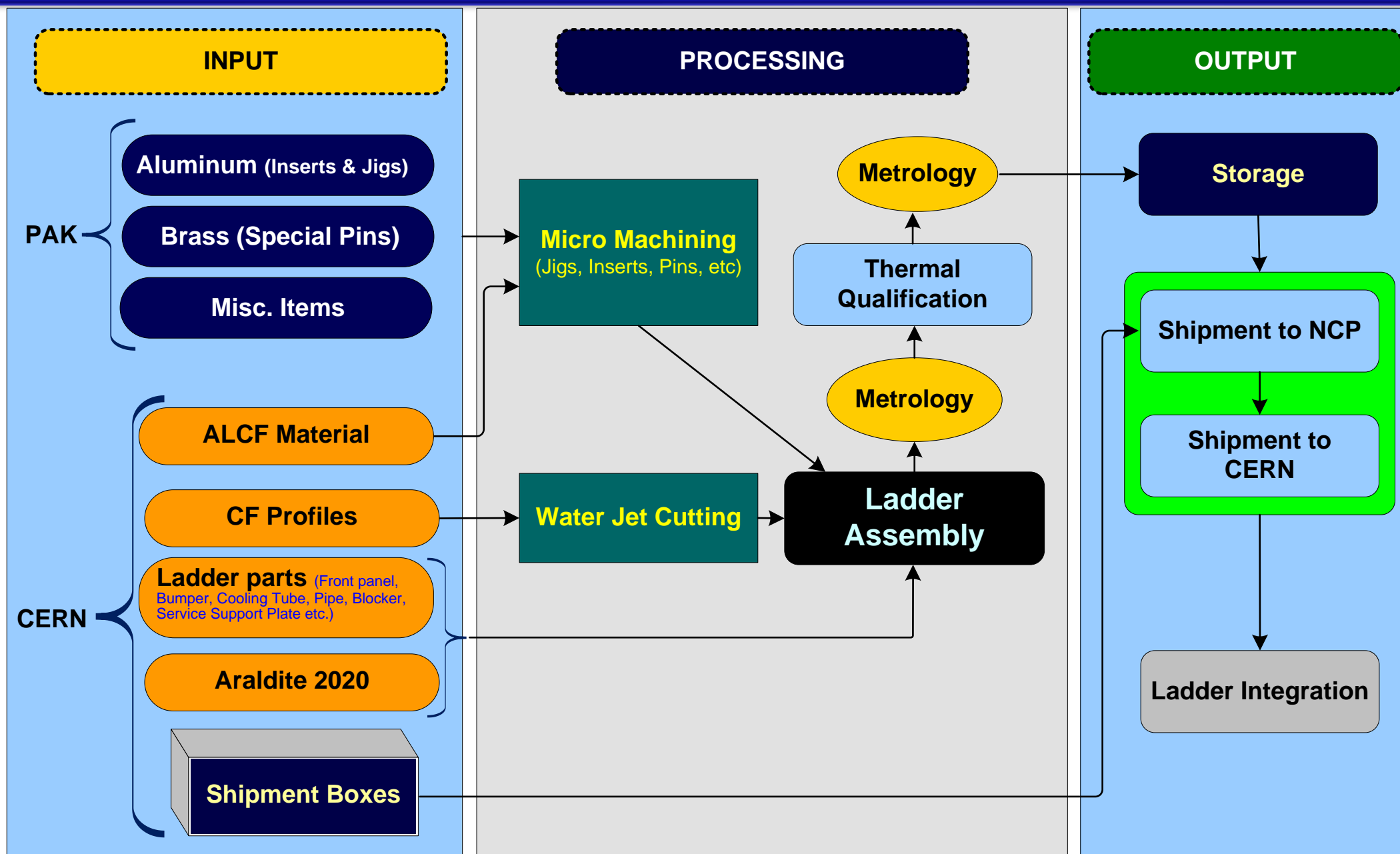
Conclusion: measurement show good planarity for the inserts



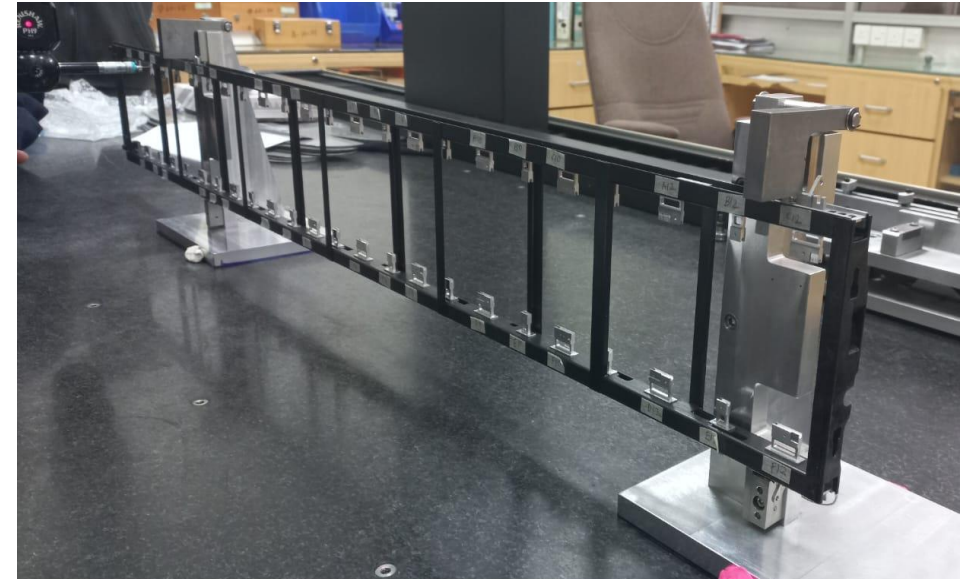
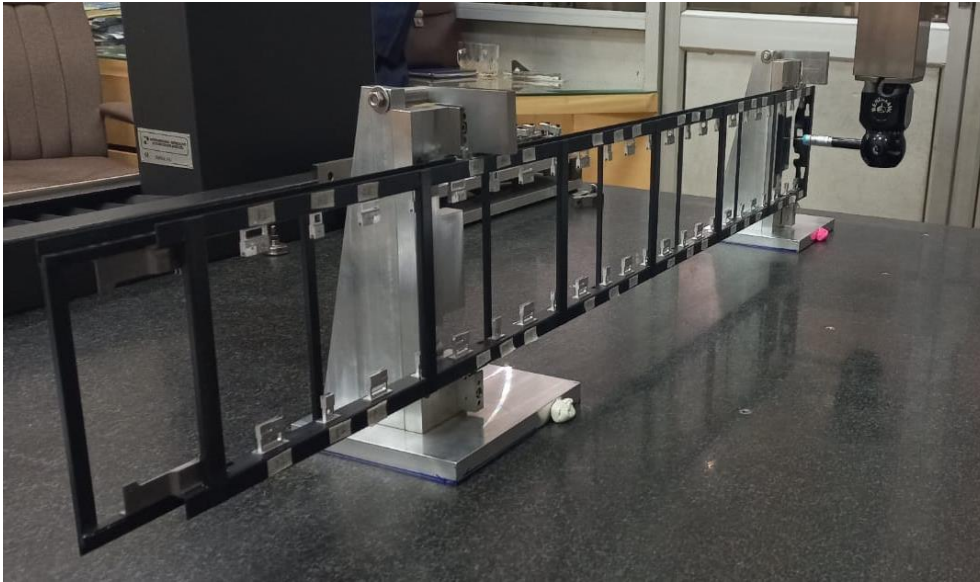
Slide from Eric Chabert, presented on 24/11/2021 at CERN

TB2S Ladders Pre-Production/Production

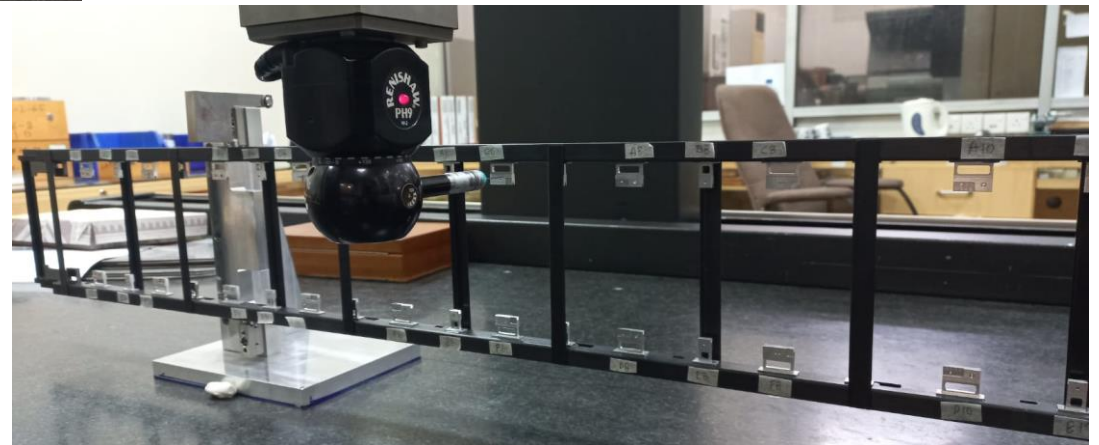
TB2S Ladders Assembly Workflow



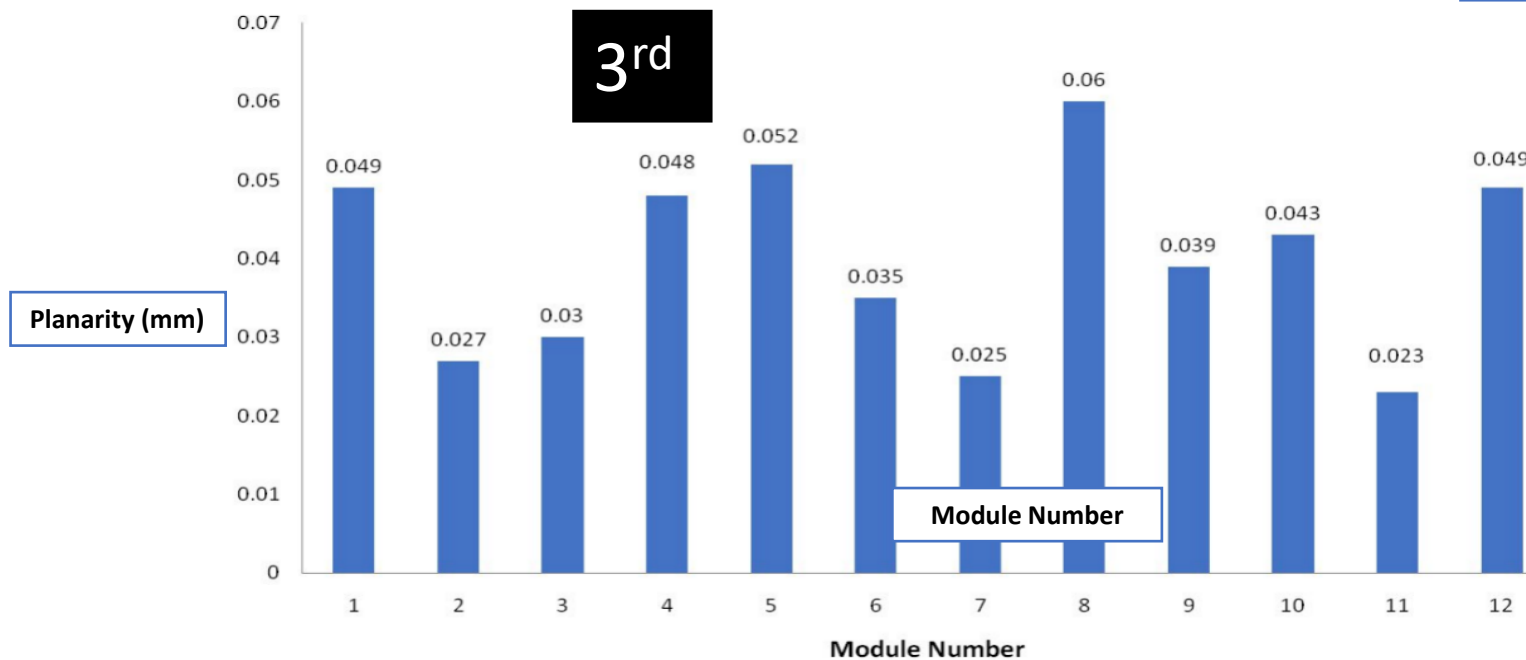
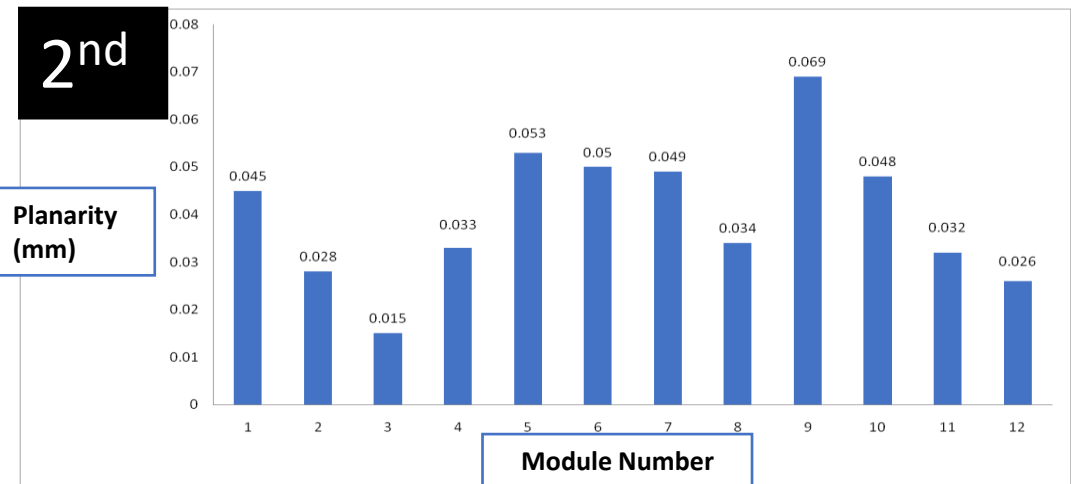
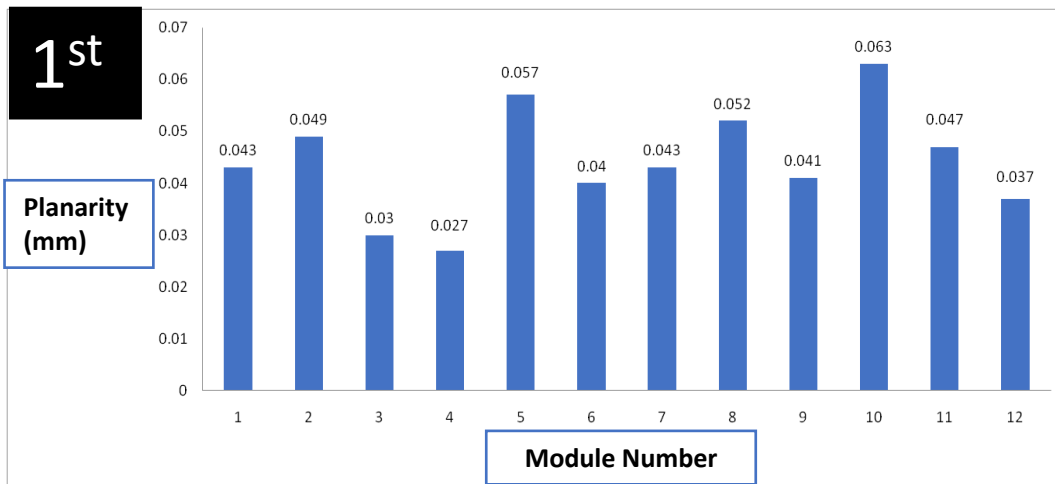
Pre-Production: Metrology at CMM (dedicated setup)



- The dedicated metrology setup is prepared
- It has already been utilized to perform metrology on the three pre-production ladders.

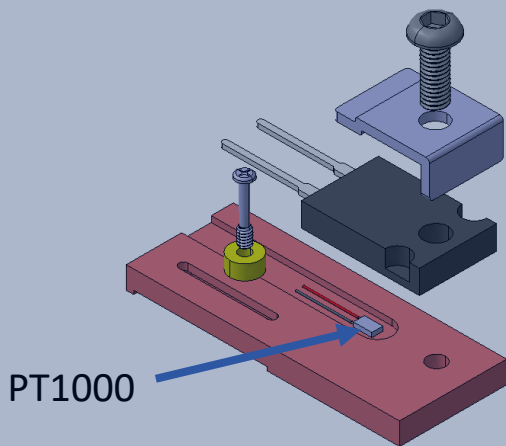
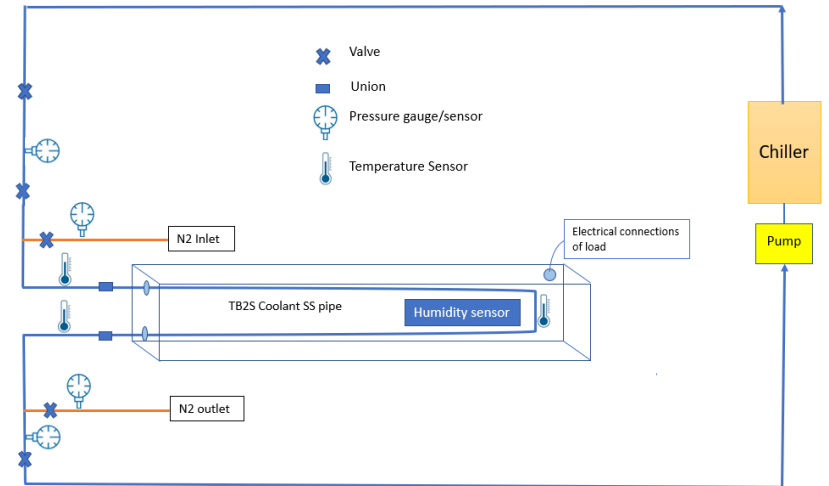


Planarity of Pre-Production Ladders

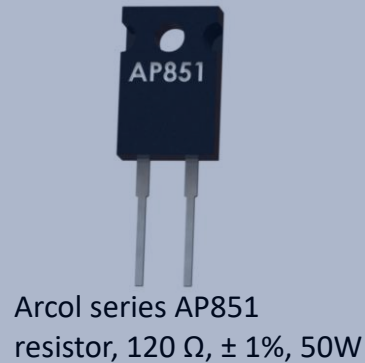


Thermal Qualification setup

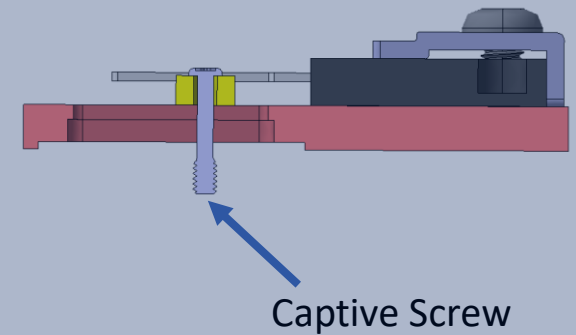
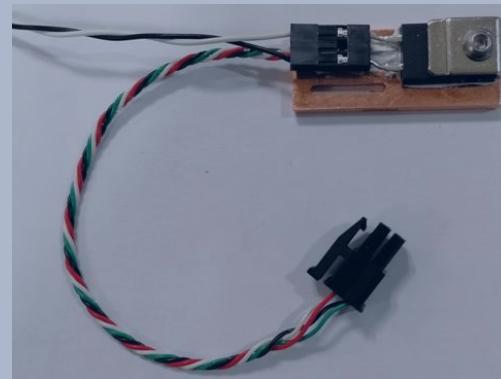
- A dedicated thermal qualification setup has been built at NCP and relocated to the company.
- A comprehensive thermal qualification procedure document has been drafted.
- To study the thermal performance of the ladder, equivalent twelve 2S modules load is applied by using heating elements



PT1000



Arcol series AP851 resistor, 120 Ω , $\pm 1\%$, 50W



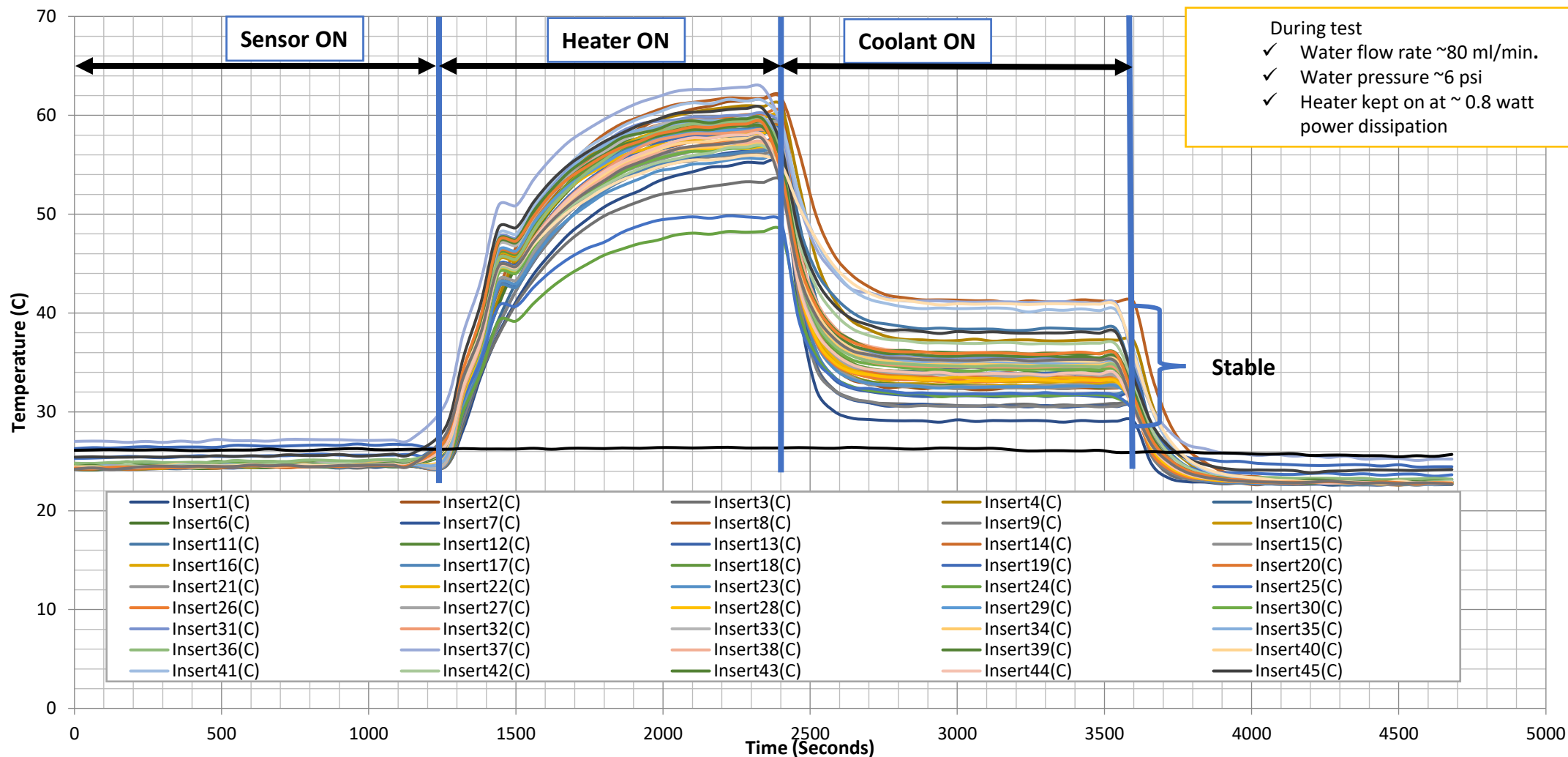
Captive Screw

Thermal Qualification of the Pre-Production Ladder

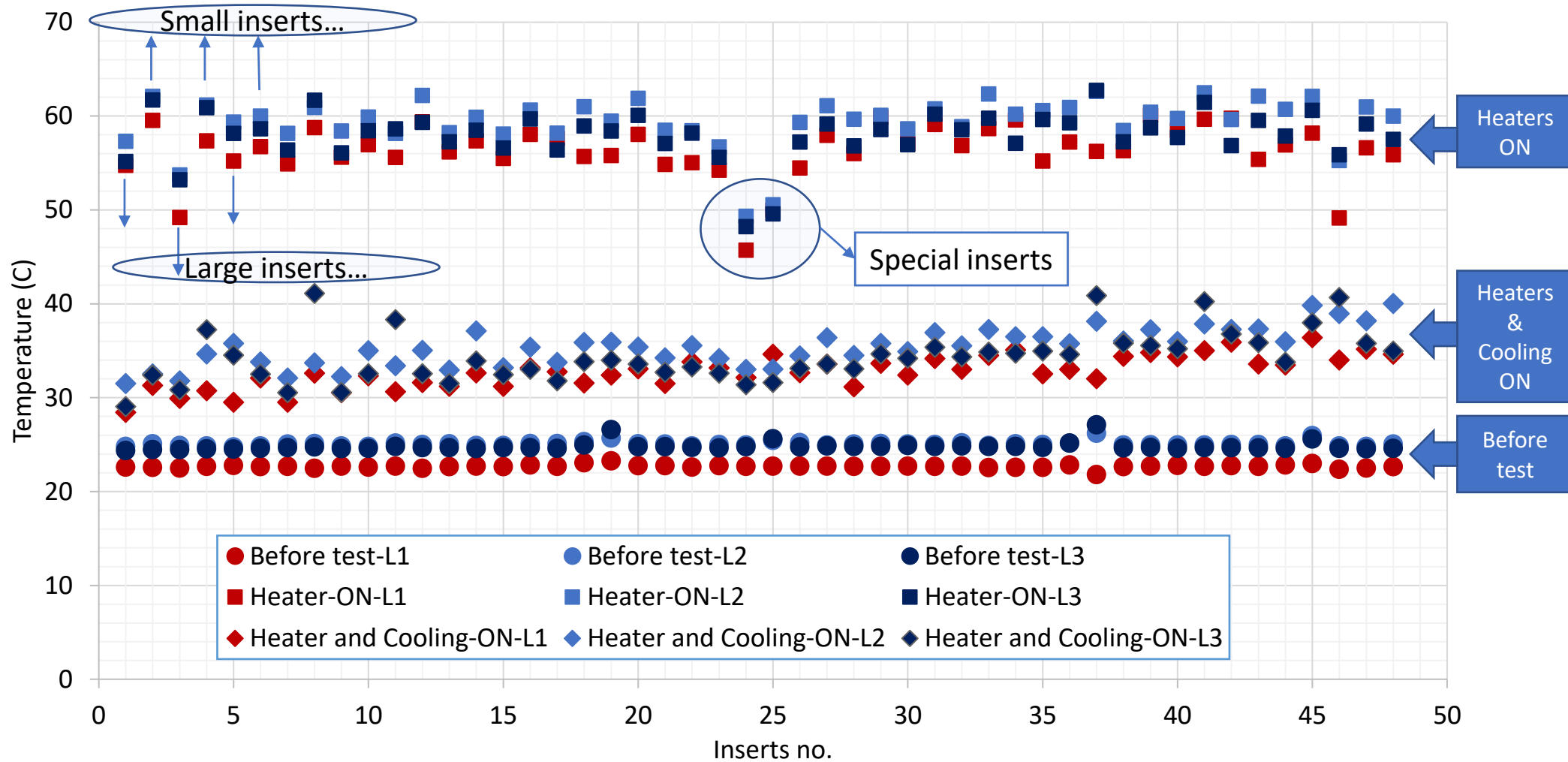
- Forty-eight heating elements installed
- Each heater dissipating approximately 0.8 Watts
- The thermal response is monitored
- Torque $\sim 6\text{cNm}$
- Three pre-production ladders qualified



Thermal QC of the 3rd Pre-Production TB2S Ladder



Thermal QC of three Pre-Production Ladders

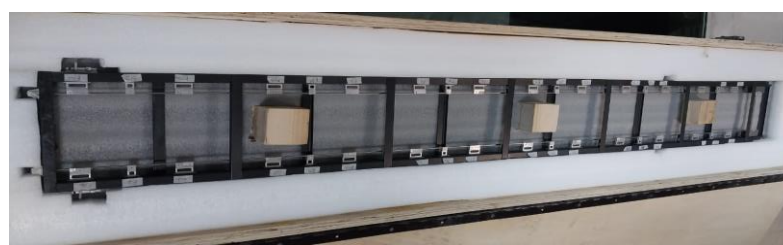


Pre-production ladders

Fourth pre-production ladder assembly is in progress with modified Jig design.



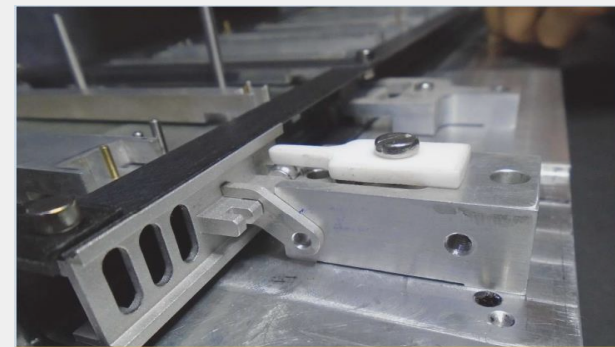
First pre-production ladder shipped to CERN on Jan. 10, 2024



2nd and 3rd pre-production ladder shipped to CERN on 16 May 2024



Support sphere Type II Fitment Trials



Support sphere Type I Fitment Trials

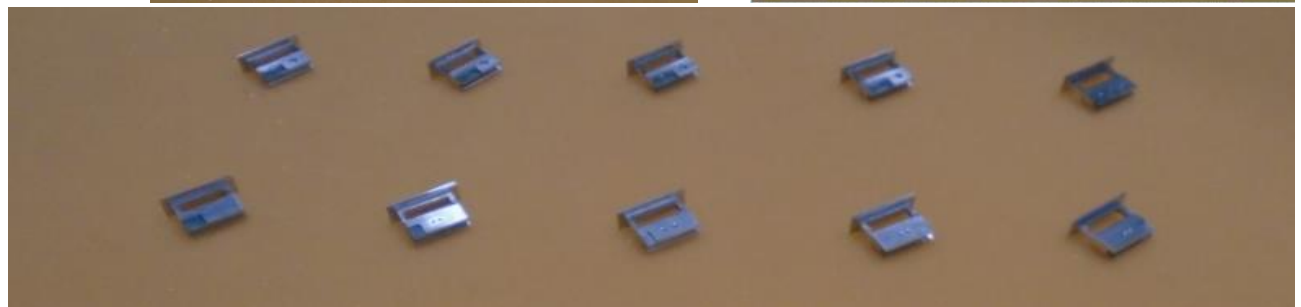
Six precision granite control tables added for assembly on Jig 1.



Inserts Manufacturing Summary

	Qty Completed	Enough for no. of ladders
Small Insert	1336	~61
Special Insert	97	~49
Large Insert Z-ve	1635	~68

Design for Z+ ladders is being finalized at CERN



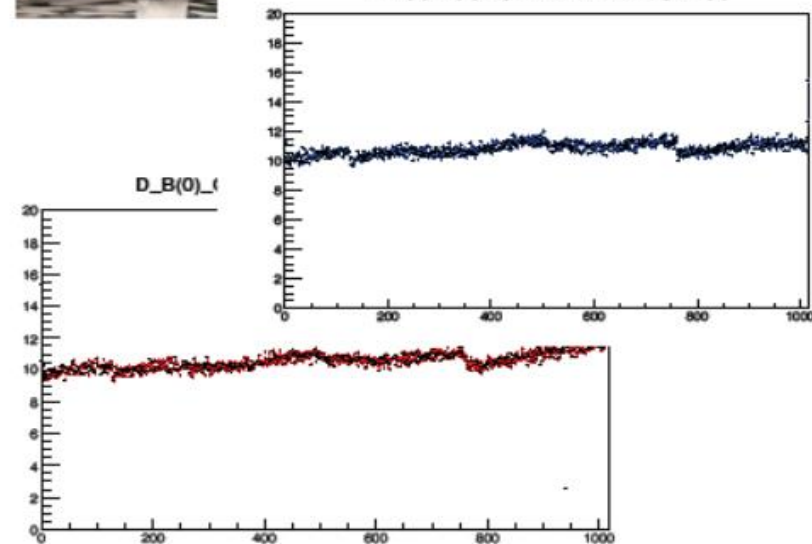
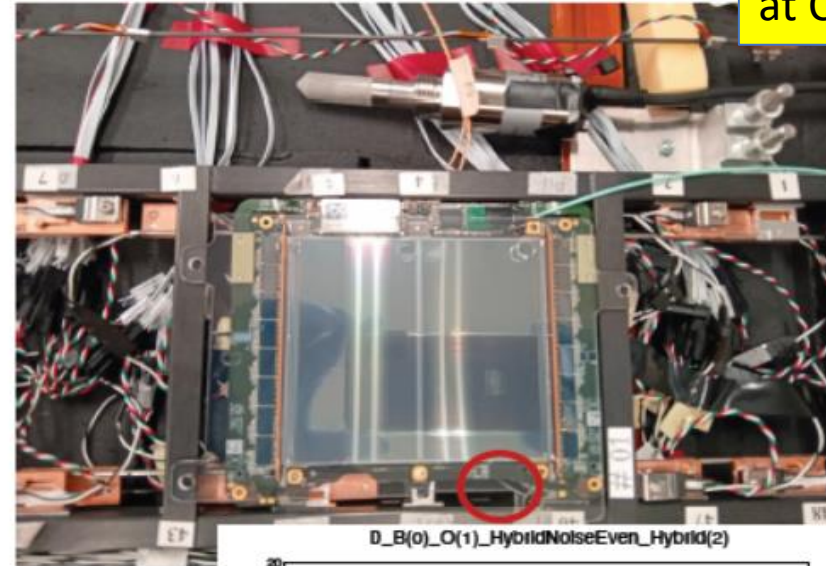
Cold Test of 1st Pre-production Ladder at CERN



Test with 2S_18_5_NCP-00102

NCP module on NCP Ladder at CERN

- Ground balancer not connected.
- Module tests :
 - At room temperature in the single test box and on the ladder,
 - on the ladder, without screwing => verify the module works in cold,
 - On the ladder with screws at nominal torque 10cNm.
- During the test :
 - Pedennoise taken at about 15°C, 0°C, -15°C, -20°C, -25°C, -30°C, -35°C,
 - One wire bond connection a bit loose FIXME chip+strip numbers, working and not working a bit randomly,
 - One wire bond stopped to work at some point.
- After the test and the module is removed from the ladder, and removing the electrical pigtail => service hybrid mechanically disconnected.
 - not glued in the first place,
 - Should we glue for the full ladder test ?



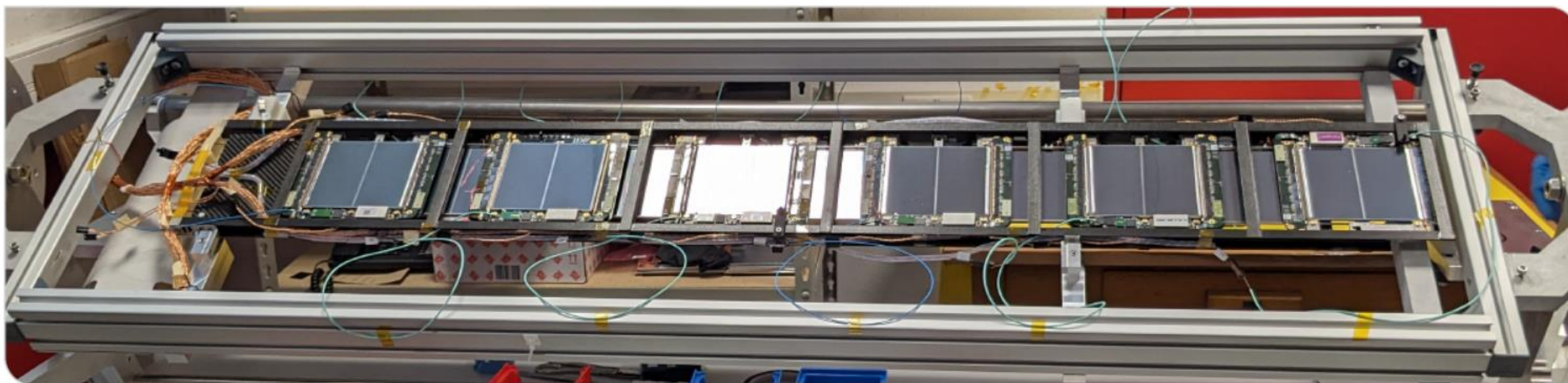
Slide from Jeremy Andrea

Cold test of Ladder with 12 2S Modules (first test!)



Preparation of TB2S Ladder Cold Test at CERN

Mohsin Abbas (CERN), Jeremy Andrea (IPHC), Irfan Asghar (NCP), Pier Filippo Cianchetta (CERN), Laurent Gross (IPHC), Clément Hass (IPHC), **Lea Stockmeier** (KIT), Cristiano Turrioni (Perugia), Giovanni Zevi Della Porta (CERN), | June 13, 2024



KIT – The Research University in the Helmholtz Association

www.kit.edu

Silicon detector lab development

GEM QC Setup in 2018



Well-equipped Semiconductor detectors Lab in
2023!
And well trained person power!

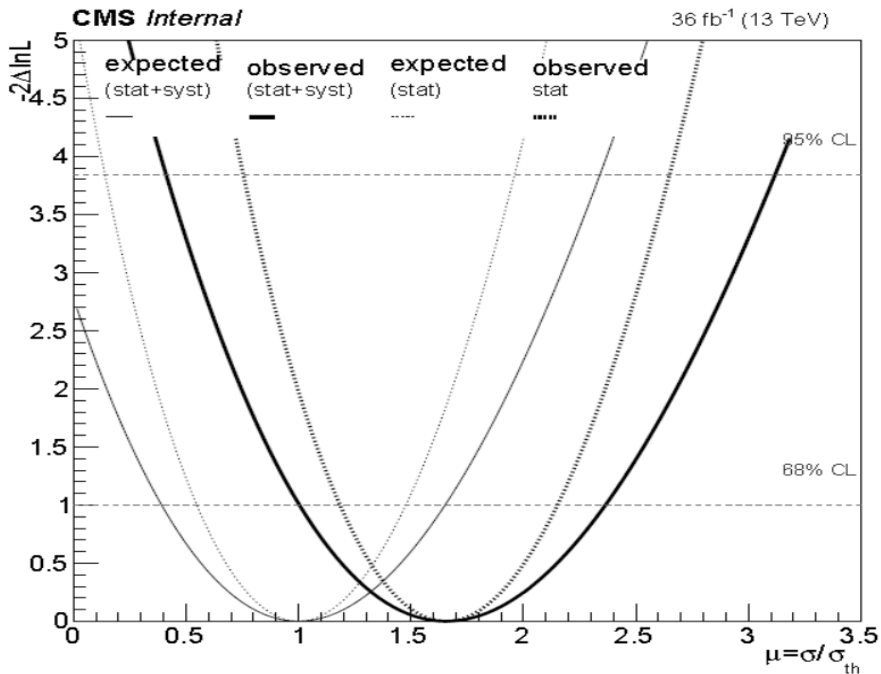


Physics Projects: Some Physics Analysis Projects Finished at NCP

- The cross section measurement of top quark in association with Z boson (Measured for the first time in any HEP experiment)
 - ❑ Analysis Note: CMS/AN-14-182 and CMS/Top-12-039 (published in JHEP, arxiv.org/abs/1702.01404)
 - ❑ Analysis at 13 TeV, Note: CMS/AN-16-285, CMS/Top-16-020 (published in PLB)
- Measurement of $t\bar{t}b\bar{r}$ cross-section in $l+jets$ channel at 13 TeV
 - ❑ Documented in CMS Paper: Top-16-006
- Search for Microscopic Black Holes with the Early Run 2 CMS Data
 - ❑ Documented in CMS Paper: EXO-15-007
- Measurement of CKM matrix elements in single top quark t-channel production in proton-proton collisions at $\sqrt{s} = 13$ TeV
- Measurement of the single top quark and antiquark production cross sections in the t-channel and their ratio in proton-proton collisions at $\sqrt{s} = 13$ TeV
- Measurement of the inclusive single top t-channel cross section at 13 TeV (2016 data) CMS-TOP-17-001

tqZ Results @ 13 TeV

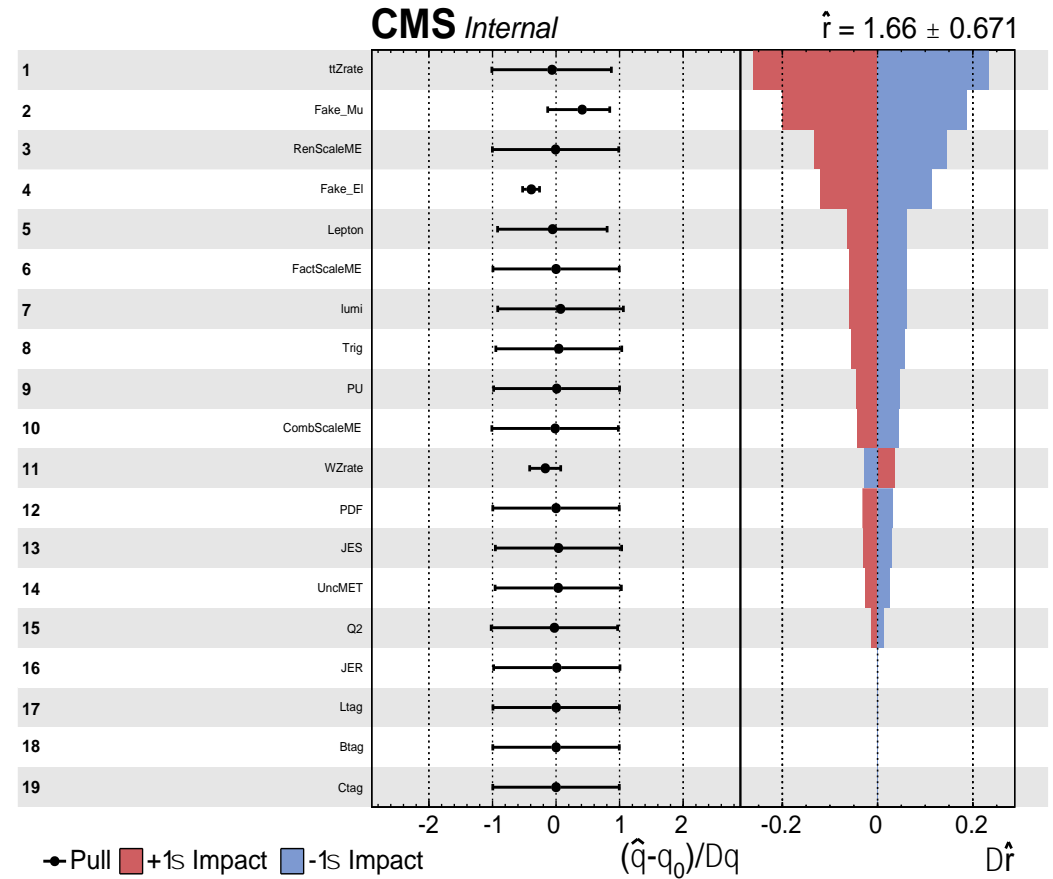
Signal Strength Calculated by simultaneously. Fitting tZq and ttZ region



Expected Signal Strength : $1.66^{+0.66}_{-0.60}$

Expected Significance : $1.95 \pm 0.09 \sigma$

Observed Significance : 2.81σ



$$\sigma_{tZq}(measured) = 156^{+47}_{-42}(stat)^{+40}_{-34}(syst) fb$$

First measurement of tqZ!

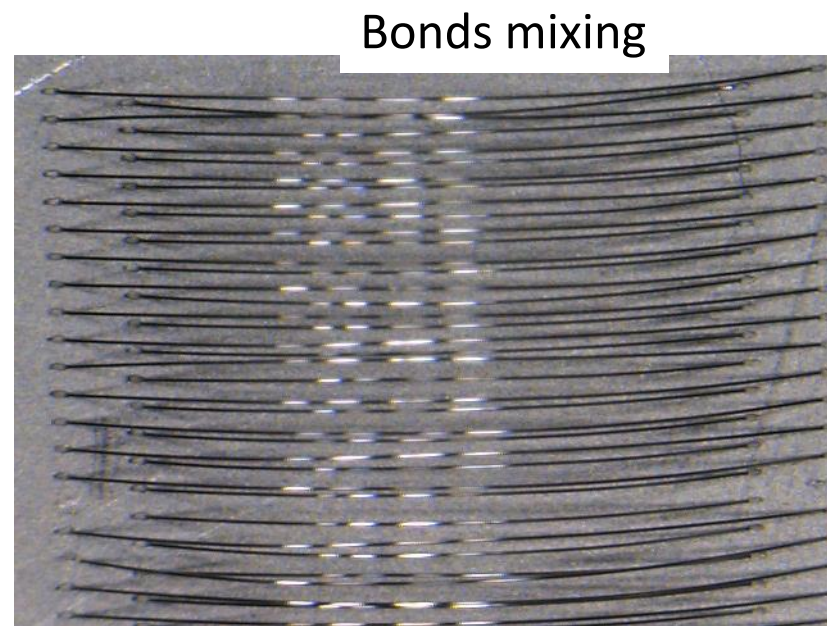
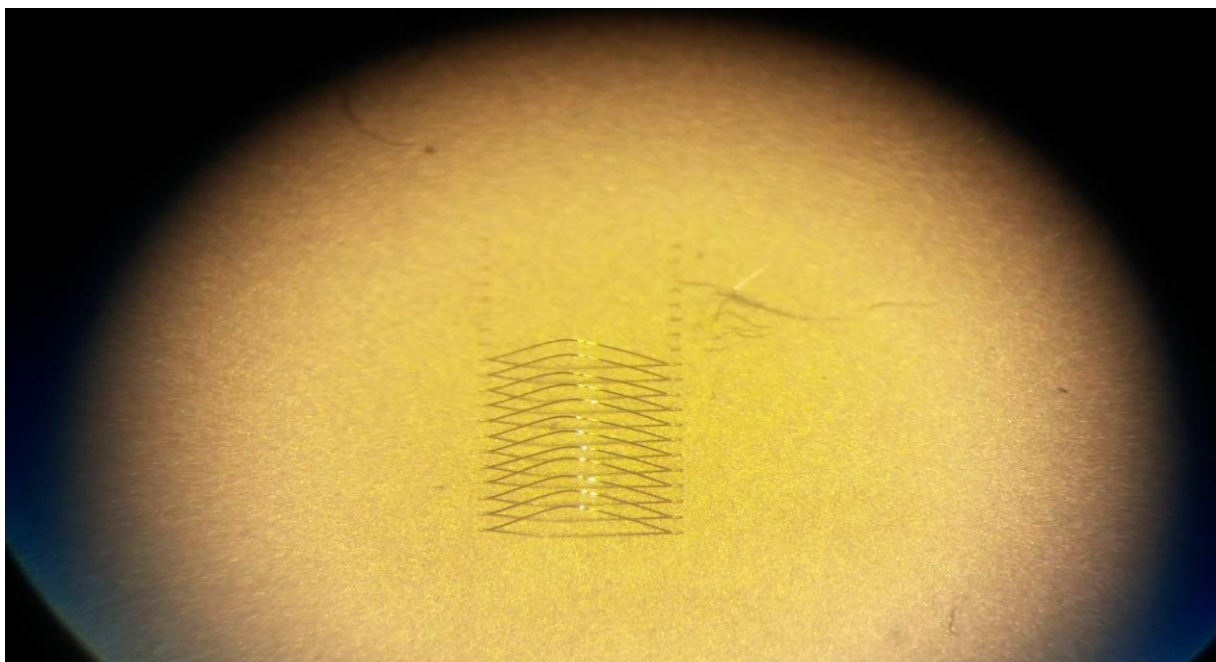
Feasibility studies of further rare top processes are in progress.

Summary

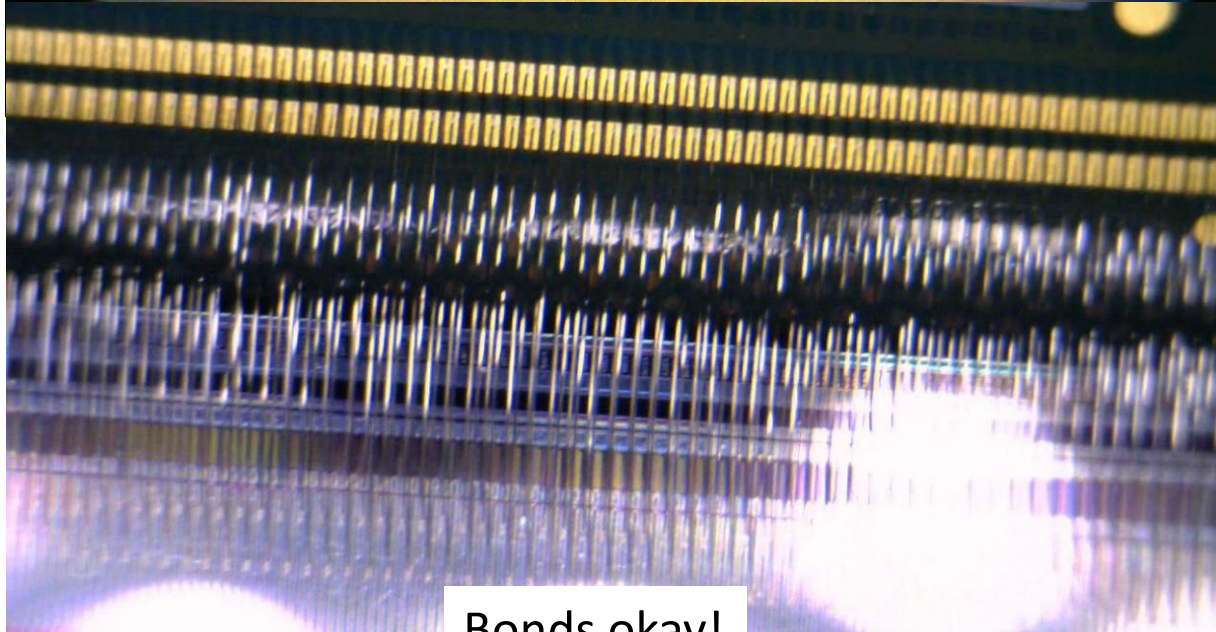
- The three main Phase-2 upgrade projects are progress well
 1. SQC status: The last batches of Silicon sensor qualification are being tested. The project is going to finish this month
 2. Module Production: Ready for production, kickoff modules assembled and tested. One kickoff module is at CERN now. Production will commence as soon as module components arrives.
 3. Ladder production: In progress in a local company
 4. GEM (GE1/1) project successfully finished

Thank You!

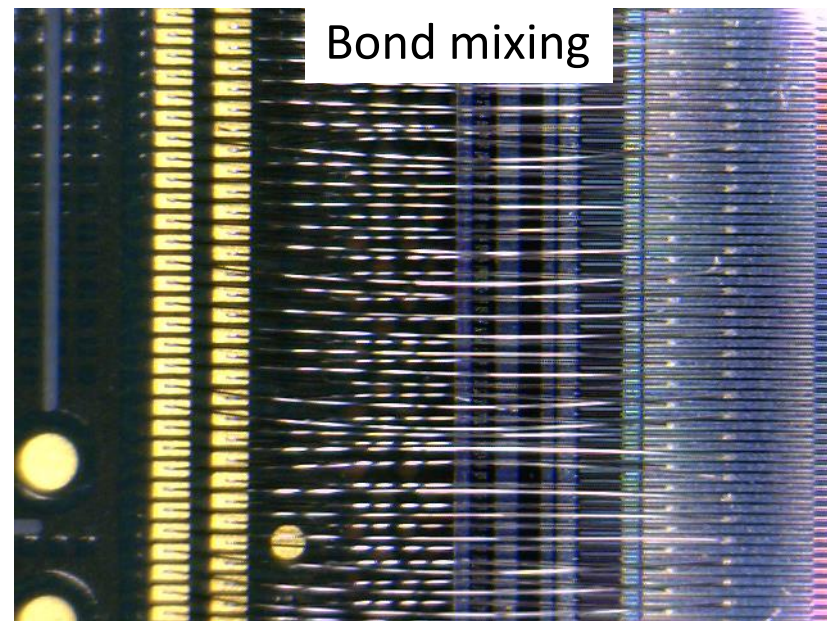
Some wire bonds silicon and hybrid!



Bonds mixing



Bonds okay!



Bond mixing

Outer Tracker R-Z view

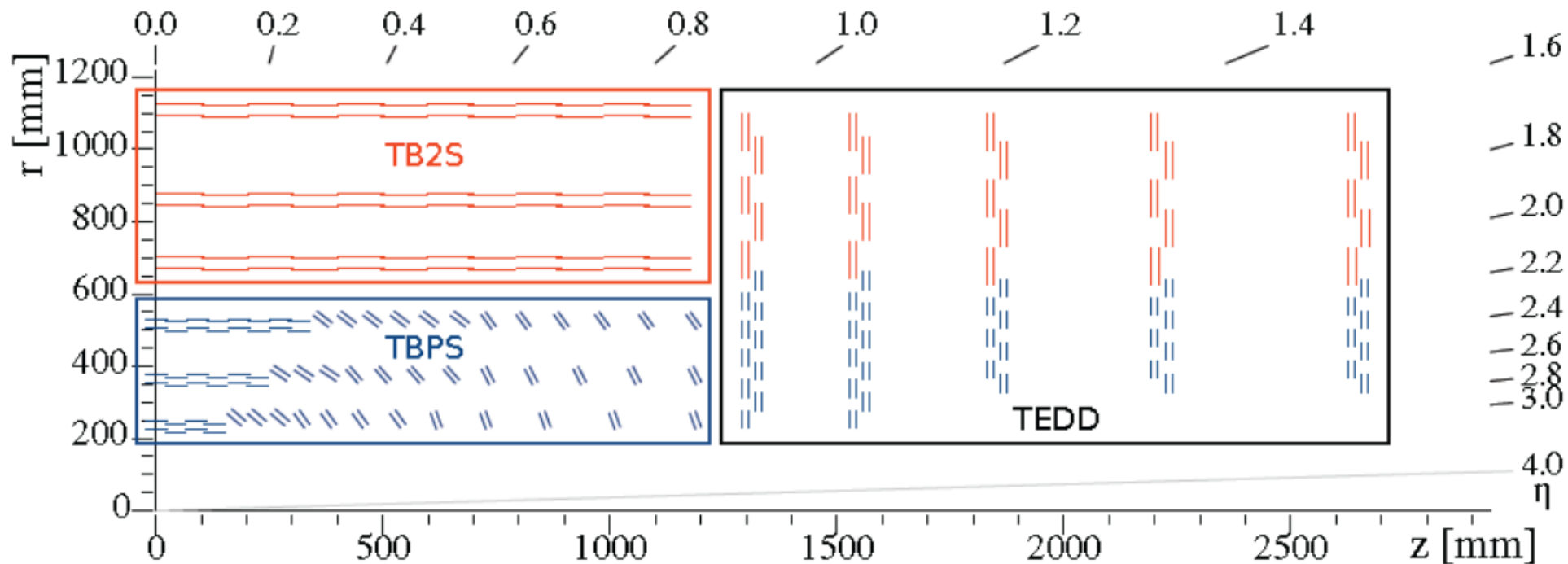
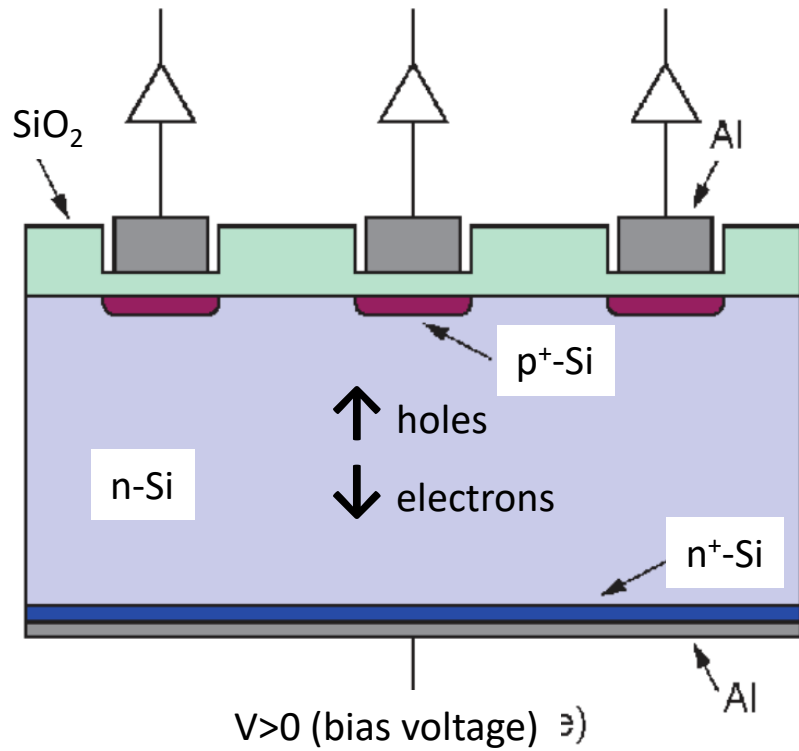
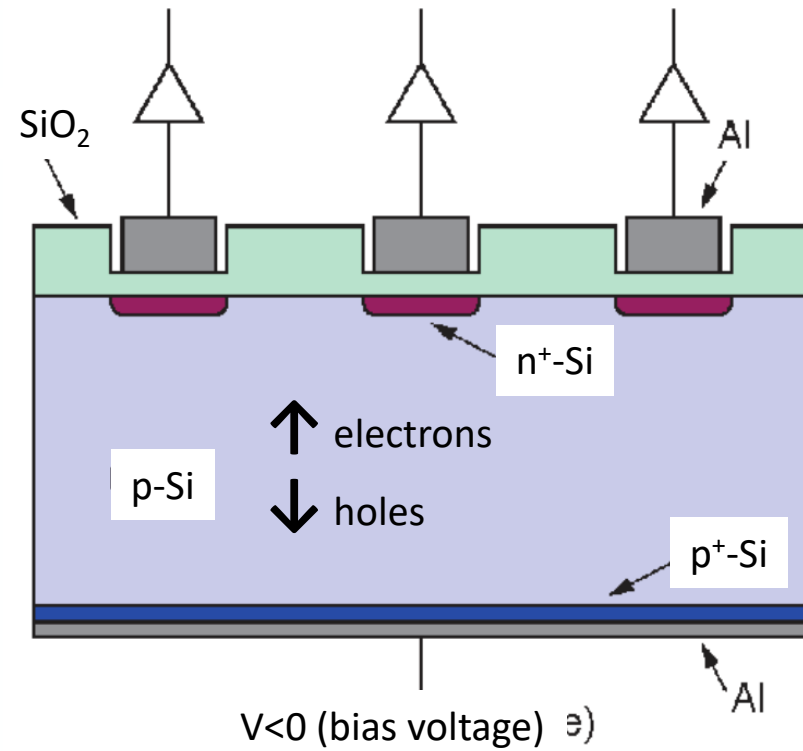


Figure 3.1: Sketch of one quarter of the Outer Tracker in r - z view. Blue (red) lines represent PS (2S) modules. The three sub-detectors, named TBPS, TB2S, and TEDD, are indicated. All overlapping layers are shown separately, while in Fig. 2.3 the mean positions are shown.

Other designs



p-in-n, AC coupled



n-in-p sensors

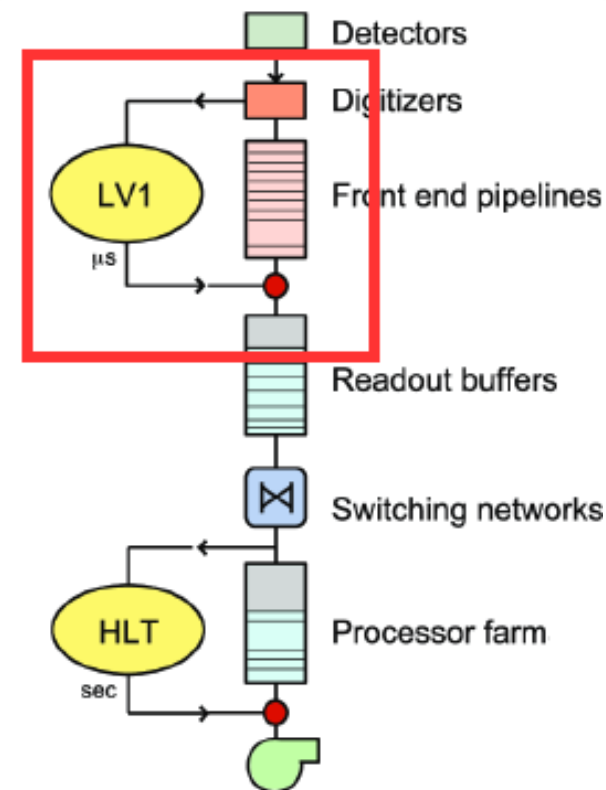
Two Level Trigger System

➤ Level-1 Trigger (L1T)

- ❑ Hardware-based Trigger
- ❑ Uses low-res detector information from calorimeter and muon
- ❑ No tracker in the trigger decision

➤ Data stored in on-detector buffers

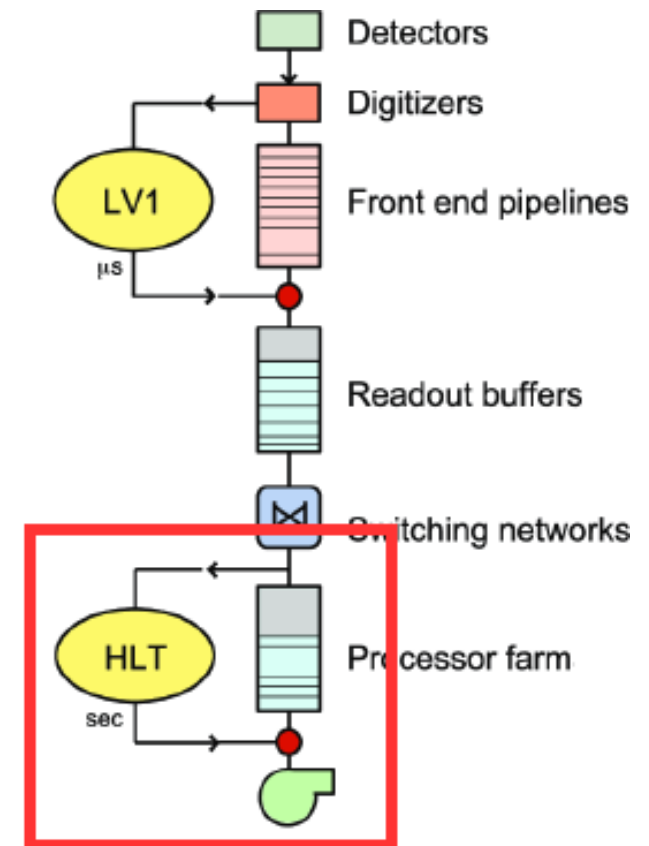
- ❑ 3.8 μs to take a decision
- ❑ Limited by tracker buffer size



➤ Data bandwidth reduced from 40 MHz (as delivered by detector) to 100 kHz (~ 100 GB/s)

High-Level Trigger (HLT)

- Dedicated Computer farm with ~ 26000 cores
 - ❑ Using full-detector information
 - ❑ Two-stage event selection
 - ❖ Only calorimeter, ~ 50 ms
 - ❖ Full-detector, w/ tracking & PF, ~ 1 sec
- Data rate is reduced from 100 kHz \rightarrow 1kHz
 - ❑ ~ 1 GB/sec, which is stored on disk
- Plan to use tracker at LVL1 in HL-LHC
 - ❑ Improved resolution, identification, pile-up rejection
 - ❑ Max rate 100 \rightarrow 750 kHz
 - ❑ Latency 3.8 \rightarrow 12.5 μ s
- HLT
 - ❑ Output rate 1 kHz \rightarrow 7.5 kHz
 - ❑ Even higher computing power would be needed



Sensors to qualify for the CMS phase-II upgrade project

Type	Outer		Active		Strip/Pixel Cell		Quantity needed
	width	length	width	length	pitch	length	
2S	94 183	102 700	91 488	100 703	90	50 260	15 216
PS-s	98 140	49 160	96 055	47 163	100	23 479	5 592
PS-p	98 740	49 160	96 055	47 163	100	1 467	5 592

At NCP SQC site- 2S sensors

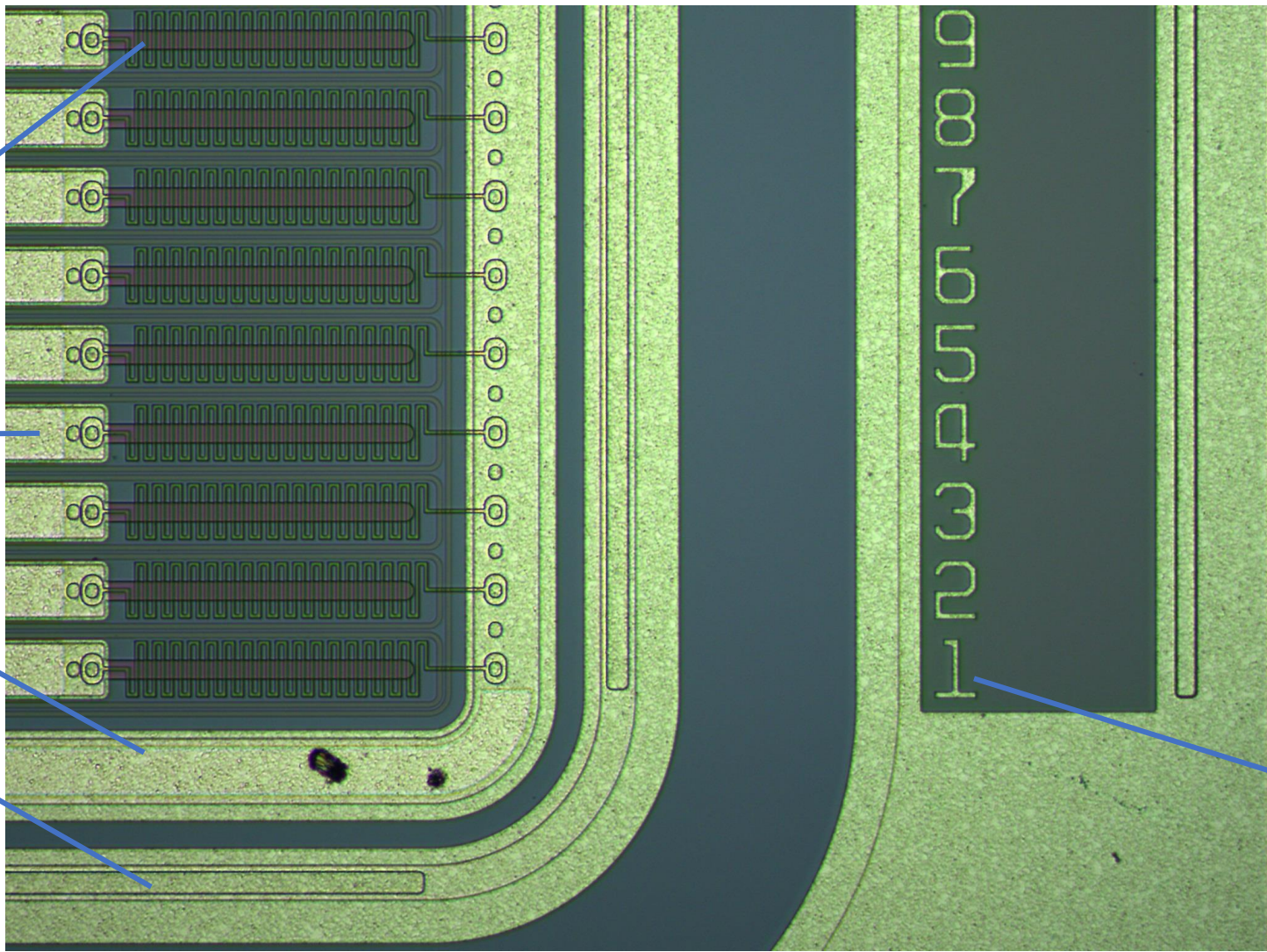
The 2S and PS-s strip sensors share a common design of the periphery (bias, guard and edge ring) and also the active strip area is identical with exception of the strip pitch and length

Polysilicon resistor

DC pads

Bias ring

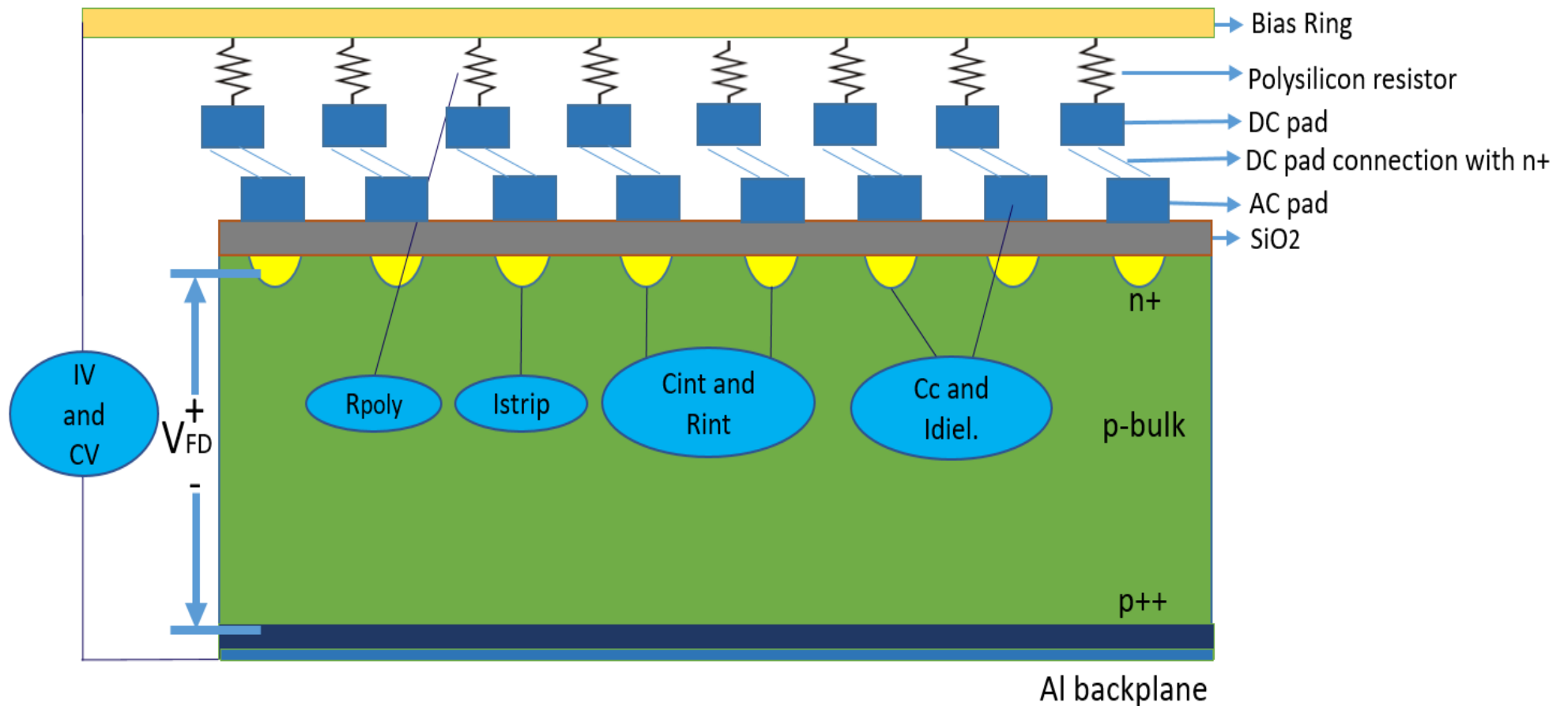
Guard ring



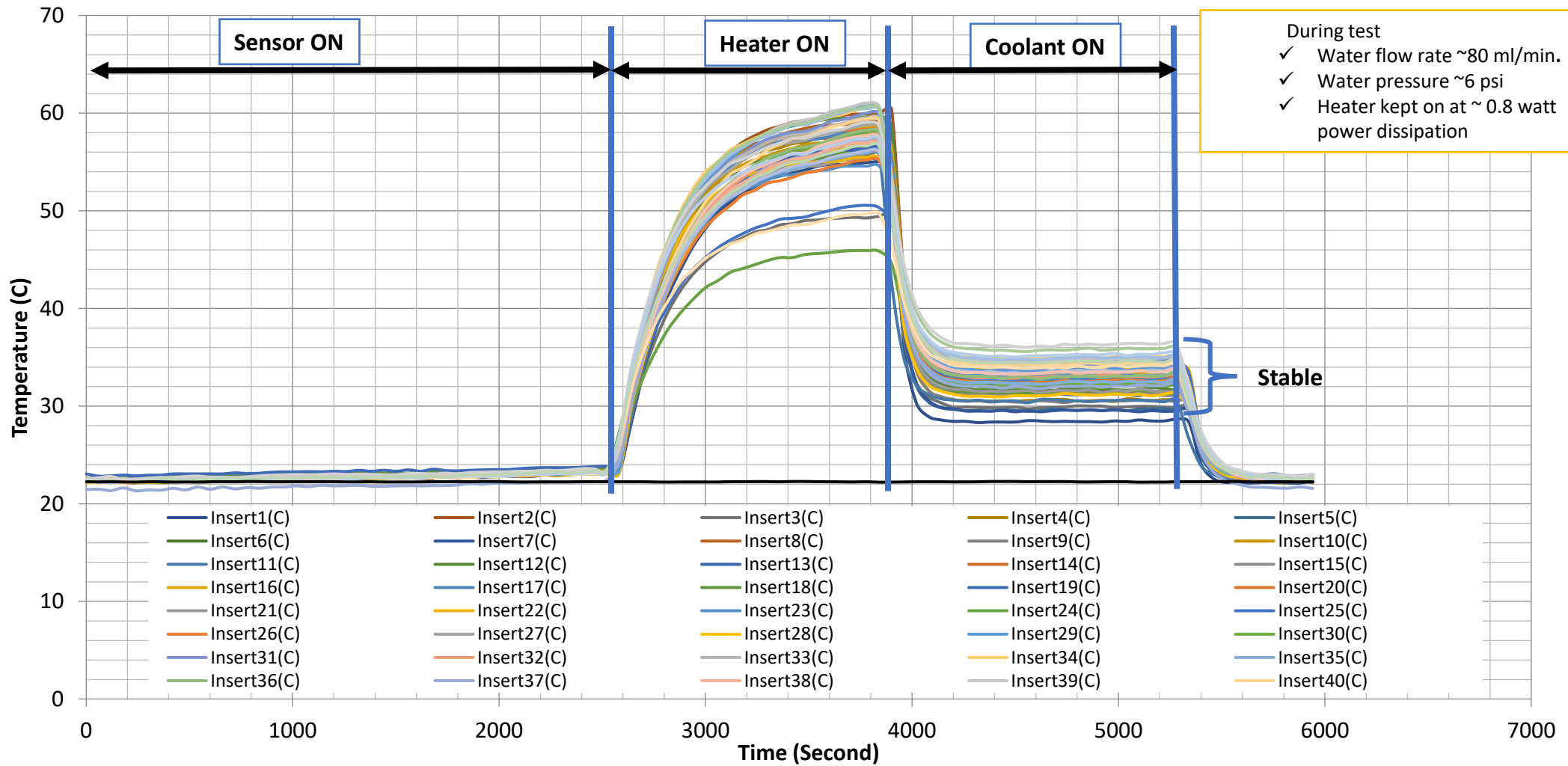
Strip numbering



SQC proposed tests



Thermal QC of the 1st Pre-Production TB2S Ladder



Thermal QC of the 2nd Pre-Production TB2S Ladder

